

M68HC05 Microcontrollers

MC68HC705J1A
MC68HRC705J1A
MC68HSC705J1A
MC68HSR705J1A

Technical Data

MC68HC705J1A/D
Rev. 4, 5/2002

Freescale Semiconductor, Inc.

Freescale Semiconductor, Inc.

**For More Information On This Product,
Go to: www.freescale.com**

MC68HC705J1A
MC68HRC705J1A
MC68HSC705J1A
MC68HSR705J1A
Technical Data

To provide the most up-to-date information, the revision of our documents on the World Wide Web will be the most current. Your printed copy may be an earlier revision. To verify you have the latest information available, refer to:

<http://www.freescale.com>

The following revision history table summarizes changes contained in this document. For your convenience, the page number designators have been linked to the appropriate location.

Revision History

| Date | Revision Level | Description | Page Number(s) |
|-----------|----------------|--|----------------|
| May, 2002 | 4.0 | Figure 2-2. I/O Register Summary — Corrected reset state for last entry (Mask Option Register) | 37 |
| | | Figure 2-4. Mask Option Register (MOR) — Corrected reset state | 41 |
| | | 6.3.3 Pulldown Register A — Corrected note | 91 |
| | | 6.4.3 Pulldown Register B — Corrected note | 94 |

List of Sections

Section 1. General Description21

Section 2. Memory33

Section 3. Central Processor Unit (CPU)45

Section 4. Resets and Interrupts69

Section 5. Low-Power Modes.79

Section 6. Parallel Input/Output (I/O) Ports87

**Section 7. Computer Operating Properly
(COP) Module97**

Section 8. External Interrupt Module (IRQ).101

Section 9. Multifunction Timer Module109

Section 10. Electrical Specifications.117

Section 11. Mechanical Specifications131

Section 12. Ordering Information135

Appendix A. MC68HRC705J1A137

Appendix B. MC68HSC705J1A141

Appendix C. MC68HSR705J1A145

Index. 151

Table of Contents

Section 1. General Description

| | | |
|---------|---|----|
| 1.1 | Contents | 21 |
| 1.2 | Introduction | 22 |
| 1.3 | Features | 24 |
| 1.4 | Programmable Options | 25 |
| 1.5 | Pin Assignments | 25 |
| 1.5.1 | V _{DD} and V _{SS} | 25 |
| 1.5.2 | OSC1 and OSC2 | 27 |
| 1.5.2.1 | Crystal Oscillator | 27 |
| 1.5.2.2 | Ceramic Resonator Oscillator | 28 |
| 1.5.2.3 | RC Oscillator | 30 |
| 1.5.2.4 | External Clock | 30 |
| 1.6 | $\overline{\text{RESET}}$ | 30 |
| 1.7 | $\overline{\text{IRQ}}/V_{\text{PP}}$ | 31 |
| 1.8 | PA0–PA7 | 31 |
| 1.9 | PB0–PB5 | 31 |

Section 2. Memory

| | | |
|-----|---|----|
| 2.1 | Contents | 33 |
| 2.2 | Introduction | 33 |
| 2.3 | Memory Map | 34 |
| 2.4 | Input/Output Register Summary | 35 |
| 2.5 | RAM | 37 |

| | | |
|-------|---|----|
| 2.6 | EPROM/OTPROM | 38 |
| 2.6.1 | EPROM/OTPROM Programming | 38 |
| 2.6.2 | EPROM Programming Register | 39 |
| 2.6.3 | EPROM Erasing | 40 |
| 2.7 | Mask Option Register | 40 |
| 2.8 | EPROM Programming Characteristics | 43 |

Section 3. Central Processor Unit (CPU)

| | | |
|---------|--------------------------------------|----|
| 3.1 | Contents | 45 |
| 3.2 | Introduction | 46 |
| 3.3 | CPU Control Unit | 46 |
| 3.4 | Arithmetic/Logic Unit | 46 |
| 3.5 | CPU Registers | 48 |
| 3.5.1 | Accumulator | 48 |
| 3.5.2 | Index Register | 48 |
| 3.5.3 | Stack Pointer | 49 |
| 3.5.4 | Program Counter | 50 |
| 3.5.5 | Condition Code Register | 50 |
| 3.6 | Instruction Set | 52 |
| 3.6.1 | Addressing Modes | 52 |
| 3.6.1.1 | Inherent | 52 |
| 3.6.1.2 | Immediate | 52 |
| 3.6.1.3 | Direct | 53 |
| 3.6.1.4 | Extended | 53 |
| 3.6.1.5 | Indexed, No Offset | 53 |
| 3.6.1.6 | Indexed, 8-Bit Offset | 53 |
| 3.6.1.7 | Indexed, 16-Bit Offset | 54 |
| 3.6.1.8 | Relative | 54 |
| 3.6.2 | Instruction Types | 55 |
| 3.6.2.1 | Register/Memory Instructions | 55 |
| 3.6.2.2 | Read-Modify-Write Instructions | 56 |
| 3.6.2.3 | Jump/Branch Instructions | 57 |
| 3.6.2.4 | Bit Manipulation Instructions | 59 |
| 3.6.2.5 | Control Instructions | 60 |

3.7 Instruction Set Summary61
 3.8 Opcode Map66

Section 4. Resets and Interrupts

4.1 Contents69
 4.2 Introduction69
 4.3 Resets70
 4.3.1 Power-On Reset71
 4.3.2 External Reset72
 4.3.3 COP Watchdog Reset72
 4.3.4 Illegal Address Reset72
 4.4 Interrupts73
 4.4.1 Software Interrupt73
 4.4.2 External Interrupt73
 4.4.3 Timer Interrupts76
 4.4.3.1 Real-Time Interrupt76
 4.4.3.2 Timer Overflow Interrupt76
 4.4.4 Interrupt Processing76

Section 5. Low-Power Modes

5.1 Contents79
 5.2 Introduction79
 5.3 Exiting Stop and Wait Modes80
 5.4 Effects of Stop and Wait Modes81
 5.4.1 Clock Generation81
 5.4.2 CPU82
 5.4.3 COP Watchdog82
 5.4.4 Timer83
 5.4.5 EPROM/OTPROM84
 5.4.6 Data-Retention Mode84
 5.5 Timing85

Section 6. Parallel Input/Output (I/O) Ports

6.1 Contents87

6.2 Introduction87

6.3 Port A89

6.3.1 Port A Data Register89

6.3.2 Data Direction Register A90

6.3.3 Pulldown Register A91

6.3.4 Port A LED Drive Capability92

6.3.5 Port A I/O Pin Interrupts92

6.4 Port B92

6.4.1 Port B Data Register92

6.4.2 Data Direction Register B93

6.4.3 Pulldown Register B94

6.5 5.0-Volt I/O Port Electrical Characteristics95

6.6 3.3-Volt I/O Port Electrical Characteristics95

Section 7. Computer Operating Properly (COP) Module

7.1 Contents97

7.2 Introduction97

7.3 Operation98

7.3.1 COP Watchdog Timeout98

7.3.2 COP Watchdog Timeout Period98

7.3.3 Clearing the COP Watchdog98

7.4 Interrupts99

7.5 COP Register99

7.6 Low-Power Modes100

7.6.1 Stop Mode100

7.6.2 Wait Mode100

Section 8. External Interrupt Module (IRQ)

| | | |
|-------|--|-----|
| 8.1 | Contents | 101 |
| 8.2 | Introduction | 101 |
| 8.3 | Operation | 102 |
| 8.3.1 | $\overline{\text{IRQ}}/\text{V}_{\text{PP}}$ Pin | 104 |
| 8.3.2 | Optional External Interrupts | 104 |
| 8.4 | IRQ Status and Control Register | 106 |
| 8.5 | External Interrupt Timing | 107 |
| 8.5.1 | 5.0-Volt External Interrupt Timing Characteristics | 107 |
| 8.5.2 | 3.3-Volt External Interrupt Timing Characteristics | 107 |

Section 9. Multifunction Timer Module

| | | |
|-------|---|-----|
| 9.1 | Contents | 109 |
| 9.2 | Introduction | 109 |
| 9.3 | Operation | 111 |
| 9.4 | Interrupts | 112 |
| 9.5 | I/O Registers | 112 |
| 9.5.1 | Timer Status and Control Register | 112 |
| 9.5.2 | Timer Counter Register | 114 |
| 9.6 | Low-Power Modes | 115 |
| 9.6.1 | Stop Mode | 115 |
| 9.6.2 | Wait Mode | 115 |

Section 10. Electrical Specifications

| | | |
|------|---------------------------------------|-----|
| 10.1 | Contents | 117 |
| 10.2 | Introduction | 117 |
| 10.3 | Maximum Ratings | 118 |
| 10.4 | Operating Temperature Range | 119 |
| 10.5 | Thermal Characteristics | 119 |

10.6 Power Considerations 120

10.7 5.0-Volt DC Electrical Characteristics 121

10.8 3.3-Volt DC Electrical Characteristics 122

10.9 Driver Characteristics 123

10.10 Typical Supply Currents 125

10.11 EPROM Programming Characteristics 126

10.12 5.0-Volt Control Timing 126

10.13 3.3-Volt Control Timing 127

Section 11. Mechanical Specifications

11.1 Contents 131

11.2 Introduction 131

11.3 Plastic Dual In-Line Package (Case 738) 132

11.4 Small Outline Integrated Circuit (Case 751) 132

11.5 Ceramic Dual In-Line Package (Case 732) 133

Section 12. Ordering Information

12.1 Contents 135

12.2 Introduction 135

12.3 MCU Order Numbers 135

Appendix A. MC68HRC705J1A

A.1 Contents 137

A.2 Introduction 137

A.3 RC Oscillator Connections 138

A.4 Typical Internal Operating Frequency
for RC Oscillator Option 139

A.5 Package Types and Order Numbers 140

Appendix B. MC68HSC705J1A

B.1 Contents 141
B.2 Introduction 141
B.3 5.0-Volt DC Electrical Characteristics 142
B.4 3.3-Volt DC Electrical Characteristics 142
B.5 Typical Supply Currents 142
B.6 Package Types and Order Numbers 144

Appendix C. MC68HSR705J1A

C.1 Contents 145
C.2 Introduction 145
C.3 RC Oscillator Connections (External Resistor) 145
C.4 Typical Internal Operating Frequency at 25°C
for High-Speed RC Oscillator Option 146
C.5 RC Oscillator Connections (No External Resistor) 147
C.6 Typical Internal Operating Frequency versus Temperature
(No External Resistor) 148
C.7 Package Types and Order Numbers 149

Index

Index 151

List of Figures

| Figure | Title | Page |
|--------|---|------|
| 1-1 | Block Diagram | 23 |
| 1-2 | Pin Assignments | 26 |
| 1-3 | Bypassing Layout Recommendation | 26 |
| 1-4 | Crystal Connections with Oscillator Internal Resistor Mask Option | 28 |
| 1-5 | Crystal Connections without Oscillator Internal Resistor Mask Option | 28 |
| 1-6 | Ceramic Resonator Connections with Oscillator Internal Resistor Mask Option | 29 |
| 1-7 | Ceramic Resonator Connections without Oscillator Internal Resistor Mask Option | 29 |
| 1-8 | External Clock Connections | 30 |
| | | |
| 2-1 | Memory Map | 34 |
| 2-2 | I/O Register Summary | 35 |
| 2-3 | EPROM Programming Register (EPROG) | 39 |
| 2-4 | Mask Option Register (MOR) | 41 |
| | | |
| 3-1 | Programming Model | 47 |
| 3-2 | Accumulator (A) | 48 |
| 3-3 | Index Register (X) | 48 |
| 3-4 | Stack Pointer (SP) | 49 |
| 3-5 | Program Counter (PC) | 50 |
| 3-6 | Condition Code Register (CCR) | 50 |
| | | |
| 4-1 | Reset Sources | 70 |
| 4-2 | Power-On Reset Timing | 71 |

| Figure | Title | Page |
|--------|--|------|
| 4-3 | External Reset Timing | 72 |
| 4-4 | External Interrupt Logic | 74 |
| 4-5 | External Interrupt Timing | 75 |
| 4-6 | Interrupt Stacking Order | 77 |
| 4-7 | Interrupt Flowchart | 78 |
| 5-1 | Stop Mode Recovery Timing | 85 |
| 5-2 | Stop/Halt/Wait Flowchart | 86 |
| 6-1 | Parallel I/O Port Register Summary | 88 |
| 6-2 | Port A Data Register (PORTA) | 89 |
| 6-3 | Data Direction Register A (DDRA) | 90 |
| 6-4 | Port A I/O Circuitry | 90 |
| 6-5 | Pulldown Register A (PDRA) | 91 |
| 6-6 | Port B Data Register (PORTB) | 92 |
| 6-7 | Data Direction Register B (DDRB) | 93 |
| 6-8 | Port B I/O Circuitry | 93 |
| 6-9 | Pulldown Register B (PDRB) | 94 |
| 7-1 | COP Register (COPR) | 99 |
| 8-1 | IRQ Module Block Diagram | 102 |
| 8-2 | Interrupt Flowchart | 103 |
| 8-3 | IRQ Status and Control Register (ISCR) | 106 |
| 8-4 | External Interrupt Timing | 107 |
| 9-1 | Multifunction Timer Block Diagram | 110 |
| 9-2 | I/O Register Summary | 111 |
| 9-3 | Timer Status and Control Register (TSCR) | 112 |
| 9-4 | Timer Counter Register (TCR) | 114 |

| Figure | Title | Page |
|--------|---|------|
| 10-1 | PA0–PA7, PB0–PB5 Typical High-Side Driver Characteristics | 123 |
| 10-2 | PA0–PA3, PB0–PB5 Typical Low-Side Driver Characteristics | 123 |
| 10-3 | PA4–PA7 Typical Low-Side Driver Characteristics | 124 |
| 10-4 | Typical Operating I_{DD} (25°C) | 125 |
| 10-5 | Typical Wait Mode I_{DD} (25°C) | 125 |
| 10-6 | External Interrupt Timing | 128 |
| 10-7 | Stop Mode Recovery Timing | 128 |
| 10-8 | Power-On Reset Timing | 129 |
| 10-9 | External Reset Timing | 129 |
| A-1 | RC Oscillator Connections | 138 |
| A-2 | Typical Internal Operating Frequency for Various V_{DD} at 25°C — RC Oscillator Option Only | 139 |
| B-1 | Typical High-Speed Operating I_{DD} (25°C) | 142 |
| B-2 | Typical High-Speed Wait Mode I_{DD} (25°C) | 143 |
| C-1 | Typical Internal Operating Frequency at 25°C for High-Speed RC Oscillator Option | 146 |
| C-2 | RC Oscillator Connections (No External Resistor) | 147 |
| C-3 | Typical Internal Operating Frequency versus Temperature (OSCREG Bit = 1) | 148 |

List of Tables

| Table | Title | Page |
|-------|--|------|
| 1-1 | Programmable Options | 25 |
| 3-1 | Register/Memory Instructions | 55 |
| 3-2 | Read-Modify-Write Instructions | 56 |
| 3-3 | Jump and Branch Instructions | 58 |
| 3-4 | Bit Manipulation Instructions | 59 |
| 3-5 | Control Instructions | 60 |
| 3-6 | Instruction Set Summary | 61 |
| 3-7 | Opcode Map | 67 |
| 4-1 | External Reset Timing | 72 |
| 4-2 | External Interrupt Timing ($V_{DD} = 5.0$ Vdc) | 75 |
| 4-3 | External Interrupt Timing ($V_{DD} = 3.3$ Vdc) | 75 |
| 4-4 | Reset/Interrupt Vector Addresses | 77 |
| 6-1 | Port A Pin Operation | 91 |
| 6-2 | Port B Pin Operation | 94 |
| 9-1 | Real-Time Interrupt Rate Selection | 114 |
| 12-1 | Order Numbers | 135 |
| A-1 | MC68HRC705J1A (RC Oscillator Option) Order Numbers | 140 |
| B-1 | MC68HSC705J1A (High Speed) Order Numbers | 144 |
| C-1 | MC68HSR705J1A (High-Speed RC Oscillator Option) Order Numbers | 149 |

Section 1. General Description

1.1 Contents

| | | |
|---------|--|----|
| 1.2 | Introduction | 22 |
| 1.3 | Features | 24 |
| 1.4 | Programmable Options | 25 |
| 1.5 | Pin Assignments | 25 |
| 1.5.1 | V_{DD} and V_{SS} | 25 |
| 1.5.2 | OSC1 and OSC2 | 27 |
| 1.5.2.1 | Crystal Oscillator | 27 |
| 1.5.2.2 | Ceramic Resonator Oscillator | 28 |
| 1.5.2.3 | RC Oscillator | 30 |
| 1.5.2.4 | External Clock | 30 |
| 1.6 | $\overline{\text{RESET}}$ | 30 |
| 1.7 | $\overline{\text{IRQ}}/V_{PP}$ | 31 |
| 1.8 | PA0–PA7 | 31 |
| 1.9 | PB0–PB5 | 31 |

1.2 Introduction

The MC68HC705J1A is a member of Motorola's low-cost, high-performance M68HC05 Family of 8-bit microcontroller units (MCUs). The M68HC05 Family is based on the customer-specified integrated circuit (CSIC) design strategy. All MCUs in the family use the popular M68HC05 central processor unit (CPU) and are available with a variety of subsystems, memory sizes and types, and package types.

On-chip memory of the MC68HC705J1A includes 1240 bytes of erasable, programmable read-only memory (EPROM). In packages without the transparent window for EPROM erasure, the 1240 EPROM bytes serve as one-time programmable read-only memory (OTPROM).

The MC68HRC705J1A is a resistor-capacitor (RC) oscillator mask option version of the MC68HC705J1A and is discussed in [Appendix A. MC68HRC705J1A](#).

A high-speed version of the MC68HC705J1A, the MC68HSC705J1A, is discussed in [Appendix B. MC68HSC705J1A](#).

The MC68HSR705J1A, discussed in [Appendix C. MC68HSR705J1A](#), is a high-speed version of the MC68HRC705J1A.

A functional block diagram of the MC68HC705J1A is shown in [Figure 1-1](#).

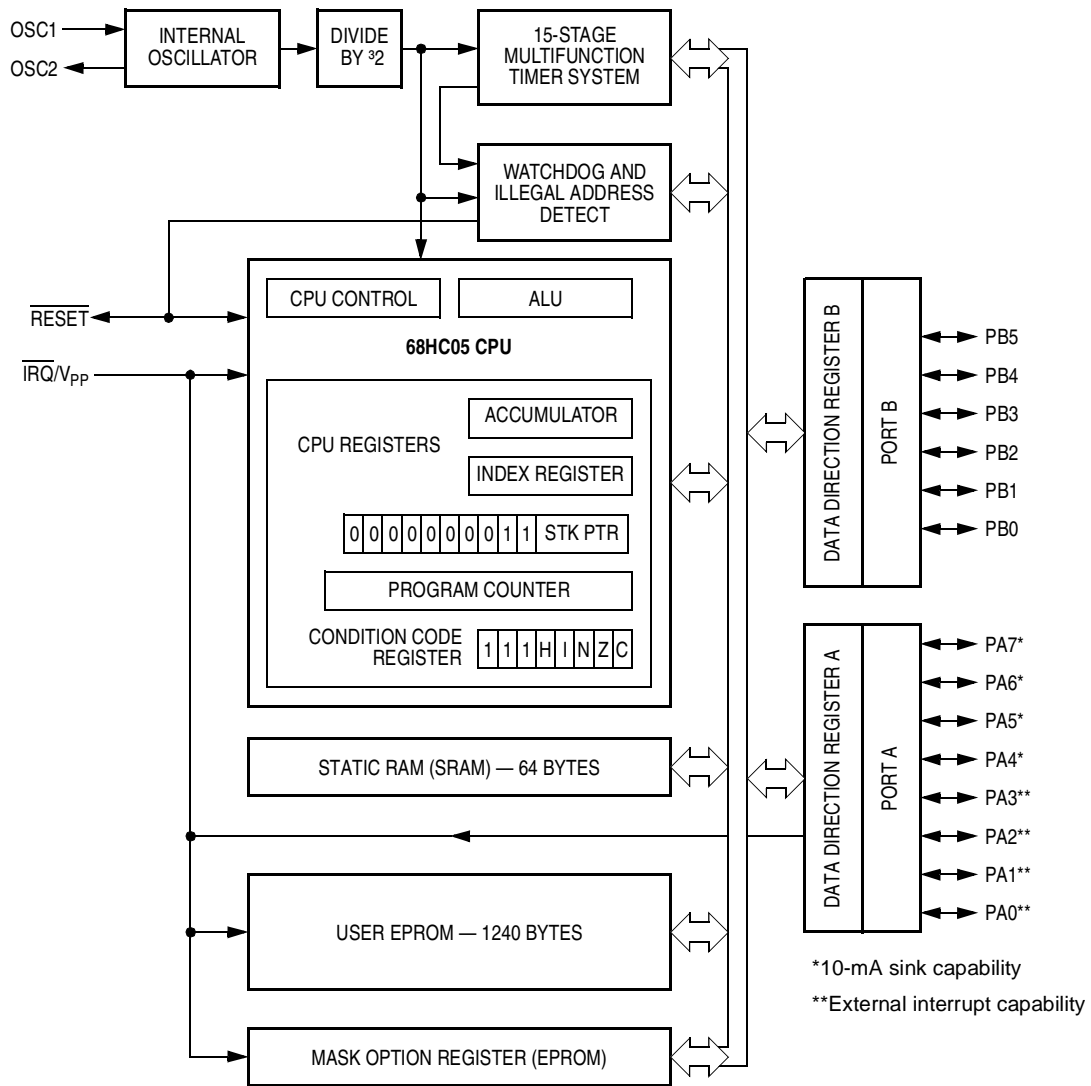


Figure 1-1. Block Diagram

Freescale Semiconductor, Inc.

1.3 Features

Features of the MC68HC705J1A include:

- Peripheral modules:
 - 15-stage multifunction timer
 - Computer operating properly (COP) watchdog
- 14 bidirectional input/output (I/O) lines, including:
 - 10-mA sink capability on four I/O pins
 - Mask option register (MOR) and software programmable pulldowns on all I/O pins
 - MOR selectable interrupt on four I/O pins, a keyboard scan feature
- MOR selectable sensitivity on external interrupt (edge- and level-sensitive or edge-sensitive only)
- On-chip oscillator with connections for:
 - Crystal
 - Ceramic resonator
 - Resistor-capacitor (RC) oscillator
 - External clock
- 1240 bytes of EPROM/OTPROM, including eight bytes for user vectors
- 64 bytes of user random-access memory (RAM)
- Memory-mapped I/O registers
- Fully static operation with no minimum clock speed
- Power-saving stop, halt, wait, and data-retention modes
- External interrupt mask bit and acknowledge bit
- Illegal address reset
- Internal steering diode and pullup resistor from $\overline{\text{RESET}}$ pin to V_{DD}

1.4 Programmable Options

The options in [Table 1-1](#) are programmable in the mask option register (MOR).

Table 1-1. Programmable Options

| Feature | Option |
|---|--|
| COP watchdog timer | Enabled or disabled |
| External interrupt triggering | Edge-sensitive only or edge- and level-sensitive |
| Port A $\overline{\text{IRQ}}$ pin interrupts | Enabled or disabled |
| Port pulldown resistors | Enabled or disabled |
| STOP instruction mode | Stop mode or halt mode |
| Crystal oscillator internal resistor | Enabled or disabled |
| EPROM security | Enabled or disabled |
| Short oscillator delay counter | Enabled or disabled |

1.5 Pin Assignments

[Figure 1-2](#) shows the MC68HC705J1A pin assignments.

1.5.1 V_{DD} and V_{SS}

V_{DD} and V_{SS} are the power supply and ground pins. The MCU operates from a single power supply.

Very fast signal transitions occur on the MCU pins, placing high, short-duration current demands on the power supply. To prevent noise problems, take special care as [Figure 1-3](#) shows, by placing the bypass capacitors as close as possible to the MCU. C2 is an optional bulk current bypass capacitor for use in applications that require the port pins to source high current levels.

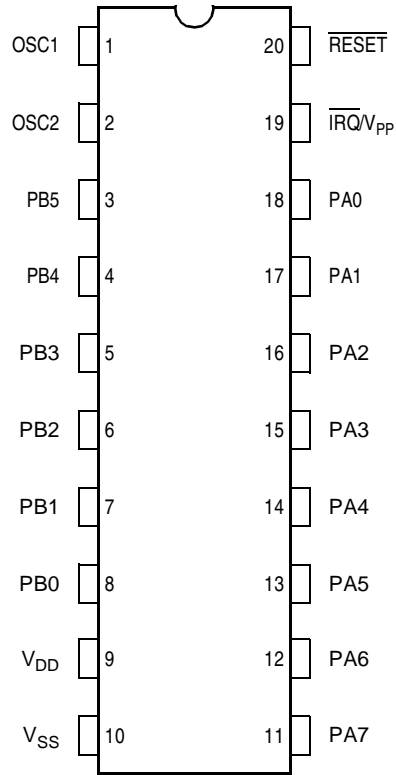


Figure 1-2. Pin Assignments

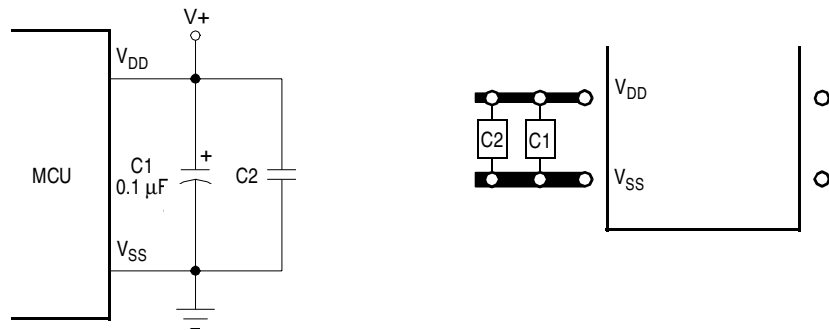


Figure 1-3. Bypassing Layout Recommendation

1.5.2 OSC1 and OSC2

The OSC1 and OSC2 pins are the connections for the on-chip oscillator. The oscillator can be driven by any of these:

1. Crystal (See [Figure 1-4](#) and [Figure 1-5](#).)
2. Ceramic resonator (See [Figure 1-6](#) and [Figure 1-7](#).)
3. Resistor/capacitor (RC) oscillator (Refer to [Appendix A. MC68HRC705J1A](#) and [Appendix C. MC68HSR705J1A](#).)
4. External clock signal (See [Figure 1-8](#).)

The frequency, f_{osc} , of the oscillator or external clock source is divided by two to produce the internal operating frequency, f_{op} .

1.5.2.1 Crystal Oscillator

[Figure 1-4](#) and [Figure 1-5](#) show a typical crystal oscillator circuit for an AT-cut, parallel resonant crystal. Follow the crystal supplier's recommendations, as the crystal parameters determine the external component values required to provide reliable startup and maximum stability. The load capacitance values used in the oscillator circuit design should include all stray layout capacitances.

To minimize output distortion, mount the crystal and capacitors as close as possible to the pins. An internal startup resistor of approximately 2 M Ω is provided between OSC1 and OSC2 for the crystal oscillator as a programmable mask option.

NOTE: Use an AT-cut crystal and not an AT-strip crystal because the MCU can overdrive an AT-strip crystal.

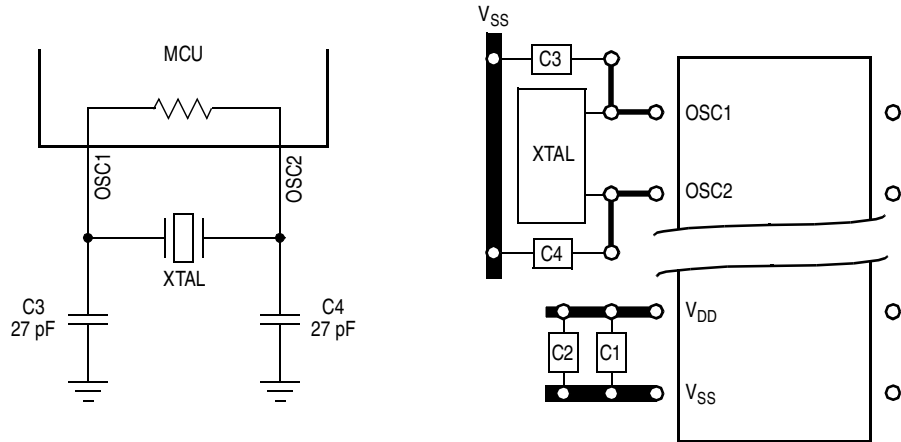


Figure 1-4. Crystal Connections with Oscillator Internal Resistor Mask Option

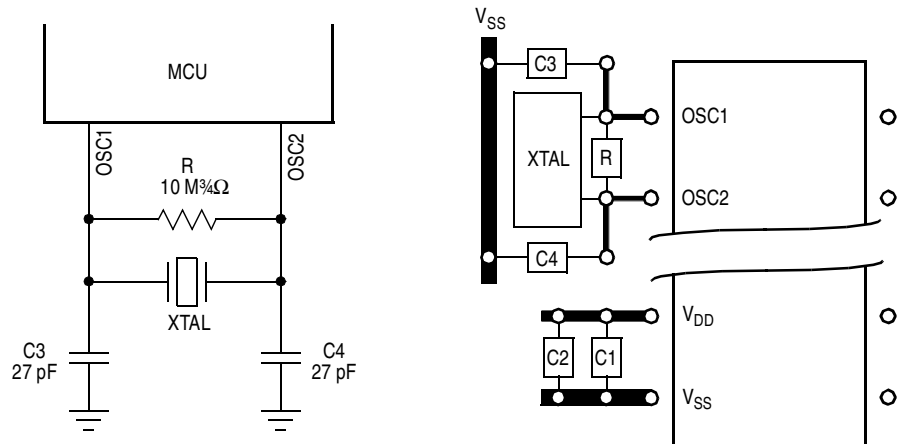


Figure 1-5. Crystal Connections without Oscillator Internal Resistor Mask Option

1.5.2.2 Ceramic Resonator Oscillator

To reduce cost, use a ceramic resonator instead of the crystal. The circuits shown in [Figure 1-6](#) and [Figure 1-7](#) show ceramic resonator circuits. Follow the resonator manufacturer's recommendations, as the resonator parameters determine the external component values required for maximum stability and reliable starting. The load capacitance values used in the oscillator circuit design should include all stray capacitances.

Mount the resonator and components as close as possible to the pins for startup stabilization and to minimize output distortion. An internal startup resistor of approximately 2 M Ω is provided between OSC1 and OSC2 as a programmable mask option.

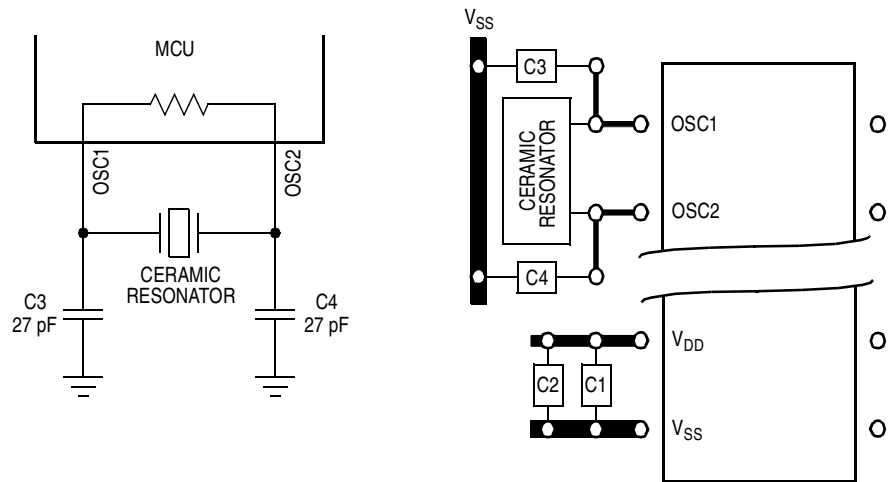


Figure 1-6. Ceramic Resonator Connections with Oscillator Internal Resistor Mask Option

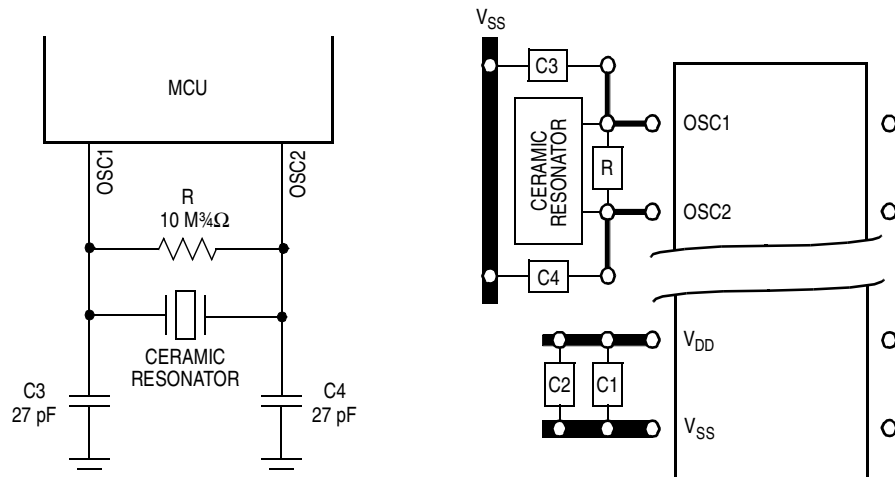


Figure 1-7. Ceramic Resonator Connections without Oscillator Internal Resistor Mask Option

General Description

1.5.2.3 RC Oscillator

Refer to [Appendix A. MC68HRC705J1A](#) and [Appendix C. MC68HSR705J1A](#).

1.5.2.4 External Clock

An external clock from another complementary metal-oxide semiconductor (CMOS)-compatible device can be connected to the OSC1 input, with the OSC2 input not connected, as shown in [Figure 1-8](#). This configuration is possible regardless of whether the crystal/ceramic resonator or the RC oscillator is enabled.

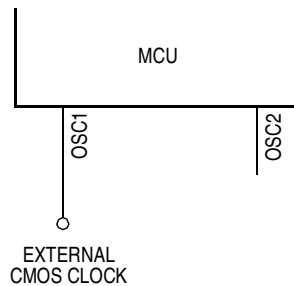


Figure 1-8. External Clock Connections

1.6 RESET

Applying a logic 0 to the RESET pin forces the MCU to a known startup state. An internal reset also pulls the RESET pin low. An internal resistor to V_{DD} pulls the RESET pin high. A steering diode between the RESET and V_{DD} pins discharges any RESET pin voltage when power is removed from the MCU. The RESET pin contains an internal Schmitt trigger to improve its noise immunity as an input. Refer to [Section 4. Resets and Interrupts](#) for more information.

1.7 $\overline{\text{IRQ}}/\text{V}_{\text{PP}}$

The external interrupt/programming voltage pin ($\overline{\text{IRQ}}/\text{V}_{\text{PP}}$) drives the asynchronous IRQ interrupt function of the CPU. Additionally, it is used to program the user EPROM and mask option register. (See [Section 2. Memory](#) and [Section 8. External Interrupt Module \(IRQ\)](#).)

The LEVEL bit in the mask option register provides negative edge-sensitive triggering or both negative edge-sensitive and low level-sensitive triggering for the interrupt function.

If level-sensitive triggering is selected, the $\overline{\text{IRQ}}/\text{V}_{\text{PP}}$ input requires an external resistor to V_{DD} for wired-OR operation. If the $\overline{\text{IRQ}}/\text{V}_{\text{PP}}$ pin is not used, it must be tied to the V_{DD} supply.

The $\overline{\text{IRQ}}/\text{V}_{\text{PP}}$ pin contains an internal Schmitt trigger as part of its input to improve noise immunity. The voltage on this pin should not exceed V_{DD} except when the pin is being used for programming the EPROM.

NOTE: *The mask option register can enable the PA0–PA3 pins to function as external interrupt pins.*

1.8 PA0–PA7

These eight input/output (I/O) lines comprise port A, a general-purpose, bidirectional I/O port. See [Section 8. External Interrupt Module \(IRQ\)](#) for information on PA0–PA3 external interrupts.

1.9 PB0–PB5

These six I/O lines comprise port B, a general-purpose, bidirectional I/O port.

Section 2. Memory

2.1 Contents

| | | |
|-------|---|----|
| 2.2 | Introduction | 33 |
| 2.3 | Memory Map | 34 |
| 2.4 | Input/Output Register Summary | 35 |
| 2.5 | RAM | 37 |
| 2.6 | EPROM/OTPROM | 38 |
| 2.6.1 | EPROM/OTPROM Programming | 38 |
| 2.6.2 | EPROM Programming Register | 39 |
| 2.6.3 | EPROM Erasing | 40 |
| 2.7 | Mask Option Register | 40 |
| 2.8 | EPROM Programming Characteristics | 43 |

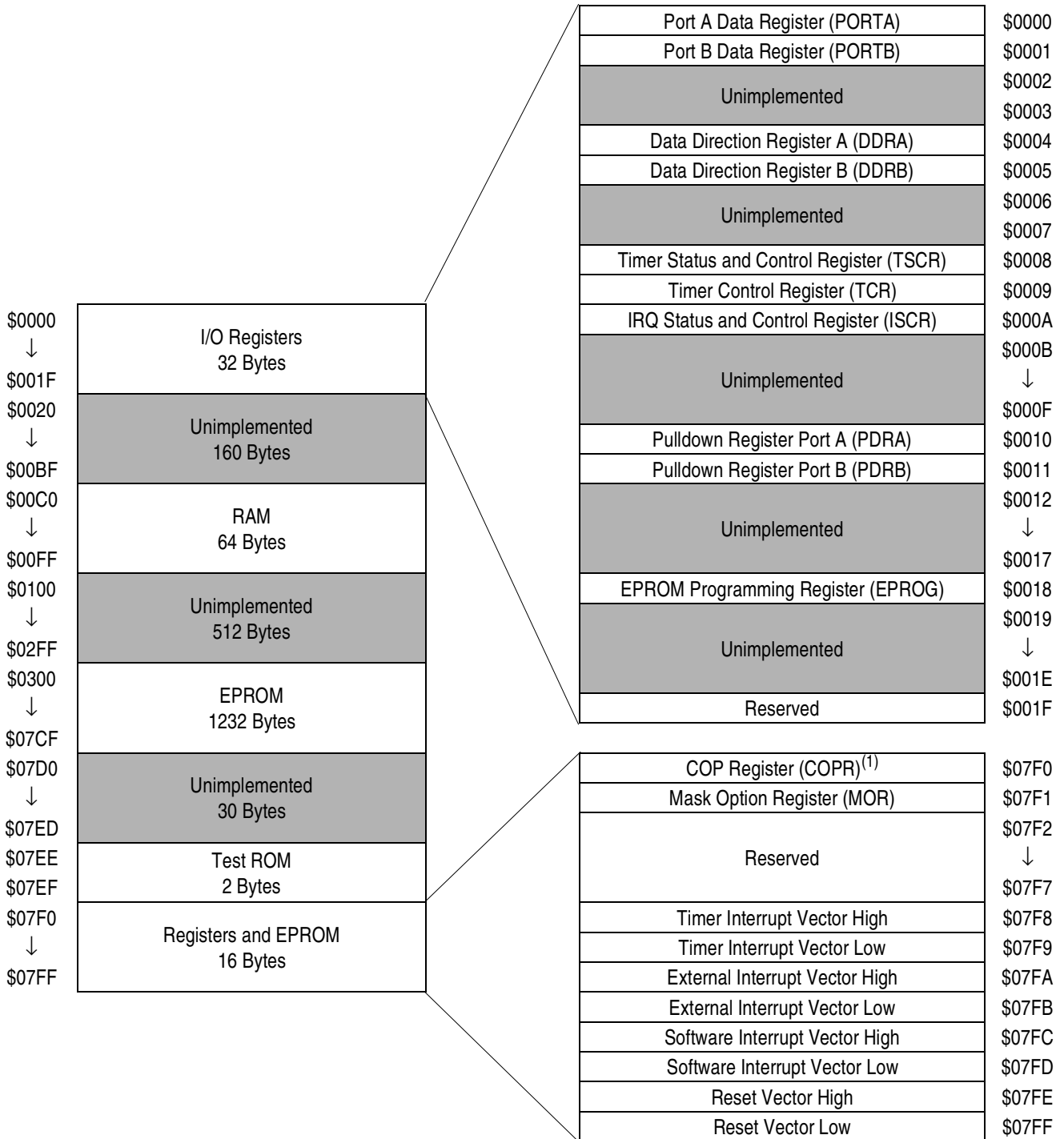
2.2 Introduction

This section describes the organization of the on-chip memory consisting of:

- 1232 bytes of user erasable, programmable read-only memory (EPROM), plus eight bytes for user vectors
- 64 bytes of user random-access memory (RAM)

Memory

2.3 Memory Map



⁽¹⁾ Writing to bit 0 of \$07F0 clears the computer operating properly (COP) watchdog.

Figure 2-1. Memory Map

2.4 Input/Output Register Summary

| Addr. | Register Name | Bit 7 | 6 | 5 | 4 | 3 | 2 | 1 | Bit 0 | |
|--------|---|--------|---------------------|-------|-------|-------|-------|-------|-------|-------|
| \$0000 | Port A Data Register (PORTA) See page 89. | Read: | PA7 | PA6 | PA5 | PA4 | PA3 | PA2 | PA1 | PA0 |
| | | Write: | | | | | | | | |
| | | Reset: | Unaffected by reset | | | | | | | |
| \$0001 | Port B Data Register (PORTB) See page 92. | Read: | 0 | 0 | PB5 | PB4 | PB3 | PB2 | PB1 | PB0 |
| | | Write: | | | | | | | | |
| | | Reset: | Unaffected by reset | | | | | | | |
| \$0002 | Unimplemented | | | | | | | | | |
| \$0003 | Unimplemented | | | | | | | | | |
| \$0004 | Data Direction Register A (DDRA) See page 90. | Read: | DDRA7 | DDRA6 | DDRA5 | DDRA4 | DDRA3 | DDRA2 | DDRA1 | DDRA0 |
| | | Write: | | | | | | | | |
| | | Reset: | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| \$0005 | Data Direction Register B (DDRB) See page 93. | Read: | 0 | 0 | DDRB5 | DDRB4 | DDRB3 | DDRB2 | DDRB1 | DDRB0 |
| | | Write: | | | | | | | | |
| | | Reset: | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| \$0006 | Unimplemented | | | | | | | | | |
| \$0007 | Unimplemented | | | | | | | | | |
| \$0008 | Timer Status and Control Register (TSCR) See page 112. | Read: | TOF | RTIF | TOIE | RTIE | 0 | 0 | RT1 | RT0 |
| | | Write: | | | | | TOFR | RTIFR | | |
| | | Reset: | 0 | 0 | 0 | 0 | 0 | 0 | 1 | 1 |

= Unimplemented R = Reserved

Figure 2-2. I/O Register Summary (Sheet 1 of 3)

Memory

| Addr. | Register Name | Bit 7 | 6 | 5 | 4 | 3 | 2 | 1 | Bit 0 | |
|--------|--|--------|-------|-------|-------|-------|-------|-------|-------|-------|
| \$0009 | Timer Counter Register (TCR) <i>See page 114.</i> | Read: | TMR7 | TMR6 | TMR5 | TMR4 | TMR3 | TMR2 | TMR1 | TMR0 |
| | | Write: | | | | | | | | |
| | | Reset: | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| \$000A | IRQ Status and Control Register (ISCR) <i>See page 106.</i> | Read: | IRQE | 0 | 0 | 0 | IRQF | 0 | 0 | 0 |
| | | Write: | | | | R | | | IRQR | |
| | | Reset: | 1 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| \$000B | Unimplemented | | | | | | | | | |
| ↓ | | | | | | | | | | |
| \$000F | Unimplemented | | | | | | | | | |
| \$0010 | Pulldown Register A (PDRA) <i>See page 91.</i> | Read: | | | | | | | | |
| | | Write: | PDIA7 | PDIA6 | PDIA5 | PDIA4 | PDIA3 | PDIA2 | PDIA1 | PDIA0 |
| | | Reset: | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| \$0011 | Pulldown Register B (PDRB) <i>See page 94.</i> | Read: | | | | | | | | |
| | | Write: | | | PDIB5 | PDIB4 | PDIB3 | PDIB2 | PDIB1 | PDIB0 |
| | | Reset: | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| \$0012 | Unimplemented | | | | | | | | | |
| ↓ | | | | | | | | | | |
| \$0017 | Unimplemented | | | | | | | | | |
| \$0018 | EPROM Programming Register (EPROG) <i>See page 39.</i> | Read: | 0 | 0 | 0 | 0 | 0 | ELAT | MPGM | EPGM |
| | | Write: | | R | R | R | R | | | |
| | | Reset: | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |

= Unimplemented R = Reserved

Figure 2-2. I/O Register Summary (Sheet 2 of 3)

| Addr. | Register Name | Bit 7 | 6 | 5 | 4 | 3 | 2 | 1 | Bit 0 | |
|--------|---|--------|---------------------|--------|--------|-------|-------|------|-------|-------|
| \$0019 | Unimplemented | | | | | | | | | |
| ↓ | | | | | | | | | | |
| \$001E | Unimplemented | | | | | | | | | |
| \$001F | Reserved | R | R | R | R | R | R | R | R | |
| \$07F0 | COP Register (COPR) <i>See page 99.</i> | Read: | | | | | | | | |
| | | Write: | | | | | | | COPC | |
| | | Reset: | 0 | | | | | | | |
| \$07F1 | Mask Option Register (MOR) <i>See page 41.</i> | Read: | SOSCD | EPMSEC | OSCREs | SWAIT | SWPDI | PIRQ | LEVEL | COPEN |
| | | Write: | | | | | | | | |
| | | Reset: | Unaffected by reset | | | | | | | |

= Unimplemented R = Reserved

Figure 2-2. I/O Register Summary (Sheet 3 of 3)

2.5 RAM

The 64 addresses from \$00C0 to \$00FF serve as both the user RAM and the stack RAM. Before processing an interrupt, the central processor unit (CPU) uses five bytes of the stack to save the contents of the CPU registers. During a subroutine call, the CPU uses two bytes of the stack to store the return address. The stack pointer decrements when the CPU stores a byte on the stack and increments when the CPU retrieves a byte from the stack.

NOTE: *Be careful when using nested subroutines or multiple interrupt levels. The CPU may overwrite data in the RAM during a subroutine or during the interrupt stacking operation.*

2.6 EPROM/OTPROM

A microcontroller unit (MCU) with a quartz window has 1240 bytes of erasable, programmable ROM (EPROM). The quartz window allows EPROM erasure with ultraviolet light.

NOTE: *Keep the quartz window covered with an opaque material except when programming the MCU. Ambient light can affect MCU operation.*

In an MCU without the quartz window, the EPROM cannot be erased and serves as 1240 bytes of one-time programmable ROM (OTPROM).

These addresses are user EPROM/OTPROM locations:

- \$0300–\$07CF
- \$07F8–\$07FF, used for user-defined interrupt and reset vectors

The computer operating properly (COP) register (COPR) is an EPROM/OTPROM location at address \$07F0.

The mask option register (MOR) is an EPROM/OTPROM location at address \$07F1.

2.6.1 EPROM/OTPROM Programming

The two ways to program the EPROM/OTPROM are:

1. Manipulating the control bits in the EPROM programming register to program the EPROM/OTPROM on a byte-by-byte basis
2. Programming the EPROM/OTPROM with the M68HC705J in-circuit simulator (M68HC705JICS) available from Freescale

2.6.2 EPROM Programming Register

The EPROM programming register (EPROG) contains the control bits for programming the EPROM/OTPROM.

Address: \$0018

| | Bit 7 | 6 | 5 | 4 | 3 | 2 | 1 | Bit 0 |
|--------|-------|---|---|---|---|------|------|-------|
| Read: | 0 | 0 | 0 | 0 | 0 | ELAT | MPGM | EPGM |
| Write: | | R | R | R | R | | | |
| Reset: | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |

= Unimplemented
 R = Reserved

Figure 2-3. EPROM Programming Register (EPROG)

ELAT — EPROM Bus Latch Bit

This read/write bit latches the address and data buses for EPROM/OTPROM programming. Clearing the ELAT bit automatically clears the EPGM bit. EPROM/OTPROM data cannot be read while the ELAT bit is set. Reset clears the ELAT bit.

- 1 = Address and data buses configured for EPROM/OTPROM programming the EPROM
- 0 = Address and data buses configured for normal operation

MPGM — MOR Programming Bit

This read/write bit applies programming power from the \overline{IRQ}/V_{PP} pin to the mask option register. Reset clears MPGM.

- 1 = Programming voltage applied to MOR
- 0 = Programming voltage not applied to MOR

EPGM — EPROM Programming Bit

This read/write bit applies the voltage from the \overline{IRQ}/V_{PP} pin to the EPROM. To write the EPGM bit, the ELAT bit must be set already. Reset clears EPGM.

- 1 = Programming voltage (\overline{IRQ}/V_{PP} pin) applied to EPROM
- 0 = Programming voltage (\overline{IRQ}/V_{PP} pin) not applied to EPROM

NOTE: Writing logic 1s to both the ELAT and EPGM bits with a single instruction sets ELAT and clears EPGM. ELAT must be set first by a separate instruction.

Bits [7:3] — Reserved

Take these steps to program a byte of EPROM/OTPROM:

1. Apply the programming voltage, V_{PP} , to the \overline{IRQ}/V_{PP} pin.
2. Set the ELAT bit.
3. Write to any EPROM/OTPROM address.
4. Set the EPGM bit and wait for a time, t_{EPGM} .
5. Clear the ELAT bit.

2.6.3 EPROM Erasing

The erased state of an EPROM bit is logic 0. Erase the EPROM by exposing it to 15 Ws/cm^2 of ultraviolet light with a wave length of 2537 angstroms. Position the ultraviolet light source one inch from the EPROM. Do not use a shortwave filter.

2.7 Mask Option Register

The mask option register (MOR) is an EPROM/OTPROM byte that controls these options:

- COP watchdog (enable or disable)
- External interrupt pin triggering (edge-sensitive only or edge- and level-sensitive)
- Port A external interrupts (enable or disable)
- Port pulldown resistors (enable or disable)
- STOP instruction (stop mode or halt mode)
- Crystal oscillator internal resistor (enable or disable)
- EPROM security (enable or disable)
- Short oscillator delay (enable or disable)

Take these steps to program the mask option register:

1. Apply the programming voltage, V_{PP} , to the \overline{IRQ}/V_{PP} pin.
2. Write to the MOR.
3. Set the MPGM bit and wait for a time, t_{MPGM} .
4. Clear the MPGM bit.
5. Reset the MCU.

Address: \$07F1

| | Bit 7 | 6 | 5 | 4 | 3 | 2 | 1 | Bit 0 |
|--------|---------------------|--------|--------|-------|-------|------|-------|-------|
| Read: | SOSCD | EPMSEC | OSCREs | SWAIT | SWPDI | PIRQ | LEVEL | COPEN |
| Write: | | | | | | | | |
| Reset: | Unaffected by reset | | | | | | | |

Figure 2-4. Mask Option Register (MOR)

SOSCD — Short Oscillator Delay Bit

The SOSCD bit controls the oscillator stabilization counter. The normal stabilization delay following reset or exit from stop mode is $4064 t_{cyc}$. Setting SOSCD enables a short oscillator stabilization delay.

- 1 = Short oscillator delay enabled
- 0 = Short oscillator delay disabled

EPMSEC — EPROM Security Bit

The EPMSEC bit controls access to the EPROM/OTEPROM.

- 1 = External access to EPROM/OTEPROM denied
- 0 = External access to EPROM/OTEPROM not denied

OSCREs — Oscillator Internal Resistor Bit

The OSCREs bit enables a 2-M Ω internal resistor in the oscillator circuit.

- 1 = Oscillator internal resistor enabled
- 0 = Oscillator internal resistor disabled

NOTE: Program the OSCREs bit to logic 0 in devices using RC oscillators.

SWAIT — Stop-to-Wait Conversion Bit

The SWAIT bit enables halt mode. When the SWAIT bit is set, the CPU interprets the STOP instruction as a WAIT instruction, and the MCU enters halt mode. Halt mode is the same as wait mode, except that an oscillator stabilization delay of 1 to 4064 t_{cyc} occurs after exiting halt mode.

- 1 = Halt mode enabled
- 0 = Halt mode not enabled

SWPDI — Software Pulldown Inhibit Bit

The SWPDI bit inhibits software control of the I/O port pulldown devices. The SWPDI bit overrides the pulldown inhibit bits in the port pulldown inhibit registers.

- 1 = Software pulldown control inhibited
- 0 = Software pulldown control not inhibited

PIRQ — Port A External Interrupt Bit

The PIRQ bit enables the PA0–PA3 pins to function as external interrupt pins.

- 1 = PA0–PA3 enabled as external interrupt pins
- 0 = PA0–PA3 not enabled as external interrupt pins

LEVEL — External Interrupt Sensitivity Bit

The LEVEL bit controls external interrupt triggering sensitivity.

- 1 = External interrupts triggered by active edges and active levels
- 0 = External interrupts triggered only by active edges

COPEN — COP Enable Bit

The COPEN bit enables the COP watchdog.

- 1 = COP watchdog enabled
- 0 = COP watchdog disabled

2.8 EPROM Programming Characteristics

| Characteristic ⁽¹⁾ | Symbol | Min | Typ | Max | Unit |
|--|--|----------------|--------|--------|------|
| Programming voltage IRQ/V _{PP} | V _{PP} | 16.0 | 16.5 | 17.0 | V |
| Programming current IRQ/V _{PP} | I _{PP} | — ¹ | 3.0 | 10.0 | mA |
| Programming time Per array byte MOR | t _{EPGM} t _{MPGM} | 4 4 | — — | — — | ms |

1. V_{DD} = 5.0 Vdc ± 10%, V_{SS} = 0 Vdc, T_A = -40°C to +105°C

Section 3. Central Processor Unit (CPU)

3.1 Contents

| | | |
|---------|--|----|
| 3.2 | Introduction | 46 |
| 3.3 | CPU Control Unit | 46 |
| 3.4 | Arithmetic/Logic Unit | 46 |
| 3.5 | CPU Registers | 48 |
| 3.5.1 | Accumulator | 48 |
| 3.5.2 | Index Register | 48 |
| 3.5.3 | Stack Pointer | 49 |
| 3.5.4 | Program Counter | 50 |
| 3.5.5 | Condition Code Register | 50 |
| 3.6 | Instruction Set | 52 |
| 3.6.1 | Addressing Modes | 52 |
| 3.6.1.1 | Inherent | 52 |
| 3.6.1.2 | Immediate | 52 |
| 3.6.1.3 | Direct | 53 |
| 3.6.1.4 | Extended | 53 |
| 3.6.1.5 | Indexed, No Offset | 53 |
| 3.6.1.6 | Indexed, 8-Bit Offset | 53 |
| 3.6.1.7 | Indexed, 16-Bit Offset | 54 |
| 3.6.1.8 | Relative | 54 |
| 3.6.2 | Instruction Types | 55 |
| 3.6.2.1 | Register/Memory Instructions | 55 |
| 3.6.2.2 | Read-Modify-Write Instructions | 56 |
| 3.6.2.3 | Jump/Branch Instructions | 57 |
| 3.6.2.4 | Bit Manipulation Instructions | 59 |
| 3.6.2.5 | Control Instructions | 60 |
| 3.7 | Instruction Set Summary | 61 |
| 3.8 | Opcode Map | 66 |

3.2 Introduction

The central processor unit (CPU) consists of a CPU control unit, an arithmetic/logic unit (ALU), and five CPU registers. The CPU control unit fetches and decodes instructions. The ALU executes the instructions. The CPU registers contain data, addresses, and status bits that reflect the results of CPU operations. See [Figure 3-1](#).

Features include:

- 2.1-MHz bus frequency
- 8-bit accumulator
- 8-bit index register
- 11-bit program counter
- 6-bit stack pointer
- Condition code register (CCR) with five status flags
- 62 instructions
- Eight addressing modes
- Power-saving stop, wait, halt, and data-retention modes

3.3 CPU Control Unit

The CPU control unit fetches and decodes instructions during program operation. The control unit selects the memory locations to read and write and coordinates the timing of all CPU operations.

3.4 Arithmetic/Logic Unit

The arithmetic/logic unit (ALU) performs the arithmetic, logic, and manipulation operations decoded from the instruction set by the CPU control unit. The ALU produces the results called for by the program and sets or clears status and control bits in the condition code register (CCR).

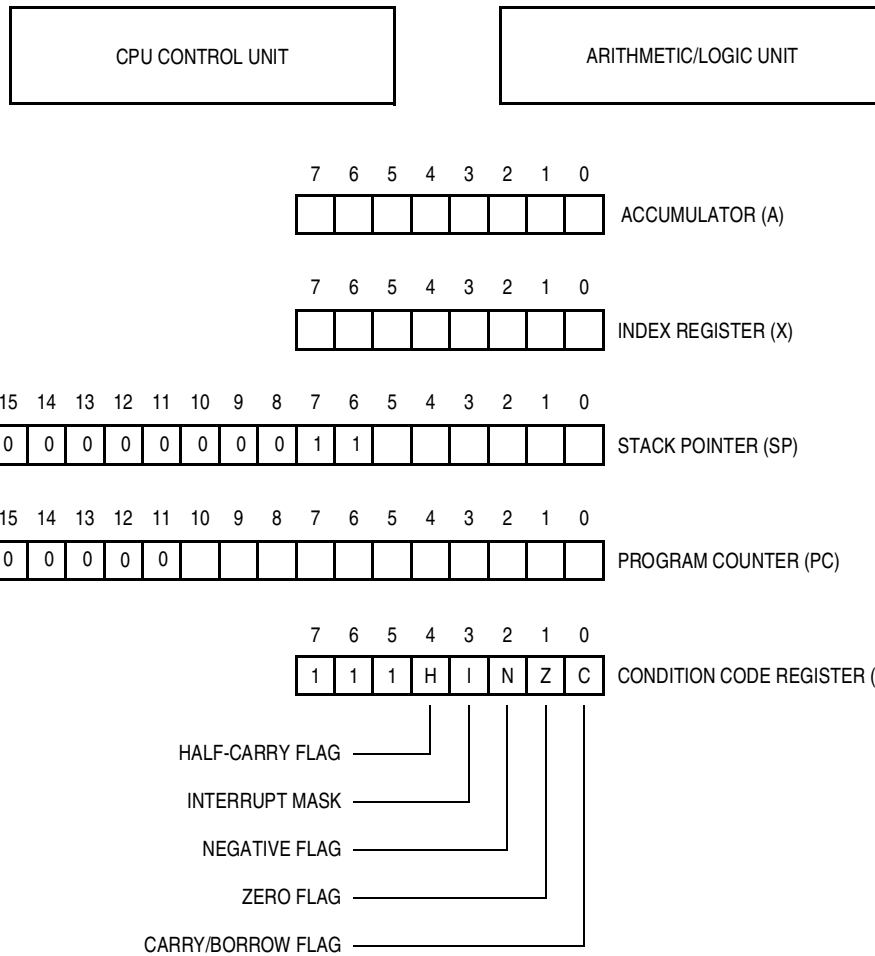


Figure 3-1. Programming Model

3.5 CPU Registers

The M68HC05 CPU contains five registers that control and monitor microcontroller unit (MCU) operation:

- Accumulator
- Index register
- Stack pointer
- Program counter
- Condition code register

CPU registers are not memory mapped.

3.5.1 Accumulator

The accumulator (A) is a general-purpose 8-bit register. The CPU uses the accumulator to hold operands and results of ALU operations.

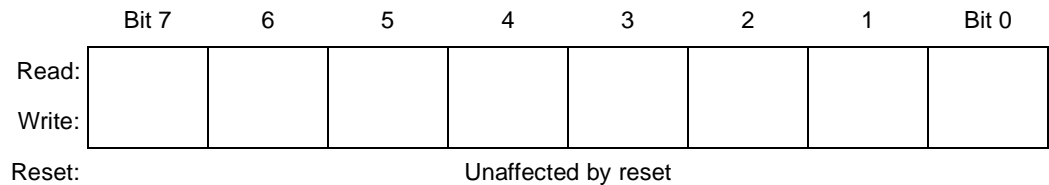


Figure 3-2. Accumulator (A)

3.5.2 Index Register

In the indexed addressing (X) modes, the CPU uses the byte in the index register to determine the conditional address of the operand. The index register also can serve as a temporary storage location or a counter.

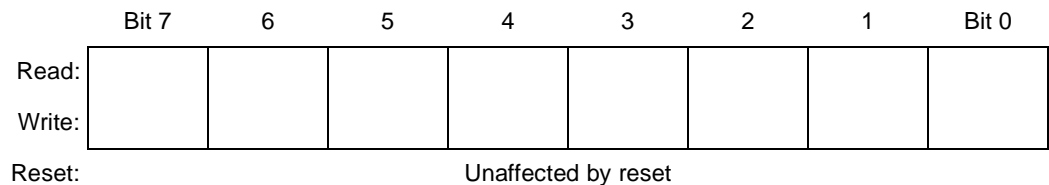


Figure 3-3. Index Register (X)

3.5.3 Stack Pointer

The stack pointer (SP) is a 16-bit register that contains the address of the next location on the stack. During a reset or after the reset stack pointer instruction (RSP), the stack pointer is preset to \$00FF. The address in the stack pointer decrements after a byte is stacked and increments before a byte is unstacked.

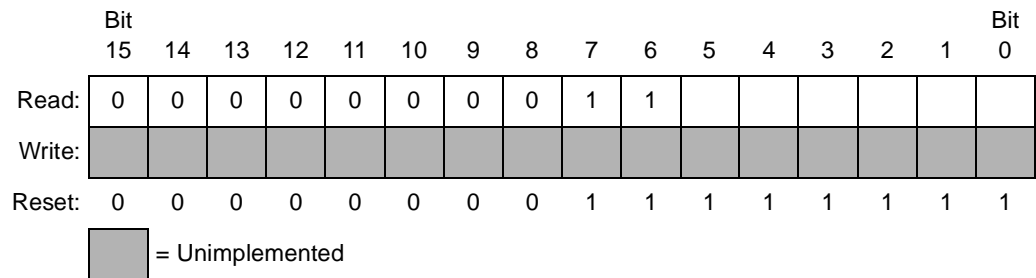


Figure 3-4. Stack Pointer (SP)

The 10 most significant bits of the stack pointer are permanently fixed at 0000000011, so the stack pointer produces addresses from \$00C0 to \$00FF. If subroutines and interrupts use more than 64 stack locations, the stack pointer wraps around to address \$00FF and begins writing over the previously stored data. A subroutine uses two stack locations; an interrupt uses five locations.

Freescale Semiconductor, Inc.

Central Processor Unit (CPU)

3.5.4 Program Counter

The program counter (PC) is a 16-bit register that contains the address of the next instruction or operand to be fetched. The five most significant bits of the program counter are ignored and appear as 00000.

Normally, the address in the program counter automatically increments to the next sequential memory location every time an instruction or operand is fetched. Jump, branch, and interrupt operations load the program counter with an address other than that of the next sequential location.

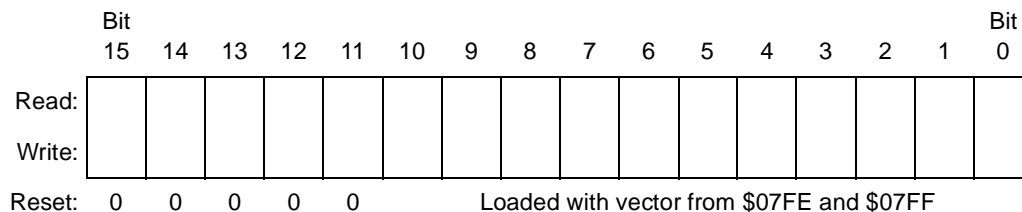


Figure 3-5. Program Counter (PC)

3.5.5 Condition Code Register

The condition code register (CCR) is an 8-bit register whose three most significant bits are permanently fixed at 111. The condition code register contains the interrupt mask and four flags that indicate the results of the instruction just executed.

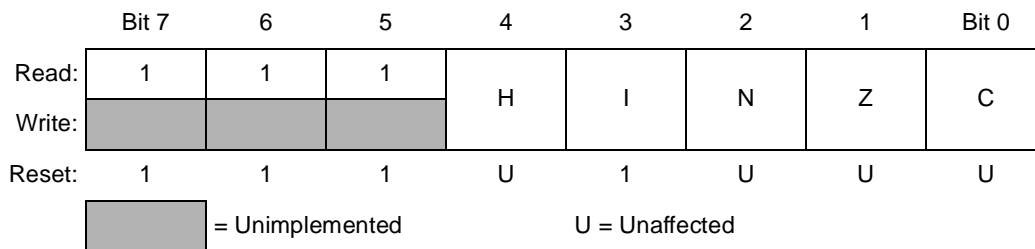


Figure 3-6. Condition Code Register (CCR)

H — Half-Carry Flag

The CPU sets the half-carry flag when a carry occurs between bits 3 and 4 of the accumulator during an ADD (add without carry) or ADC (add with carry) operation. The half-carry flag is required for binary-coded decimal (BCD) arithmetic operations.

I — Interrupt Mask Bit

Setting the interrupt mask disables interrupts. If an interrupt request occurs while the interrupt mask is logic 0, the CPU saves the CPU registers on the stack, sets the interrupt mask, and then fetches the interrupt vector. If an interrupt request occurs while the interrupt mask is logic 1, the interrupt request is latched. Normally, the CPU processes the latched interrupt request as soon as the interrupt mask is cleared again.

A return-from-interrupt instruction (RTI) unstacks the CPU registers, restoring the interrupt mask to its cleared state. After any reset, the interrupt mask is set and can be cleared only by a software instruction.

N — Negative Flag

The CPU sets the negative flag when an ALU operation produces a negative result.

Z — Zero Flag

The CPU sets the zero flag when an ALU operation produces a result of \$00.

C — Carry/Borrow Flag

The CPU sets the carry/borrow flag when an addition operation produces a carry out of bit 7 of the accumulator or when a subtraction operation requires a borrow. Some logical operations and data manipulation instructions also clear or set the carry/borrow flag.

3.6 Instruction Set

The MCU instruction set has 62 instructions and uses eight addressing modes.

3.6.1 Addressing Modes

The CPU uses eight addressing modes for flexibility in accessing data. The addressing modes provide eight different ways for the CPU to find the data required to execute an instruction. The eight addressing modes are:

- Inherent
- Immediate
- Direct
- Extended
- Indexed, no offset
- Indexed, 8-bit offset
- Indexed, 16-bit offset
- Relative

3.6.1.1 *Inherent*

Inherent instructions are those that have no operand, such as return from interrupt (RTI) and stop (STOP). Some of the inherent instructions act on data in the CPU registers, such as set carry flag (SEC) and increment accumulator (INCA). Inherent instructions require no operand address and are one byte long.

3.6.1.2 *Immediate*

Immediate instructions are those that contain a value to be used in an operation with the value in the accumulator or index register. Immediate instructions require no operand address and are two bytes long. The opcode is the first byte, and the immediate data value is the second byte.

3.6.1.3 *Direct*

Direct instructions can access any of the first 256 memory locations with two bytes. The first byte is the opcode, and the second is the low byte of the operand address. In direct addressing, the CPU automatically uses \$00 as the high byte of the operand address.

3.6.1.4 *Extended*

Extended instructions use three bytes and can access any address in memory. The first byte is the opcode; the second and third bytes are the high and low bytes of the operand address.

When using the Freescale assembler, the programmer does not need to specify whether an instruction is direct or extended. The assembler automatically selects the shortest form of the instruction.

3.6.1.5 *Indexed, No Offset*

Indexed instructions with no offset are 1-byte instructions that can access data with variable addresses within the first 256 memory locations. The index register contains the low byte of the effective address of the operand. The CPU automatically uses \$00 as the high byte, so these instructions can address locations \$0000–\$00FF.

Indexed, no offset instructions are often used to move a pointer through a table or to hold the address of a frequently used RAM or input/output (I/O) location.

3.6.1.6 *Indexed, 8-Bit Offset*

Indexed, 8-bit offset instructions are 2-byte instructions that can access data with variable addresses within the first 511 memory locations. The CPU adds the unsigned byte in the index register to the unsigned byte following the opcode. The sum is the effective address of the operand. These instructions can access locations \$0000–\$01FE.

Indexed 8-bit offset instructions are useful for selecting the kth element in an n-element table. The table can begin anywhere within the first 256 memory locations and could extend as far as location 510 (\$01FE).

The k value is typically in the index register, and the address of the beginning of the table is in the byte following the opcode.

3.6.1.7 Indexed, 16-Bit Offset

Indexed, 16-bit offset instructions are 3-byte instructions that can access data with variable addresses at any location in memory. The CPU adds the unsigned byte in the index register to the two unsigned bytes following the opcode. The sum is the effective address of the operand. The first byte after the opcode is the high byte of the 16-bit offset; the second byte is the low byte of the offset.

Indexed, 16-bit offset instructions are useful for selecting the kth element in an n-element table anywhere in memory.

As with direct and extended addressing, the Freescale assembler determines the shortest form of indexed addressing.

3.6.1.8 Relative

Relative addressing is only for branch instructions. If the branch condition is true, the CPU finds the effective branch destination by adding the signed byte following the opcode to the contents of the program counter. If the branch condition is not true, the CPU goes to the next instruction. The offset is a signed, two's complement byte that gives a branching range of -128 to $+127$ bytes from the address of the next location after the branch instruction.

When using the Freescale assembler, the programmer does not need to calculate the offset because the assembler determines the proper offset and verifies that it is within the span of the branch.

3.6.2 Instruction Types

The MCU instructions fall into these five categories:

- Register/memory instructions
- Read-modify-write instructions
- Jump/branch instructions
- Bit manipulation instructions
- Control instructions

3.6.2.1 Register/Memory Instructions

These instructions operate on CPU registers and memory locations. Most of them use two operands. One operand is in either the accumulator or the index register. The CPU finds the other operand in memory.

Table 3-1. Register/Memory Instructions

| Instruction | Mnemonic |
|---|----------|
| Add memory byte and carry bit to accumulator | ADC |
| Add memory byte to accumulator | ADD |
| AND memory byte with accumulator | AND |
| Bit test accumulator | BIT |
| Compare accumulator | CMP |
| Compare index register with memory byte | CPX |
| EXCLUSIVE OR accumulator with memory byte | EOR |
| Load accumulator with memory byte | LDA |
| Load index register with memory byte | LDX |
| Multiply | MUL |
| OR accumulator with memory byte | ORA |
| Subtract memory byte and carry bit from accumulator | SBC |
| Store accumulator in memory | STA |
| Store index register in memory | STX |
| Subtract memory byte from accumulator | SUB |

3.6.2.2 Read-Modify-Write Instructions

These instructions read a memory location or a register, modify its contents, and write the modified value back to the memory location or to the register.

NOTE: Do not use read-modify-write instructions on registers with write-only bits.

Table 3-2. Read-Modify-Write Instructions

| Instruction | Mnemonic |
|-------------------------------------|---------------------|
| Arithmetic shift left (same as LSL) | ASL |
| Arithmetic shift right | ASR |
| Bit clear | BCLR ⁽¹⁾ |
| Bit set | BSET ⁽¹⁾ |
| Clear register | CLR |
| Complement (one's complement) | COM |
| Decrement | DEC |
| Increment | INC |
| Logical shift left (same as ASL) | LSL |
| Logical shift right | LSR |
| Negate (two's complement) | NEG |
| Rotate left through carry bit | ROL |
| Rotate right through carry bit | ROR |
| Test for negative or zero | TST ⁽²⁾ |

1. Unlike other read-modify-write instructions, BCLR and BSET use only direct addressing.
2. TST is an exception to the read-modify-write sequence because it does not write a replacement value.

3.6.2.3 Jump/Branch Instructions

Jump instructions allow the CPU to interrupt the normal sequence of the program counter. The unconditional jump instruction (JMP) and the jump-to-subroutine instruction (JSR) have no register operand. Branch instructions allow the CPU to interrupt the normal sequence of the program counter when a test condition is met. If the test condition is not met, the branch is not performed.

The BRCLR and BRSET instructions cause a branch based on the state of any readable bit in the first 256 memory locations. These 3-byte instructions use a combination of direct addressing and relative addressing. The direct address of the byte to be tested is in the byte following the opcode. The third byte is the signed offset byte. The CPU finds the effective branch destination by adding the third byte to the program counter if the specified bit tests true. The bit to be tested and its condition (set or clear) is part of the opcode. The span of branching is from -128 to $+127$ from the address of the next location after the branch instruction. The CPU also transfers the tested bit to the carry/borrow bit of the condition code register.

NOTE: *Do not use BRCLR or BRSET instructions on registers with write-only bits.*

Table 3-3. Jump and Branch Instructions

| Instruction | Mnemonic |
|--|----------|
| Branch if carry bit clear | BCC |
| Branch if carry bit set | BCS |
| Branch if equal | BEQ |
| Branch if half-carry bit clear | BHCC |
| Branch if half-carry bit set | BHCS |
| Branch if higher | BHI |
| Branch if higher or same | BHS |
| Branch if $\overline{\text{IRQ}}$ pin high | BIH |
| Branch if $\overline{\text{IRQ}}$ pin low | BIL |
| Branch if lower | BLO |
| Branch if lower or same | BLS |
| Branch if interrupt mask clear | BMC |
| Branch if minus | BMI |
| Branch if interrupt mask set | BMS |
| Branch if not equal | BNE |
| Branch if plus | BPL |
| Branch always | BRA |
| Branch if bit clear | BRCLR |
| Branch never | BRN |
| Branch if bit set | BRSET |
| Branch to subroutine | BSR |
| Unconditional jump | JMP |
| Jump to subroutine | JSR |

3.6.2.4 Bit Manipulation Instructions

The CPU can set or clear any writable bit in the first 256 bytes of memory, which includes I/O registers and on-chip RAM locations. The CPU can also test and branch based on the state of any bit in any of the first 256 memory locations.

Table 3-4. Bit Manipulation Instructions

| Instruction | Mnemonic |
|---------------------|----------|
| Bit clear | BCLR |
| Branch if bit clear | BRCLR |
| Branch if bit set | BRSET |
| Bit set | BSET |

NOTE: Do not use bit manipulation instructions on registers with write-only bits.

3.6.2.5 Control Instructions

These instructions act on CPU registers and control CPU operation during program execution.

Table 3-5. Control Instructions

| Instruction | Mnemonic |
|--|----------|
| Clear carry bit | CLC |
| Clear interrupt mask | CLI |
| No operation | NOP |
| Reset stack pointer | RSP |
| Return from interrupt | RTI |
| Return from subroutine | RTS |
| Set carry bit | SEC |
| Set interrupt mask | SEI |
| Stop oscillator and enable $\overline{\text{IRQ}}$ pin | STOP |
| Software interrupt | SWI |
| Transfer accumulator to index register | TAX |
| Transfer index register to accumulator | TXA |
| Stop CPU clock and enable interrupts | WAIT |

3.7 Instruction Set Summary

Table 3-6. Instruction Set Summary (Sheet 1 of 6)

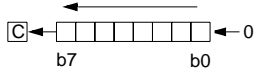
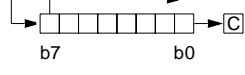
| Source Form | Operation | Description | Effect on CCR | | | | | Address Mode | Opcode | Operand | Cycles |
|--|---------------------------------------|--|---------------|---|---|---|---|--|--|--|--------------------------------------|
| | | | H | I | N | Z | C | | | | |
| ADC #opr ADC opr ADC opr ADC opr,X ADC opr,X ADC ,X | Add with Carry | $A \leftarrow (A) + (M) + (C)$ | ↑ | — | ↑ | ↑ | ↑ | IMM DIR EXT IX2 IX1 IX | A9 B9 C9 D9 E9 F9 | ii dd hh ll ee ff ff | 2 3 4 5 4 3 |
| ADD #opr ADD opr ADD opr ADD opr,X ADD opr,X ADD ,X | Add without Carry | $A \leftarrow (A) + (M)$ | ↑ | — | ↑ | ↑ | ↑ | IMM DIR EXT IX2 IX1 IX | AB BB CB DB EB FB | ii dd hh ll ee ff ff | 2 3 4 5 4 3 |
| AND #opr AND opr AND opr AND opr,X AND opr,X AND ,X | Logical AND | $A \leftarrow (A) \wedge (M)$ | — | — | ↑ | ↑ | — | IMM DIR EXT IX2 IX1 IX | A4 B4 C4 D4 E4 F4 | ii dd hh ll ee ff ff | 2 3 4 5 4 3 |
| ASL opr ASLA ASLX ASL opr,X ASL ,X | Arithmetic Shift Left (Same as LSL) |  | — | — | ↑ | ↑ | ↑ | DIR INH INH IX1 IX | 38 48 58 68 78 | dd ff | 5 3 3 6 5 |
| ASR opr ASRA ASRX ASR opr,X ASR ,X | Arithmetic Shift Right |  | — | — | ↑ | ↑ | ↑ | DIR INH INH IX1 IX | 37 47 57 67 77 | dd ff | 5 3 3 6 5 |
| BCC rel | Branch if Carry Bit Clear | $PC \leftarrow (PC) + 2 + rel ? C = 0$ | — | — | — | — | — | REL | 24 | rr | 3 |
| BCLR n opr | Clear Bit n | $M_n \leftarrow 0$ | — | — | — | — | — | DIR (b0) DIR (b1) DIR (b2) DIR (b3) DIR (b4) DIR (b5) DIR (b6) DIR (b7) | 11 13 15 17 19 1B 1D 1F | dd dd dd dd dd dd dd dd | 5 5 5 5 5 5 5 5 |
| BCS rel | Branch if Carry Bit Set (Same as BLO) | $PC \leftarrow (PC) + 2 + rel ? C = 1$ | — | — | — | — | — | REL | 25 | rr | 3 |
| BEQ rel | Branch if Equal | $PC \leftarrow (PC) + 2 + rel ? Z = 1$ | — | — | — | — | — | REL | 27 | rr | 3 |
| BHCC rel | Branch if Half-Carry Bit Clear | $PC \leftarrow (PC) + 2 + rel ? H = 0$ | — | — | — | — | — | REL | 28 | rr | 3 |
| BHCS rel | Branch if Half-Carry Bit Set | $PC \leftarrow (PC) + 2 + rel ? H = 1$ | — | — | — | — | — | REL | 29 | rr | 3 |

Table 3-6. Instruction Set Summary (Sheet 2 of 6)

| Source Form | Operation | Description | Effect on CCR | | | | | Address Mode | Opcode | Operand | Cycles |
|--|---------------------------------------|---|---------------|---|---|---|---|--|--|--|--------------------------------------|
| | | | H | I | N | Z | C | | | | |
| BHI <i>rel</i> | Branch if Higher | $PC \leftarrow (PC) + 2 + rel ? C \vee Z = 0$ | — | — | — | — | — | REL | 22 | rr | 3 |
| BHS <i>rel</i> | Branch if Higher or Same | $PC \leftarrow (PC) + 2 + rel ? C = 0$ | — | — | — | — | — | REL | 24 | rr | 3 |
| BIH <i>rel</i> | Branch if IRQ Pin High | $PC \leftarrow (PC) + 2 + rel ? IRQ = 1$ | — | — | — | — | — | REL | 2F | rr | 3 |
| BIL <i>rel</i> | Branch if IRQ Pin Low | $PC \leftarrow (PC) + 2 + rel ? IRQ = 0$ | — | — | — | — | — | REL | 2E | rr | 3 |
| BIT # <i>opr</i> BIT <i>opr</i> BIT <i>opr</i> BIT <i>opr</i> ,X BIT <i>opr</i> ,X BIT ,X | Bit Test Accumulator with Memory Byte | $(A) \wedge (M)$ | — | — | ↓ | ↓ | — | IMM DIR EXT IX2 IX1 IX | A5 B5 C5 D5 E5 F5 | ii dd hh ll ee ff ff | 2 3 4 5 4 3 |
| BLO <i>rel</i> | Branch if Lower (Same as BCS) | $PC \leftarrow (PC) + 2 + rel ? C = 1$ | — | — | — | — | — | REL | 25 | rr | 3 |
| BLS <i>rel</i> | Branch if Lower or Same | $PC \leftarrow (PC) + 2 + rel ? C \vee Z = 1$ | — | — | — | — | — | REL | 23 | rr | 3 |
| BMC <i>rel</i> | Branch if Interrupt Mask Clear | $PC \leftarrow (PC) + 2 + rel ? I = 0$ | — | — | — | — | — | REL | 2C | rr | 3 |
| BMI <i>rel</i> | Branch if Minus | $PC \leftarrow (PC) + 2 + rel ? N = 1$ | — | — | — | — | — | REL | 2B | rr | 3 |
| BMS <i>rel</i> | Branch if Interrupt Mask Set | $PC \leftarrow (PC) + 2 + rel ? I = 1$ | — | — | — | — | — | REL | 2D | rr | 3 |
| BNE <i>rel</i> | Branch if Not Equal | $PC \leftarrow (PC) + 2 + rel ? Z = 0$ | — | — | — | — | — | REL | 26 | rr | 3 |
| BPL <i>rel</i> | Branch if Plus | $PC \leftarrow (PC) + 2 + rel ? N = 0$ | — | — | — | — | — | REL | 2A | rr | 3 |
| BRA <i>rel</i> | Branch Always | $PC \leftarrow (PC) + 2 + rel ? 1 = 1$ | — | — | — | — | — | REL | 20 | rr | 3 |
| BRCLR <i>n opr rel</i> | Branch if Bit n Clear | $PC \leftarrow (PC) + 2 + rel ? Mn = 0$ | — | — | — | — | ↓ | DIR (b0) DIR (b1) DIR (b2) DIR (b3) DIR (b4) DIR (b5) DIR (b6) DIR (b7) | 01 03 05 07 09 0B 0D 0F | dd rr dd rr dd rr dd rr dd rr dd rr dd rr dd rr | 5 5 5 5 5 5 5 5 |
| BRN <i>rel</i> | Branch Never | $PC \leftarrow (PC) + 2 + rel ? 1 = 0$ | — | — | — | — | — | REL | 21 | rr | 3 |
| BRSET <i>n opr rel</i> | Branch if Bit n Set | $PC \leftarrow (PC) + 2 + rel ? Mn = 1$ | — | — | — | — | ↑ | DIR (b0) DIR (b1) DIR (b2) DIR (b3) DIR (b4) DIR (b5) DIR (b6) DIR (b7) | 00 02 04 06 08 0A 0C 0E | dd rr dd rr dd rr dd rr dd rr dd rr dd rr dd rr | 5 5 5 5 5 5 5 5 |
| BSET <i>n opr</i> | Set Bit n | $Mn \leftarrow 1$ | — | — | — | — | — | DIR (b0) DIR (b1) DIR (b2) DIR (b3) DIR (b4) DIR (b5) DIR (b6) DIR (b7) | 10 12 14 16 18 1A 1C 1E | dd dd dd dd dd dd dd dd | 5 5 5 5 5 5 5 5 |

Table 3-6. Instruction Set Summary (Sheet 3 of 6)

| Source Form | Operation | Description | Effect on CCR | | | | | Address Mode | Opcode | Operand | Cycles |
|--|---|--|---------------|---|---|---|---|---------------------------------------|----------------------------------|----------------------------------|----------------------------|
| | | | H | I | N | Z | C | | | | |
| BSR <i>rel</i> | Branch to Subroutine | PC ← (PC) + 2; push (PCL) SP ← (SP) - 1; push (PCH) SP ← (SP) - 1 PC ← (PC) + <i>rel</i> | — | — | — | — | — | REL | AD | rr | 6 |
| CLC | Clear Carry Bit | C ← 0 | — | — | — | — | 0 | INH | 98 | | 2 |
| CLI | Clear Interrupt Mask | I ← 0 | — | 0 | — | — | — | INH | 9A | | 2 |
| CLR <i>opr</i> CLRA CLR X CLR <i>opr,X</i> CLR ,X | Clear Byte | M ← \$00 A ← \$00 X ← \$00 M ← \$00 M ← \$00 | — | — | 0 | 1 | — | DIR INH INH IX1 IX | 3F 4F 5F 6F 7F | dd ff | 5 3 3 6 5 |
| CMP # <i>opr</i> CMP <i>opr</i> CMP <i>opr</i> CMP <i>opr,X</i> CMP <i>opr,X</i> CMP ,X | Compare Accumulator with Memory Byte | (A) - (M) | — | — | ↑ | ↑ | ↑ | IMM DIR EXT IX2 IX1 IX | A1 B1 C1 D1 E1 F1 | ii dd hh ll ee ff ff | 2 3 4 5 4 3 |
| COM <i>opr</i> COMA COM X COM <i>opr,X</i> COM ,X | Complement Byte (One's Complement) | $M \leftarrow \overline{(M)} = \$FF - (M)$ $A \leftarrow \overline{(A)} = \$FF - (A)$ $X \leftarrow \overline{(X)} = \$FF - (X)$ $M \leftarrow \overline{(M)} = \$FF - (M)$ $M \leftarrow \overline{(M)} = \$FF - (M)$ | — | — | ↑ | ↑ | 1 | DIR INH INH IX1 IX | 33 43 53 63 73 | dd ff | 5 3 3 6 5 |
| CPX # <i>opr</i> CPX <i>opr</i> CPX <i>opr</i> CPX <i>opr,X</i> CPX <i>opr,X</i> CPX ,X | Compare Index Register with Memory Byte | (X) - (M) | — | — | ↑ | ↑ | ↑ | IMM DIR EXT IX2 IX1 IX | A3 B3 C3 D3 E3 F3 | ii dd hh ll ee ff ff | 2 3 4 5 4 3 |
| DEC <i>opr</i> DECA DEC X DEC <i>opr,X</i> DEC ,X | Decrement Byte | M ← (M) - 1 A ← (A) - 1 X ← (X) - 1 M ← (M) - 1 M ← (M) - 1 | — | — | ↑ | ↑ | — | DIR INH INH IX1 IX | 3A 4A 5A 6A 7A | dd ff | 5 3 3 6 5 |
| EOR # <i>opr</i> EOR <i>opr</i> EOR <i>opr</i> EOR <i>opr,X</i> EOR <i>opr,X</i> EOR ,X | EXCLUSIVE OR Accumulator with Memory Byte | A ← (A) ⊕ (M) | — | — | ↑ | ↑ | — | IMM DIR EXT IX2 IX1 IX | A8 B8 C8 D8 E8 F8 | ii dd hh ll ee ff ff | 2 3 4 5 4 3 |
| INC <i>opr</i> INCA INC X INC <i>opr,X</i> INC ,X | Increment Byte | M ← (M) + 1 A ← (A) + 1 X ← (X) + 1 M ← (M) + 1 M ← (M) + 1 | — | — | ↑ | ↑ | — | DIR INH INH IX1 IX | 3C 4C 5C 6C 7C | dd ff | 5 3 3 6 5 |

Table 3-6. Instruction Set Summary (Sheet 4 of 6)

| Source Form | Operation | Description | Effect on CCR | | | | | Address Mode | Opcode | Operand | Cycles |
|--|--------------------------------------|---|---------------|---|---|---|---|---------------------------------------|----------------------------------|--|----------------------------|
| | | | H | I | N | Z | C | | | | |
| JMP <i>opr</i> JMP <i>opr</i> JMP <i>opr,X</i> JMP <i>opr,X</i> JMP ,X | Unconditional Jump | PC ← Jump Address | — | — | — | — | — | DIR EXT IX2 IX1 IX | BC CC DC EC FC | dd hh ll ee ff ff ff | 2 3 4 3 2 |
| JSR <i>opr</i> JSR <i>opr</i> JSR <i>opr,X</i> JSR <i>opr,X</i> JSR ,X | Jump to Subroutine | PC ← (PC) + n (n = 1, 2, or 3) Push (PCL); SP ← (SP) - 1 Push (PCH); SP ← (SP) - 1 PC ← Effective Address | — | — | — | — | — | DIR EXT IX2 IX1 IX | BD CD DD ED FD | dd hh ll ee ff ff ff | 5 6 7 6 5 |
| LDA # <i>opr</i> LDA <i>opr</i> LDA <i>opr</i> LDA <i>opr,X</i> LDA <i>opr,X</i> LDA ,X | Load Accumulator with Memory Byte | A ← (M) | — | — | ↑ | ↑ | — | IMM DIR EXT IX2 IX1 IX | A6 B6 C6 D6 E6 F6 | ii dd hh ll ee ff ff ff | 2 3 4 5 4 3 |
| LDX # <i>opr</i> LDX <i>opr</i> LDX <i>opr</i> LDX <i>opr,X</i> LDX <i>opr,X</i> LDX ,X | Load Index Register with Memory Byte | X ← (M) | — | — | ↑ | ↑ | — | IMM DIR EXT IX2 IX1 IX | AE BE CE DE EE FE | ii dd hh ll ee ff ff ff | 2 3 4 5 4 3 |
| LSL <i>opr</i> LSLA LSLX LSL <i>opr,X</i> LSL ,X | Logical Shift Left (Same as ASL) | | — | — | ↑ | ↑ | ↑ | DIR INH INH IX1 IX | 38 48 58 68 78 | dd ff ff | 5 3 3 6 5 |
| LSR <i>opr</i> LSRA LSRX LSR <i>opr,X</i> LSR ,X | Logical Shift Right | | — | — | 0 | ↑ | ↑ | DIR INH INH IX1 IX | 34 44 54 64 74 | dd ff ff | 5 3 3 6 5 |
| MUL | Unsigned Multiply | X : A ← (X) × (A) | 0 | — | — | — | 0 | INH | 42 | | 11 |
| NEG <i>opr</i> NEGA NEGX NEG <i>opr,X</i> NEG ,X | Negate Byte (Two's Complement) | M ← -(M) = \$00 - (M) A ← -(A) = \$00 - (A) X ← -(X) = \$00 - (X) M ← -(M) = \$00 - (M) M ← -(M) = \$00 - (M) | — | — | ↑ | ↑ | ↑ | DIR INH INH IX1 IX | 30 40 50 60 70 | dd ff ff | 5 3 3 6 5 |
| NOP | No Operation | | — | — | — | — | — | INH | 9D | | 2 |
| ORA # <i>opr</i> ORA <i>opr</i> ORA <i>opr</i> ORA <i>opr,X</i> ORA <i>opr,X</i> ORA ,X | Logical OR Accumulator with Memory | A ← (A) ∨ (M) | — | — | ↑ | ↑ | — | IMM DIR EXT IX2 IX1 IX | AA BA CA DA EA FA | ii dd hh ll ee ff ff ff | 2 3 4 5 4 3 |

Table 3-6. Instruction Set Summary (Sheet 5 of 6)

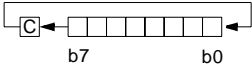
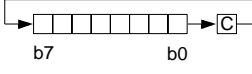
| Source Form | Operation | Description | Effect on CCR | | | | | Address Mode | Opcode | Operand | Cycles |
|--|---|---|---------------|---|---|---|---|---------------------------------------|----------------------------------|----------------------------------|----------------------------|
| | | | H | I | N | Z | C | | | | |
| ROL <i>opr</i> ROLA ROLX ROL <i>opr</i> ,X ROL ,X | Rotate Byte Left through Carry Bit |  | — | — | ↑ | ↑ | ↑ | DIR INH INH IX1 IX | 39 49 59 69 79 | dd ff | 5 3 3 6 5 |
| ROR <i>opr</i> RORA RORX ROR <i>opr</i> ,X ROR ,X | Rotate Byte Right through Carry Bit |  | — | — | ↑ | ↑ | ↑ | DIR INH INH IX1 IX | 36 46 56 66 76 | dd ff | 5 3 3 6 5 |
| RSP | Reset Stack Pointer | SP ← \$00FF | — | — | — | — | — | INH | 9C | | 2 |
| RTI | Return from Interrupt | SP ← (SP) + 1; Pull (CCR) SP ← (SP) + 1; Pull (A) SP ← (SP) + 1; Pull (X) SP ← (SP) + 1; Pull (PCH) SP ← (SP) + 1; Pull (PCL) | ↑ | ↑ | ↑ | ↑ | ↑ | INH | 80 | | 9 |
| RTS | Return from Subroutine | SP ← (SP) + 1; Pull (PCH) SP ← (SP) + 1; Pull (PCL) | — | — | — | — | — | INH | 81 | | 6 |
| SBC # <i>opr</i> SBC <i>opr</i> SBC <i>opr</i> SBC <i>opr</i> ,X SBC <i>opr</i> ,X SBC ,X | Subtract Memory Byte and Carry Bit from Accumulator | A ← (A) – (M) – (C) | — | — | ↑ | ↑ | ↑ | IMM DIR EXT IX2 IX1 IX | A2 B2 C2 D2 E2 F2 | ii dd hh ll ee ff ff | 2 3 4 5 4 3 |
| SEC | Set Carry Bit | C ← 1 | — | — | — | — | 1 | INH | 99 | | 2 |
| SEI | Set Interrupt Mask | I ← 1 | — | 1 | — | — | — | INH | 9B | | 2 |
| STA <i>opr</i> STA <i>opr</i> STA <i>opr</i> ,X STA <i>opr</i> ,X STA ,X | Store Accumulator in Memory | M ← (A) | — | — | ↑ | ↑ | — | DIR EXT IX2 IX1 IX | B7 C7 D7 E7 F7 | dd hh ll ee ff ff | 4 5 6 5 4 |
| STOP | Stop Oscillator and Enable IRQ Pin | | — | 0 | — | — | — | INH | 8E | | 2 |
| STX <i>opr</i> STX <i>opr</i> STX <i>opr</i> ,X STX <i>opr</i> ,X STX ,X | Store Index Register In Memory | M ← (X) | — | — | ↑ | ↑ | — | DIR EXT IX2 IX1 IX | BF CF DF EF FF | dd hh ll ee ff ff | 4 5 6 5 4 |
| SUB # <i>opr</i> SUB <i>opr</i> SUB <i>opr</i> SUB <i>opr</i> ,X SUB <i>opr</i> ,X SUB ,X | Subtract Memory Byte from Accumulator | A ← (A) – (M) | — | — | ↑ | ↑ | ↑ | IMM DIR EXT IX2 IX1 IX | A0 B0 C0 D0 E0 F0 | ii dd hh ll ee ff ff | 2 3 4 5 4 3 |

Table 3-6. Instruction Set Summary (Sheet 6 of 6)

| Source Form | Operation | Description | Effect on CCR | | | | | Address Mode | Opcode | Operand | Cycles |
|--|--|--|---------------|---|---|---|---|--------------------------------|----------------------------|--------------|-----------------------|
| | | | H | I | N | Z | C | | | | |
| SWI | Software Interrupt | PC ← (PC) + 1; Push (PCL) SP ← (SP) - 1; Push (PCH) SP ← (SP) - 1; Push (X) SP ← (SP) - 1; Push (A) SP ← (SP) - 1; Push (CCR) SP ← (SP) - 1; I ← 1 PCH ← Interrupt Vector High Byte PCL ← Interrupt Vector Low Byte | — | 1 | — | — | — | INH | 83 | | 10 |
| TAX | Transfer Accumulator to Index Register | X ← (A) | — | — | — | — | — | INH | 97 | | 2 |
| TST <i>opr</i> TSTA TSTX TST <i>opr,X</i> TST ,X | Test Memory Byte for Negative or Zero | (M) - \$00 | — | — | ↑ | ↓ | — | DIR INH INH IX1 IX | 3D 4D 5D 6D 7D | dd ff | 4 3 3 5 4 |
| TXA | Transfer Index Register to Accumulator | A ← (X) | — | — | — | — | — | INH | 9F | | 2 |
| WAIT | Stop CPU Clock and Enable Interrupts | | — | ↑ | — | — | — | INH | 8F | | 2 |

- | | | | |
|-------|---|------------|--------------------------------------|
| A | Accumulator | <i>opr</i> | Operand (one or two bytes) |
| C | Carry/borrow flag | PC | Program counter |
| CCR | Condition code register | PCH | Program counter high byte |
| dd | Direct address of operand | PCL | Program counter low byte |
| dd rr | Direct address of operand and relative offset of branch instruction | REL | Relative addressing mode |
| DIR | Direct addressing mode | <i>rel</i> | Relative program counter offset byte |
| ee ff | High and low bytes of offset in indexed, 16-bit offset addressing | rr | Relative program counter offset byte |
| EXT | Extended addressing mode | SP | Stack pointer |
| ff | Offset byte in indexed, 8-bit offset addressing | X | Index register |
| H | Half-carry flag | Z | Zero flag |
| hh ll | High and low bytes of operand address in extended addressing | # | Immediate value |
| I | Interrupt mask | ^ | Logical AND |
| ii | Immediate operand byte | ∨ | Logical OR |
| IMM | Immediate addressing mode | ⊕ | Logical EXCLUSIVE OR |
| INH | Inherent addressing mode | () | Contents of |
| IX | Indexed, no offset addressing mode | -() | Negation (two's complement) |
| IX1 | Indexed, 8-bit offset addressing mode | ← | Loaded with |
| IX2 | Indexed, 16-bit offset addressing mode | ? | If |
| M | Memory location | : | Concatenated with |
| N | Negative flag | ↑ | Set or cleared |
| n | Any bit | — | Not affected |

3.8 Opcode Map

See [Table 3-7](#).

Table 3-7. Opcode Map

| MSB LSB | Bit Manipulation | | Branch | | Read-Modify-Write | | | | Control | | | Register/Memory | | | | | | MSB LSB | |
|------------|------------------|-----------|-----------|-----------|-------------------|-----------|-----------|-----------|----------|-----------|-----------|-----------------|----------|-----------|-----------|----------|----------|------------|---|
| | DIR | DIR | REL | REL | DIR | INH | INH | IX1 | IX | INH | INH | IMM | DIR | EXT | IX2 | IX1 | IX | | |
| 0 | 5 DIR2 | 5 DIR2 | 3 REL2 | 3 REL2 | 5 DIR1 | 3 INH1 | 3 INH2 | 6 IX11 | 5 IX1 | 9 INH | 8 INH | 9 INH | 2 SUB | 3 SUB | 4 EXT3 | 5 SUB | 4 SUB | 3 SUB | 0 |
| 1 | 5 DIR2 | 5 DIR2 | 3 REL | 3 REL | | | | | | 6 INH | 1 INH | 2 CMP | 3 CMP | 4 EXT3 | 5 CMP | 4 CMP | 5 CMP | 4 CMP | 1 |
| 2 | 5 DIR2 | 5 DIR2 | 3 REL | 3 REL | 11 INH | | | | | | | 2 SBC | 3 SBC | 4 EXT3 | 5 SBC | 4 SBC | 5 SBC | 4 SBC | 2 |
| 3 | 3 DIR1 | 3 DIR1 | 3 REL2 | 3 REL2 | 3 DIR1 | 3 INH1 | 3 INH2 | 6 IX11 | 5 IX1 | 10 INH | 10 INH | 2 CPX | 3 CPX | 4 EXT3 | 5 CPX | 4 CPX | 5 CPX | 4 CPX | 3 |
| 4 | 3 DIR2 | 3 DIR2 | 3 REL2 | 3 REL2 | 5 DIR1 | 3 INH1 | 3 INH2 | 6 IX11 | 5 IX1 | | | 2 AND | 3 AND | 4 EXT3 | 5 AND | 4 AND | 5 AND | 4 AND | 4 |
| 5 | 3 DIR2 | 3 DIR2 | 3 REL2 | 3 REL2 | | | | | | | | 2 BIT | 3 BIT | 4 EXT3 | 5 BIT | 4 BIT | 5 BIT | 4 BIT | 5 |
| 6 | 3 DIR2 | 3 DIR2 | 3 REL2 | 3 REL2 | 5 DIR1 | 3 INH1 | 3 INH2 | 6 IX11 | 5 IX1 | | | 2 LDA | 3 LDA | 4 EXT3 | 5 LDA | 4 LDA | 5 LDA | 4 LDA | 6 |
| 7 | 3 DIR2 | 3 DIR2 | 3 REL2 | 3 REL2 | 5 DIR1 | 3 INH1 | 3 INH2 | 6 IX11 | 5 IX1 | 1 INH | 1 INH | 2 STA | 3 STA | 4 EXT3 | 5 STA | 6 STA | 5 STA | 4 STA | 7 |
| 8 | 3 DIR2 | 3 DIR2 | 3 REL2 | 3 REL2 | 5 DIR1 | 3 INH1 | 3 INH2 | 6 IX11 | 5 IX1 | | | 2 EOR | 3 EOR | 4 EXT3 | 5 EOR | 4 EOR | 5 EOR | 4 EOR | 8 |
| 9 | 3 DIR2 | 3 DIR2 | 3 REL2 | 3 REL2 | 5 DIR1 | 3 INH1 | 3 INH2 | 6 IX11 | 5 IX1 | | | 2 ADC | 3 ADC | 4 EXT3 | 5 ADC | 4 ADC | 5 ADC | 4 ADC | 9 |
| A | 3 DIR2 | 3 DIR2 | 3 REL2 | 3 REL2 | 5 DIR1 | 3 INH1 | 3 INH2 | 6 IX11 | 5 IX1 | | | 2 ORA | 3 ORA | 4 EXT3 | 5 ORA | 4 ORA | 5 ORA | 4 ORA | A |
| B | 3 DIR2 | 3 DIR2 | 3 REL | 3 REL | | | | | | | | 2 ADD | 3 ADD | 4 EXT3 | 5 ADD | 4 ADD | 5 ADD | 4 ADD | B |
| C | 3 DIR2 | 3 DIR2 | 3 REL2 | 3 REL2 | 5 DIR1 | 3 INH1 | 3 INH2 | 6 IX11 | 5 IX1 | | | 2 JMP | 3 JMP | 4 EXT3 | 5 JMP | 4 JMP | 5 JMP | 3 JMP | C |
| D | 3 DIR2 | 3 DIR2 | 3 REL2 | 3 REL2 | 4 DIR1 | 3 INH1 | 3 INH2 | 5 IX11 | 4 IX1 | | | 6 BSR | 7 BSR | 5 EXT3 | 6 BSR | 7 BSR | 6 BSR | 5 BSR | D |
| E | 3 DIR2 | 3 DIR2 | 3 REL | 3 REL | | | | | | 2 INH | 2 INH | 2 LDX | 3 LDX | 4 EXT3 | 5 LDX | 4 LDX | 5 LDX | 4 LDX | E |
| F | 3 DIR2 | 3 DIR2 | 3 REL2 | 3 REL2 | 5 DIR1 | 3 INH1 | 3 INH2 | 6 IX11 | 5 IX1 | 2 INH | 2 INH | 2 STX | 3 STX | 4 EXT3 | 5 STX | 6 STX | 5 STX | 4 STX | F |

INH = Inherent
 IMM = Immediate
 DIR = Direct
 EXT = Extended
 REL = Relative
 IX = Indexed, No Offset
 IX1 = Indexed, 8-Bit Offset
 IX2 = Indexed, 16-Bit Offset
 MSB of Opcode in Hexadecimal
 Number of Cycles
 Opcode Mnemonic
 Number of Bytes/Addressing Mode

Section 4. Resets and Interrupts

4.1 Contents

| | | |
|---------|------------------------------------|----|
| 4.2 | Introduction | 69 |
| 4.3 | Resets | 70 |
| 4.3.1 | Power-On Reset | 71 |
| 4.3.2 | External Reset | 72 |
| 4.3.3 | COP Watchdog Reset | 72 |
| 4.3.4 | Illegal Address Reset | 72 |
| 4.4 | Interrupts | 73 |
| 4.4.1 | Software Interrupt | 73 |
| 4.4.2 | External Interrupt | 73 |
| 4.4.3 | Timer Interrupts | 76 |
| 4.4.3.1 | Real-Time Interrupt | 76 |
| 4.4.3.2 | Timer Overflow Interrupt | 76 |
| 4.4.4 | Interrupt Processing | 76 |

4.2 Introduction

Reset initializes the microcontroller unit (MCU) by returning the program counter to a known address and by forcing control and status bits to known states.

Interrupts temporarily change the sequence of program execution to respond to events that occur during processing.

4.3 Resets

A reset immediately stops the operation of the instruction being executed, initializes certain control and status bits, and loads the program counter with a user-defined reset vector address. These sources can generate a reset:

- Power-on reset (POR) circuit
- $\overline{\text{RESET}}$ pin
- Computer operating properly (COP) watchdog
- Illegal address

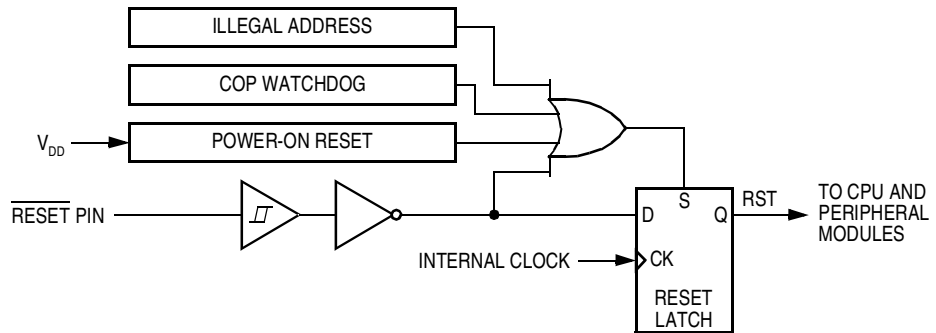


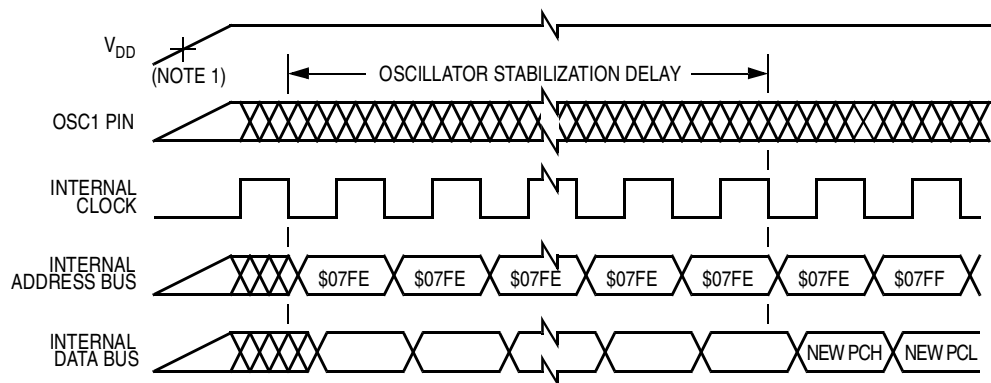
Figure 4-1. Reset Sources

4.3.1 Power-On Reset

A positive transition on the V_{DD} pin generates a power-on reset.

NOTE: *The power-on reset is strictly for power-up conditions and cannot be used to detect drops in power supply voltage.*

A $4064 \cdot t_{cyc}$ (internal clock cycle) delay after the oscillator becomes active allows the clock generator to stabilize. If any reset source is active at the end of this delay, the MCU remains in the reset condition until all reset sources are inactive.

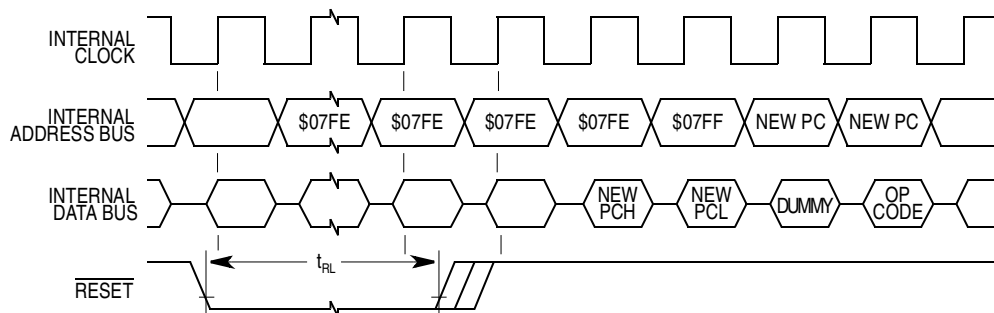


- Notes:
1. Power-on reset threshold is typically between 1 V and 2 V.
 2. Internal clock, internal address bus, and internal data bus are not available externally.

Figure 4-2. Power-On Reset Timing

4.3.2 External Reset

A logic 0 applied to the $\overline{\text{RESET}}$ pin for $1\ 1/2\ t_{\text{cyc}}$ generates an external reset. A Schmitt trigger senses the logic level at the $\overline{\text{RESET}}$ pin.



Notes:

1. Internal clock, internal address bus, and internal data bus are not available externally.
2. The next rising edge of the internal clock after the rising edge of $\overline{\text{RESET}}$ initiates the reset sequence.

Figure 4-3. External Reset Timing

Table 4-1. External Reset Timing

| Characteristic | Symbol | Min | Max | Unit |
|---------------------------------------|-----------------|-----|-----|------------------|
| $\overline{\text{RESET}}$ pulse width | t_{RL} | 1.5 | — | t_{cyc} |

4.3.3 COP Watchdog Reset

A timeout of the COP watchdog generates a COP reset. The COP watchdog is part of a software error detection system and must be cleared periodically to start a new timeout period. To clear the COP watchdog and prevent a COP reset, write a logic 0 to bit 0 (COPC) of the COP register at location \$07F0.

4.3.4 Illegal Address Reset

An opcode fetch from an address not in random-access memory (RAM) or erasable, programmable read-only memory (EPROM) generates a reset.

4.4 Interrupts

These sources can generate interrupts:

- Software interrupt (SWI) instruction
- External interrupt pins:
 - $\overline{\text{IRQ}}/V_{\text{PP}}$
 - PA0–PA3
- Timer:
 - Real-time interrupt flag (RTIF)
 - Timer overflow flag (TOF)

An interrupt temporarily stops the program sequence to process a particular event. An interrupt does not stop the operation of the instruction being executed, but takes effect when the current instruction completes its execution. Interrupt processing automatically saves the CPU registers on the stack and loads the program counter with a user-defined interrupt vector address.

4.4.1 Software Interrupt

The software interrupt (SWI) instruction causes a non-maskable interrupt.

4.4.2 External Interrupt

An interrupt signal on the $\overline{\text{IRQ}}/V_{\text{PP}}$ pin latches an external interrupt request. When the CPU completes its current instruction, it tests the IRQ latch. If the IRQ latch is set, the CPU then tests the I bit in the condition code register. If the I bit is clear, the CPU then begins the interrupt sequence.

The CPU clears the IRQ latch during interrupt processing, so that another interrupt signal on the $\overline{\text{IRQ}}/\text{V}_{\text{PP}}$ pin can latch another interrupt request during the interrupt service routine. As soon as the I bit is cleared during the return from interrupt, the CPU can recognize the new interrupt request. Figure 4-4 shows the $\overline{\text{IRQ}}/\text{V}_{\text{PP}}$ pin interrupt logic.

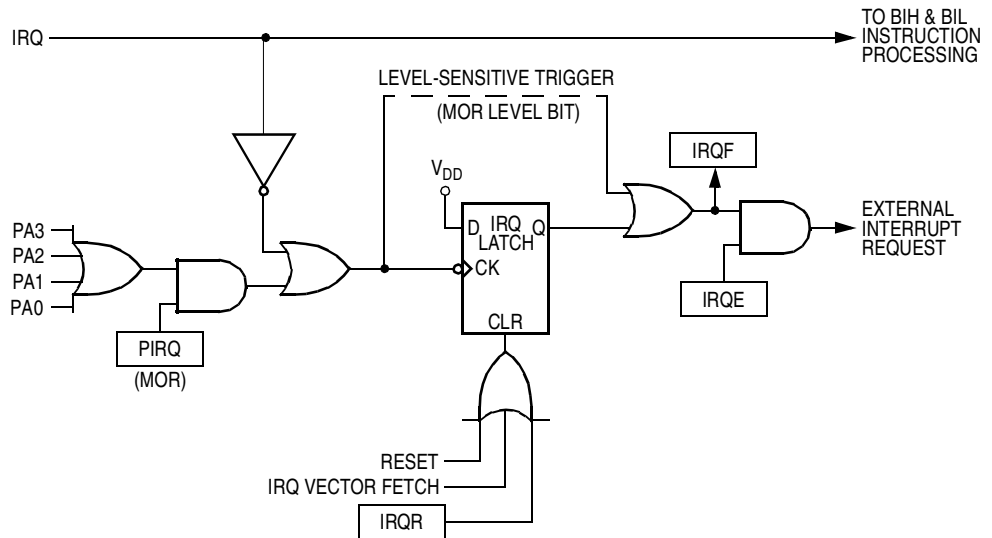


Figure 4-4. External Interrupt Logic

Setting the I bit in the condition code register disables external interrupts.

The port A external interrupt bit (PIRQ) in the mask option register enables pins PA0–PA3 to function as external interrupt pins.

The external interrupt sensitivity bit (LEVEL) in the mask option register controls interrupt triggering sensitivity of external interrupt pins. The $\overline{\text{IRQ}}/\text{V}_{\text{PP}}$ pin can be negative-edge triggered only or negative-edge and low-level triggered. Port A external interrupt pins can be positive-edge triggered only or both positive-edge and high-level triggered. The level-sensitive triggering option allows multiple external interrupt sources to be wire-ORed to an external interrupt pin. An external interrupt request, shown in Figure 4-5, is latched as long as any source is holding an external interrupt pin low.

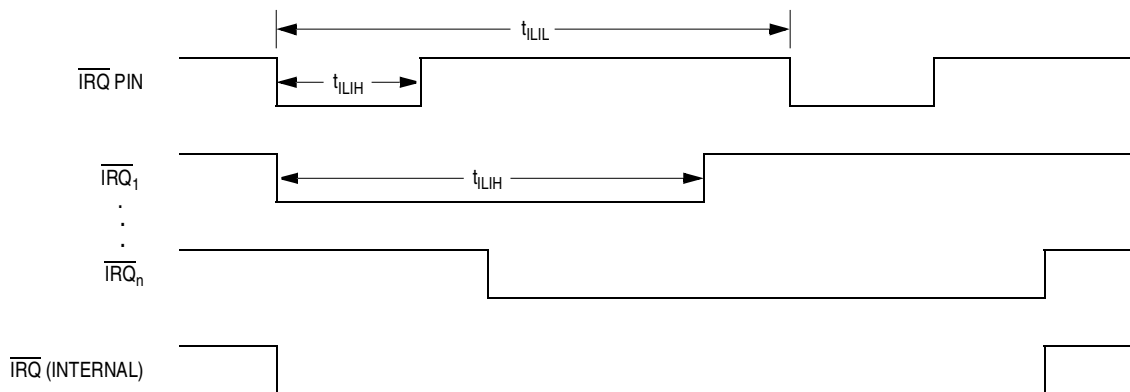


Figure 4-5. External Interrupt Timing

Table 4-2. External Interrupt Timing ($V_{\text{DD}} = 5.0 \text{ Vdc}$)⁽¹⁾

| Characteristic | Symbol | Min | Max | Unit |
|--|-------------------|---------------------|-----|------------------|
| Interrupt pulse width low (edge-triggered) | t_{ILIH} | 125 | — | ns |
| Interrupt pulse period | t_{ILIL} | Note ⁽²⁾ | — | t_{cyc} |

- $V_{\text{DD}} = 5.0 \text{ Vdc} \pm 10\%$, $V_{\text{SS}} = 0 \text{ Vdc}$, $T_{\text{A}} = -40^{\circ}\text{C}$ to $+105^{\circ}\text{C}$, unless otherwise noted
- The minimum, t_{ILIL} , should not be less than the number of interrupt service routine cycles plus $19 t_{\text{cyc}}$.

Table 4-3. External Interrupt Timing ($V_{\text{DD}} = 3.3 \text{ Vdc}$)⁽¹⁾

| Characteristic | Symbol | Min | Max | Unit |
|--|-------------------|---------------------|-----|------------------|
| Interrupt pulse width low (edge-triggered) | t_{ILIH} | 250 | — | ns |
| Interrupt pulse period | t_{ILIL} | Note ⁽²⁾ | — | t_{cyc} |

- $V_{\text{DD}} = 3.3 \text{ Vdc} \pm 10\%$, $V_{\text{SS}} = 0 \text{ Vdc}$, $T_{\text{A}} = -40^{\circ}\text{C}$ to $+105^{\circ}\text{C}$, unless otherwise noted
- The minimum, t_{ILIL} , should not be less than the number of interrupt service routine cycles plus $19 t_{\text{cyc}}$.

4.4.3 Timer Interrupts

The timer can generate these interrupt requests:

- Real time
- Timer overflow

Setting the I bit in the condition code register disables timer interrupts.

4.4.3.1 Real-Time Interrupt

A real-time interrupt occurs if the real-time interrupt flag, RTIF, becomes set while the real-time interrupt enable bit, RTIE, is also set. RTIF and RTIE are in the timer status and control register.

4.4.3.2 Timer Overflow Interrupt

A timer overflow interrupt request occurs if the timer overflow flag, TOF, becomes set while the timer overflow interrupt enable bit, TOIE, is also set. TOF and TOIE are in the timer status and control register.

4.4.4 Interrupt Processing

The CPU takes these actions to begin servicing an interrupt:

- Stores the CPU registers on the stack in the order shown in [Figure 4-6](#)
- Sets the I bit in the condition code register to prevent further interrupts
- Loads the program counter with the contents of the appropriate interrupt vector locations:
 - \$07FC and \$07FD (software interrupt vector)
 - \$07FA and \$07FB (external interrupt vector)
 - \$07F8 and \$07F9 (timer interrupt vector)

The return-from-interrupt (RTI) instruction causes the CPU to recover the CPU registers from the stack as shown in [Figure 4-6](#).

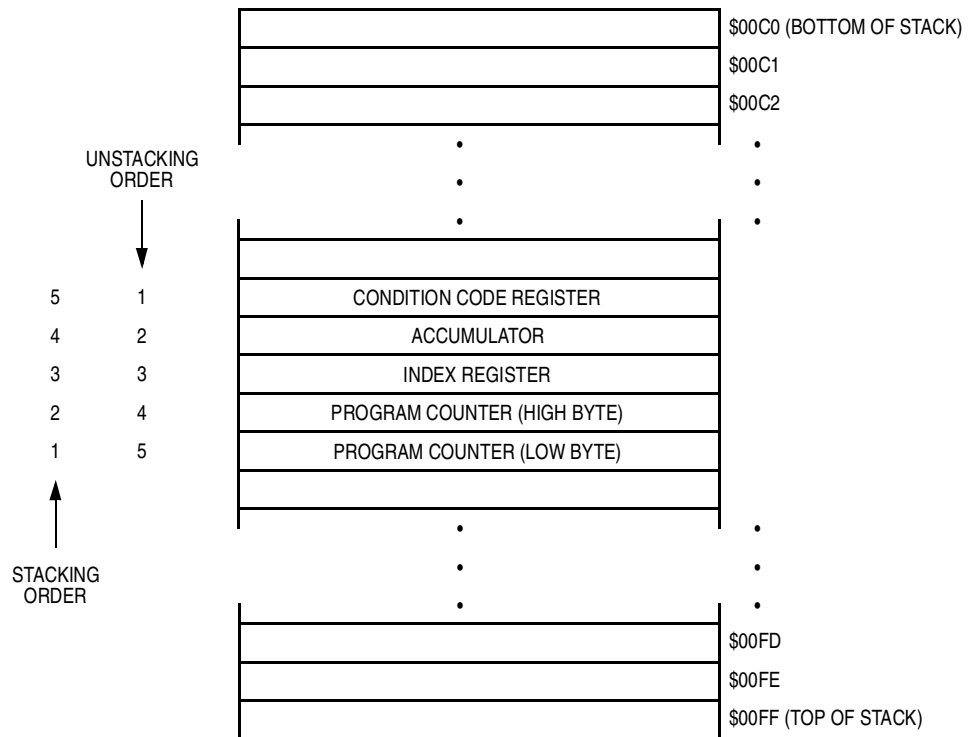


Figure 4-6. Interrupt Stacking Order

Table 4-4. Reset/Interrupt Vector Addresses

| Function | Source | Local Mask | Global Mask | Priority (1 = Highest) | Vector Address |
|--------------------------|--|----------------------|-------------|------------------------------|----------------|
| Reset | Power-on RESET pin COP watchdog ⁽¹⁾ illegal address | None | None | 1 | \$07FE-\$07FF |
| Software interrupt (SWI) | User code | None | None | Same priority as instruction | \$07FC-\$07FD |
| External interrupt | \overline{IRQ}/V_{PP} pin | IRQE | I bit | 2 | \$07FA-\$07FB |
| Timer interrupts | RTIF bit TOF bit | RTIE bit TOIE bit | I bit | 3 | \$07F8-\$07F9 |

1. The COP watchdog is programmable in the mask option register.

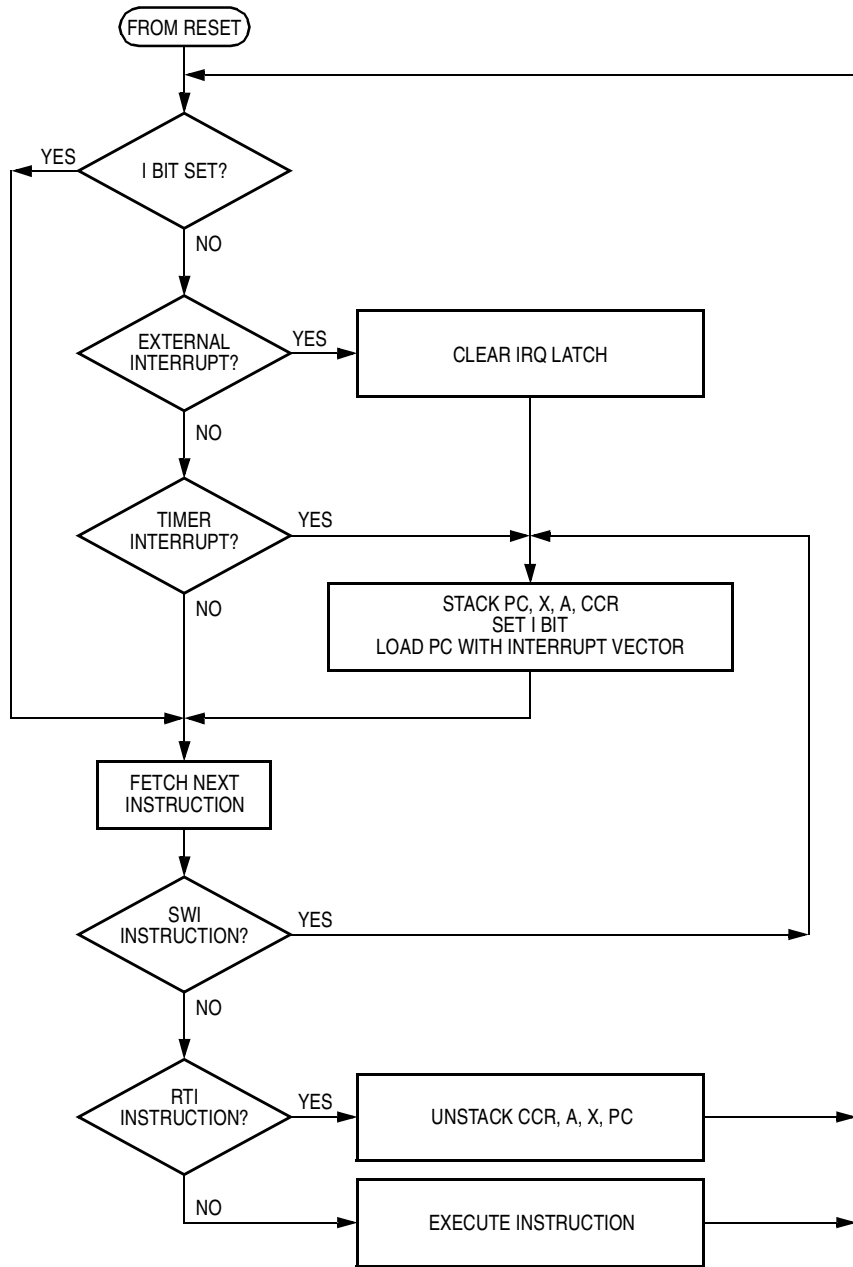


Figure 4-7. Interrupt Flowchart

Section 5. Low-Power Modes

5.1 Contents

| | | |
|-------|--|----|
| 5.2 | Introduction | 79 |
| 5.3 | Exiting Stop and Wait Modes | 80 |
| 5.4 | Effects of Stop and Wait Modes | 81 |
| 5.4.1 | Clock Generation | 81 |
| 5.4.2 | CPU | 82 |
| 5.4.3 | COP Watchdog | 82 |
| 5.4.4 | Timer | 83 |
| 5.4.5 | EPROM/OTPROM | 84 |
| 5.4.6 | Data-Retention Mode | 84 |
| 5.5 | Timing | 85 |

5.2 Introduction

The microcontroller unit (MCU) can enter these low-power standby modes:

- Stop mode — The STOP instruction puts the MCU in its lowest power-consumption mode.
- Wait mode — The WAIT instruction puts the MCU in an intermediate power-consumption mode.
- Halt mode — Halt mode is identical to wait mode, except that an oscillator stabilization delay of 1 to 4064 internal clock cycles occurs when the MCU exits halt mode. The stop-to-wait conversion bit, SWAIT, in the mask option register, enables halt mode.

Enabling halt mode prevents the computer operating properly (COP) watchdog from being inadvertently turned off by a STOP instruction.

- Data-retention mode — In data-retention mode, the MCU retains RAM contents and CPU register contents at V_{DD} voltages as low as 2.0 Vdc. The data-retention feature allows the MCU to remain in a low power-consumption state during which it retains data, but the CPU cannot execute instructions.

5.3 Exiting Stop and Wait Modes

The events described in this subsection bring the MCU out of stop mode and load the program counter with the reset vector or with an interrupt vector.

Exiting stop mode:

- External reset — A logic 0 on the $\overline{\text{RESET}}$ pin resets the MCU, starts the CPU clock, and loads the program counter with the contents of locations \$07FE and \$07FF.
- External interrupt — A high-to-low transition on the $\overline{\text{IRQ}}/V_{PP}$ pin or a low-to-high transition on an enabled port A external interrupt pin starts the CPU clock and loads the program counter with the contents of locations \$07FA and \$07FB.

Exiting wait mode:

- External reset — A logic 0 on the $\overline{\text{RESET}}$ pin resets the MCU, starts the CPU clock, and loads the program counter with the contents of locations \$07FE and \$07FF.
- External interrupt — A high-to-low transition on the $\overline{\text{IRQ}}/V_{PP}$ pin or a low-to-high transition on an enabled port A external interrupt pin starts the CPU clock and loads the program counter with the contents of locations \$07FA and \$07FB.

- COP watchdog reset — A timeout of the COP watchdog resets the MCU, starts the CPU clock, and loads the program counter with the contents of locations \$07FE and \$07FF. Software can enable timer interrupts so that the MCU periodically can exit wait mode to reset the COP watchdog.
- Timer interrupt — Real-time interrupt requests and timer overflow interrupt requests start the MCU clock and load the program counter with the contents of locations \$07F8 and \$07F9.

5.4 Effects of Stop and Wait Modes

The STOP and WAIT instructions have the effects described in this subsection on MCU modules.

5.4.1 Clock Generation

The STOP instruction:

The STOP instruction disables the internal oscillator, stopping the CPU clock and all peripheral clocks.

After exiting stop mode, the CPU clock and all enabled peripheral clocks begin running after the oscillator stabilization delay.

NOTE: *The oscillator stabilization delay holds the MCU in reset for the first 4064 internal clock cycles.*

The WAIT instruction:

The WAIT instruction disables the CPU clock.

After exiting wait mode, the CPU clock and all enabled peripheral clocks immediately begin running.

5.4.2 CPU

The STOP instruction:

- Clears the interrupt mask (I bit) in the condition code register, enabling external interrupts
- Disables the CPU clock

After exiting stop mode, the CPU clock begins running after the oscillator stabilization delay.

After exit from stop mode by external interrupt, the I bit remains clear.

After exit from stop mode by reset, the I bit is set.

The WAIT instruction:

- Clears the interrupt mask (I bit) in the condition code register, enabling interrupts
- Disables the CPU clock

After exit from wait mode by interrupt, the I bit remains clear.

After exit from wait mode by reset, the I bit is set.

5.4.3 COP Watchdog

The STOP instruction:

- Clears the COP watchdog counter
- Disables the COP watchdog clock

NOTE: *To prevent the STOP instruction from disabling the COP watchdog, program the stop-to-wait conversion bit (SWAIT) in the mask option register to logic 1.*

After exit from stop mode by external interrupt, the COP watchdog counter immediately begins counting from \$0000 and continues counting throughout the oscillator stabilization delay.

NOTE: *Immediately after exiting stop mode by external interrupt, service the COP to ensure a full COP timeout period.*

After exit from stop mode by reset:

- The COP watchdog counter immediately begins counting from \$0000.
- The COP watchdog counter is cleared at the end of the oscillator stabilization delay and begins counting from \$0000 again.

The WAIT instruction:

The WAIT instruction has no effect on the COP watchdog.

NOTE: *To prevent a COP timeout during wait mode, exit wait mode periodically to service the COP.*

5.4.4 Timer

The STOP instruction:

- Clears the RTIE, TOFE, RTIF, and TOF bits in the timer status and control register, disabling timer interrupt requests and removing any pending timer interrupt requests
- Disables the clock to the timer

After exiting stop mode by external interrupt, the timer immediately resumes counting from the last value before the STOP instruction and continues counting throughout the oscillator stabilization delay.

After exiting stop mode by reset and after the oscillator stabilization delay, the timer resumes operation from its reset state.

The WAIT instruction:

The WAIT instruction has no effect on the timer.

5.4.5 EPROM/OTPROM

The STOP instruction:

The STOP instruction during erasable, programmable read-only memory (EPROM) programming clears the EPGM bit in the EPROM programming register, removing the programming voltage from the EPROM.

The WAIT instruction:

The WAIT instruction has no effect on EPROM/one-time programmable read-only memory (OTPROM) operation.

5.4.6 Data-Retention Mode

In data-retention mode, the MCU retains random-access memory (RAM) contents and CPU register contents at V_{DD} voltages as low as 2.0 Vdc. The data-retention feature allows the MCU to remain in a low power-consumption state during which it retains data, but the CPU cannot execute instructions.

To put the MCU in data-retention mode:

1. Drive the $\overline{\text{RESET}}$ pin to logic 0.
2. Lower the V_{DD} voltage. The $\overline{\text{RESET}}$ pin must remain low continuously during data-retention mode.

To take the MCU out of data-retention mode:

1. Return V_{DD} to normal operating voltage.
2. Return the $\overline{\text{RESET}}$ pin to logic 1.

5.5 Timing

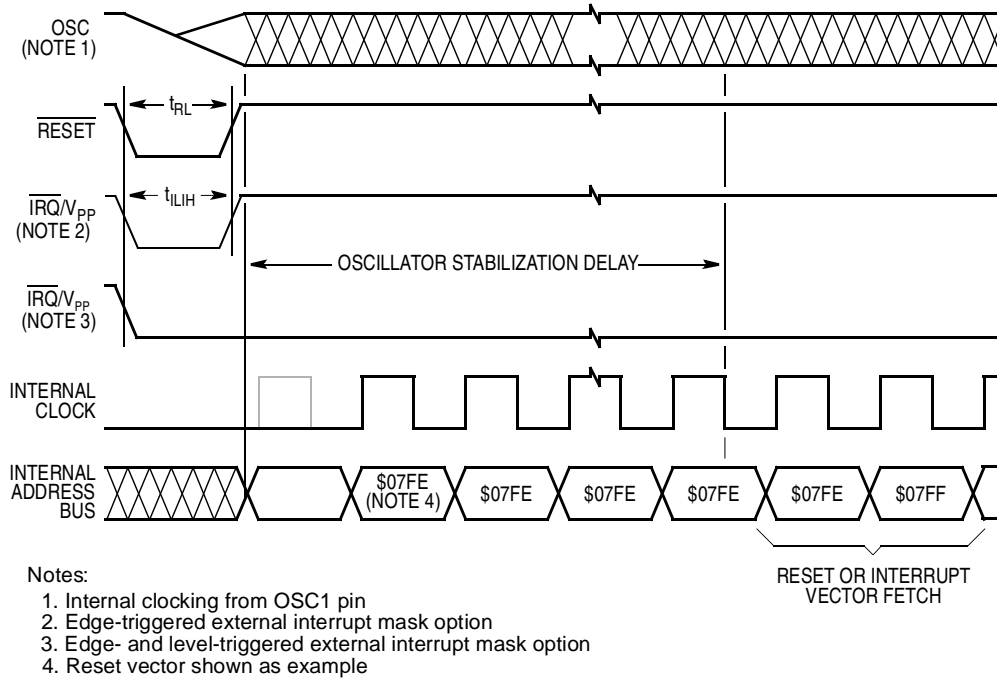


Figure 5-1. Stop Mode Recovery Timing

Section 6. Parallel Input/Output (I/O) Ports

6.1 Contents

| | | |
|-------|--|----|
| 6.2 | Introduction | 87 |
| 6.3 | Port A | 89 |
| 6.3.1 | Port A Data Register | 89 |
| 6.3.2 | Data Direction Register A | 90 |
| 6.3.3 | Pulldown Register A | 91 |
| 6.3.4 | Port A LED Drive Capability | 92 |
| 6.3.5 | Port A I/O Pin Interrupts | 92 |
| 6.4 | Port B | 92 |
| 6.4.1 | Port B Data Register | 92 |
| 6.4.2 | Data Direction Register B | 93 |
| 6.4.3 | Pulldown Register B | 94 |
| 6.5 | 5.0-Volt I/O Port Electrical Characteristics | 95 |
| 6.6 | 3.3-Volt I/O Port Electrical Characteristics | 95 |

6.2 Introduction

Fourteen bidirectional pins form one 8-bit input/output (I/O) port and one 6-bit I/O port. All the bidirectional port pins are programmable as inputs or outputs.

NOTE: *Connect any unused I/O pins to an appropriate logic level, either V_{DD} or V_{SS} . Although the I/O ports do not require termination for proper operation, termination reduces excess current consumption and the possibility of electrostatic damage.*

Parallel Input/Output (I/O) Ports

| Addr. | Register Name | Bit 7 | 6 | 5 | 4 | 3 | 2 | 1 | Bit 0 | |
|--------|--|--------|---------------------|-------|-------|-------|-------|-------|-------|-------|
| \$0000 | Port A Data Register (PORTA) See page 89. | Read: | PA7 | PA6 | PA5 | PA4 | PA3 | PA2 | PA1 | PA0 |
| | | Write: | | | | | | | | |
| | | Reset: | Unaffected by reset | | | | | | | |
| \$0001 | Port B Data Register (PORTB) See page 92. | Read: | 0 | 0 | PB5 | PB4 | PB3 | PB2 | PB1 | PB0 |
| | | Write: | | | | | | | | |
| | | Reset: | Unaffected by reset | | | | | | | |
| \$0004 | Data Direction Register A (DDRA) See page 90. | Read: | DDRA7 | DDRA6 | DDRA5 | DDRA4 | DDRA3 | DDRA2 | DDRA1 | DDRA0 |
| | | Write: | | | | | | | | |
| | | Reset: | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| \$0005 | Data Direction Register B (DDRB) See page 93. | Read: | 0 | 0 | DDRB5 | DDRB4 | DDRB3 | DDRB2 | DDRB1 | DDRB0 |
| | | Write: | | | | | | | | |
| | | Reset: | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| \$0010 | Pulldown Register A (PDRA) See page 91. | Read: | | | | | | | | |
| | | Write: | PDIA7 | PDIA6 | PDIA5 | PDIA4 | PDIA3 | PDIA2 | PDIA1 | PDIA0 |
| | | Reset: | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| \$0011 | Pulldown Register B (PDRB) See page 94. | Read: | | | | | | | | |
| | | Write: | | | PDIB5 | PDIB4 | PDIB3 | PDIB2 | PDIB1 | PDIB0 |
| | | Reset: | | | 0 | 0 | 0 | 0 | 0 | 0 |


 = Unimplemented

Figure 6-1. Parallel I/O Port Register Summary

6.3 Port A

Port A is an 8-bit bidirectional port.

6.3.1 Port A Data Register

The port A data register (PORTA) contains a latch for each port A pin.

Address: \$0000

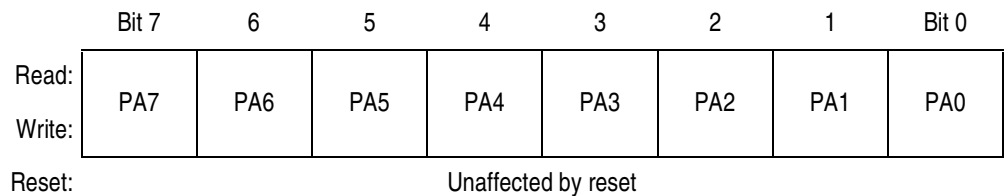


Figure 6-2. Port A Data Register (PORTA)

PA[7:0] — Port A Data Bits

These read/write bits are software programmable. Data direction of each port A pin is under the control of the corresponding bit in data direction register A. Reset has no effect on port A data.

Parallel Input/Output (I/O) Ports

6.3.2 Data Direction Register A

Data direction register A (DDRA) determines whether each port A pin is an input or an output.

Address: \$0004

| | Bit 7 | 6 | 5 | 4 | 3 | 2 | 1 | Bit 0 |
|--------|-------|-------|-------|-------|-------|-------|-------|-------|
| Read: | DDRA7 | DDRA6 | DDRA5 | DDRA4 | DDRA3 | DDRA2 | DDRA1 | DDRA0 |
| Write: | | | | | | | | |
| Reset: | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |

Figure 6-3. Data Direction Register A (DDRA)

DDRA[7:0] — Data Direction Register A Bits

These read/write bits control port A data direction. Reset clears DDRA[7:0], configuring all port A pins as inputs.

- 1 = Corresponding port A pin configured as output
- 0 = Corresponding port A pin configured as input

NOTE: Avoid glitches on port A pins by writing to the port A data register before changing data direction register A bits from 0 to 1.

Figure 6-4 shows the I/O logic of port A.

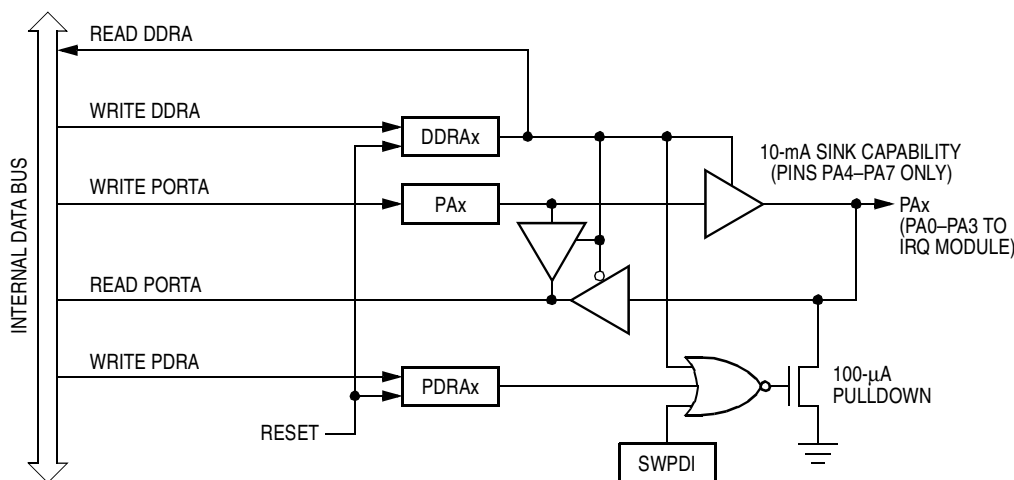


Figure 6-4. Port A I/O Circuitry

Writing a logic 1 to a DDRA bit enables the output buffer for the corresponding port A pin; a logic 0 disables the output buffer.

When bit DDRAx is a logic 1, reading address \$0000 reads the PAx data latch. When bit DDRAx is a logic 0, reading address \$0000 reads the voltage level on the pin. The data latch can always be written, regardless of the state of its data direction bit. **Table 6-1** summarizes the operation of the port A pins.

Table 6-1. Port A Pin Operation

| Data Direction Bit | I/O Pin Mode | Accesses to Data Bit | |
|--------------------|-----------------------|----------------------|----------------------|
| | | Read | Write |
| 0 | Input, high-impedance | Pin | Latch ⁽¹⁾ |
| 1 | Output | Latch | Latch |

1. Writing affects the data register but does not affect input.

6.3.3 Pulldown Register A

Pulldown register A (PDRA) inhibits the pulldown devices on port A pins programmed as inputs.

NOTE: *If the SWPDI bit in the mask option register is programmed to logic 1, reset initializes all port A pins as inputs with disabled pulldown devices.*

Address: \$0010

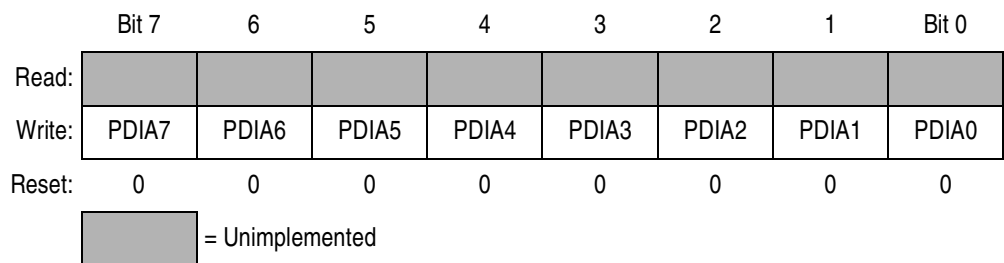


Figure 6-5. Pulldown Register A (PDRA)

PDIA[7:0] — Pulldown Inhibit A Bits

PDIA[7:0] disable the port A pulldown devices. Reset clears PDIA[7:0].

1 = Corresponding port A pulldown device disabled

0 = Corresponding port A pulldown device not disabled

Parallel Input/Output (I/O) Ports

6.3.4 Port A LED Drive Capability

The outputs for the upper four bits of port A (PA4–PA7) can drive light-emitting diodes (LEDs). PA4–PA7 can sink approximately 10 mA of current to V_{SS} .

6.3.5 Port A I/O Pin Interrupts

If the PIRQ bit in the mask option register is programmed to logic 1, PA0–PA3 pins function as external interrupt pins. See [Section 8. External Interrupt Module \(IRQ\)](#).

6.4 Port B

Port B is a 6-bit bidirectional port.

6.4.1 Port B Data Register

The port B data register (PORTB) contains a latch for each port B pin.

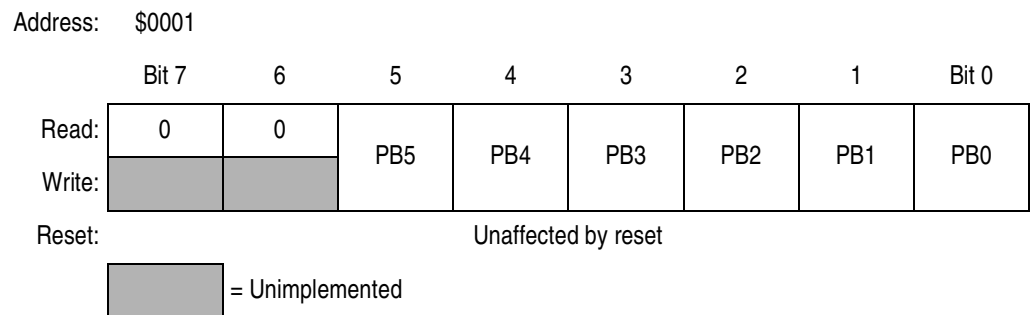


Figure 6-6. Port B Data Register (PORTB)

PB[5:0] — Port B Data Bits

These read/write bits are software programmable. Data direction of each port B pin is under the control of the corresponding bit in data direction register B. Reset has no effect on port B data.

6.4.2 Data Direction Register B

Data direction register B (DDRB) determines whether each port B pin is an input or an output.

Address: \$0005

| | Bit 7 | 6 | 5 | 4 | 3 | 2 | 1 | Bit 0 |
|--------|-------|---|-------|-------|-------|-------|-------|-------|
| Read: | 0 | 0 | DDRB5 | DDRB4 | DDRB3 | DDRB2 | DDRB1 | DDRB0 |
| Write: | | | | | | | | |
| Reset: | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |

= Unimplemented

Figure 6-7. Data Direction Register B (DDRB)

DDRB[5:0] — Data Direction Register B Bits

These read/write bits control port B data direction. Reset clears DDRB[5:0], configuring all port B pins as inputs.

- 1 = Corresponding port B pin configured as output
- 0 = Corresponding port B pin configured as input

NOTE: Avoid glitches on port B pins by writing to the port B data register before changing data direction register B bits from 0 to 1.

Figure 6-8 shows the I/O logic of port B.

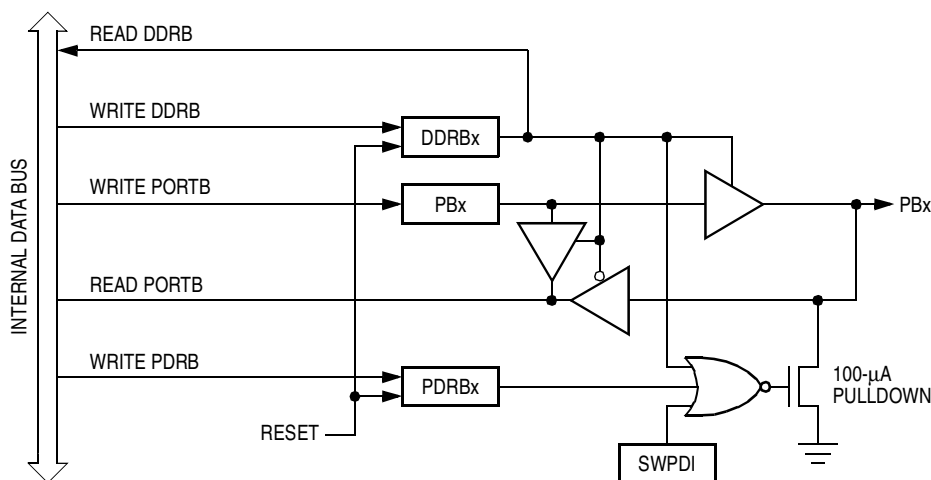


Figure 6-8. Port B I/O Circuitry

Writing a logic 1 to a DDRB bit enables the output buffer for the corresponding port B pin; a logic 0 disables the output buffer.

When bit DDRBx is a logic 1, reading address \$0001 reads the PBx data latch. When bit DDRBx is a logic 0, reading address \$0001 reads the voltage level on the pin. The data latch can always be written, regardless of the state of its data direction bit. **Table 6-2** summarizes the operation of the port B pins.

Table 6-2. Port B Pin Operation

| Data Direction Bit | I/O Pin Mode | Accesses to Data Bit | |
|--------------------|-----------------------|----------------------|----------------------|
| | | Read | Write |
| 0 | Input, high-impedance | Pin | Latch ⁽¹⁾ |
| 1 | Output | Latch | Latch |

1. Writing affects the data register, but does not affect input.

6.4.3 Pulldown Register B

Pulldown register B (PDRB) inhibits the pulldown devices on port B pins programmed as inputs.

NOTE: *If the SWPDI bit in the mask option register is programmed to logic 1, reset initializes all port B pins as inputs with disabled pulldown devices.*

Address: \$0011

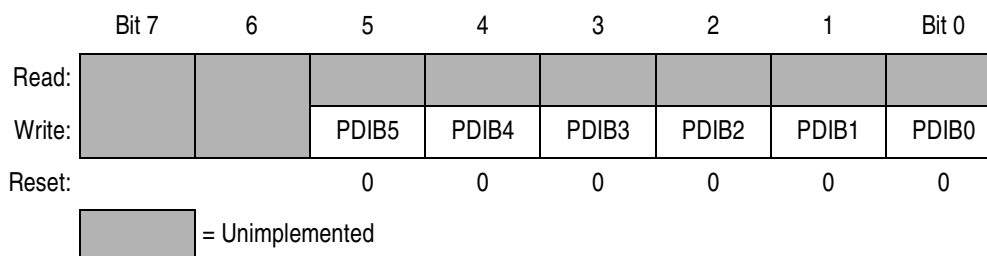


Figure 6-9. Pulldown Register B (PDRB)

PDIB[7:0] — Pulldown Inhibit B Bits

PDIB[7:0] disable the port B pulldown devices. Reset clears PDIB[7:0].

1 = Corresponding port B pulldown device disabled

0 = Corresponding port B pulldown device not disabled

6.5 5.0-Volt I/O Port Electrical Characteristics

| Characteristic ⁽¹⁾ | Symbol | Min | Typ ⁽²⁾ | Max | Unit |
|--|-----------------|-----------------------|--------------------|-----------------------|------|
| Current drain per pin excluding PA4–PA7 | I | — | 25 | — | mA |
| Output high voltage (I _{Load} = –0.8 mA) PA0–PA7, PB0–PB5 | V _{OH} | V _{DD} – 0.8 | — | — | V |
| Output low voltage (I _{Load} = 1.6 mA) PA0–PA3, PB0–PB5 (I _{Load} = 10.0 mA) PA4–PA7 | V _{OL} | — — | — — | 0.4 0.4 | V |
| Input high voltage PA0–PA7, PB0–PB5 | V _{IH} | 0.7 x V _{DD} | — | V _{DD} | V |
| Input low voltage PA0–PA7, PB0–PB5 | V _{IL} | V _{SS} | — | 0.2 x V _{DD} | V |
| I/O ports hi-z leakage current PA0–PA7, PB0–PB5 (without individual pulldown activated) | I _{IL} | — | 0.2 | ±1 | μA |
| Input pulldown current PA0–PA7, PB0–PB5 (with individual pulldown activated) | I _{IL} | 35 | 80 | 200 | μA |

- V_{DD} = 5.0 Vdc ± 10%, V_{SS} = 0 Vdc, T_A = –40°C to +105°C, unless otherwise noted
- Typical values reflect average measurements at midpoint of voltage range, 25°C.

6.6 3.3-Volt I/O Port Electrical Characteristics

| Characteristic ⁽¹⁾ | Symbol | Min | Typ ⁽²⁾ | Max | Unit |
|---|-----------------|-----------------------|--------------------|-----------------------|------|
| Current drain per pin excluding PA4–PA7 | I | — | 25 | — | mA |
| Output high voltage (I _{Load} = –0.2 mA) PA0–PA7, PB0–PB5 | V _{OH} | V _{DD} – 0.3 | — | — | V |
| Output low voltage (I _{Load} = 0.4 mA) PA0–PA3, PB0–PB5 (I _{Load} = 5.0 mA) PA4–PA7 | V _{OL} | — — | — — | 0.3 0.3 | V |
| Input high voltage PA0–PA7, PB0–PB5 | V _{IH} | 0.7 x V _{DD} | — | V _{DD} | V |
| Input low voltage PA0–PA7, PB0–PB5 | V _{IL} | V _{SS} | — | 0.2 x V _{DD} | V |
| I/O ports hi-z leakage current PA0–PA7, PB0–PB5 (without individual pulldown activated) | I _{IL} | — | 0.1 | ±1 | μA |
| Input pulldown current PA0–PA7, PB0–PB5 (with individual pulldown activated) | I _{IL} | 12 | 30 | 100 | μA |

- V_{DD} = 3.3 Vdc ± 10%, V_{SS} = 0 Vdc, T_A = –40°C to +105°C, unless otherwise noted
- Typical values reflect average measurements at midpoint of voltage range, 25°C.

Section 7. Computer Operating Properly (COP) Module

7.1 Contents

| | | |
|-------|-----------------------------------|-----|
| 7.2 | Introduction | 97 |
| 7.3 | Operation | 98 |
| 7.3.1 | COP Watchdog Timeout | 98 |
| 7.3.2 | COP Watchdog Timeout Period | 98 |
| 7.3.3 | Clearing the COP Watchdog | 98 |
| 7.4 | Interrupts | 99 |
| 7.5 | COP Register | 99 |
| 7.6 | Low-Power Modes | 100 |
| 7.6.1 | Stop Mode | 100 |
| 7.6.2 | Wait Mode | 100 |

7.2 Introduction

The computer operating properly (COP) watchdog resets the microcontroller (MCU) in case of software failure. Software that is operating properly periodically services the COP watchdog and prevents COP reset. The COP watchdog function is programmable by the COPEN bit in the mask option register.

Features include:

- Protection from runaway software
- Wait and halt mode operation

7.3 Operation

Operation of the COP is described in this subsection.

7.3.1 COP Watchdog Timeout

Four counter stages at the end of the timer make up the COP watchdog. The COP resets the MCU if the timeout period occurs before the COP watchdog timer is cleared by application software and the $\overline{\text{IRQ}}/V_{\text{PP}}$ pin voltage is between V_{SS} and V_{DD} . Periodically clearing the counter starts a new timeout period and prevents COP reset. A COP watchdog timeout indicates that the software is not executing instructions in the correct sequence.

NOTE: *The internal clock drives the COP watchdog. Therefore, the COP watchdog cannot generate a reset for errors that cause the internal clock to stop.*

The COP watchdog depends on a power supply voltage at or above a minimum specification and is not guaranteed to protect against brownout.

7.3.2 COP Watchdog Timeout Period

The COP watchdog timer function is implemented by dividing the output of the real-time interrupt circuit (RTI) by eight. The RTI select bits in the timer status and control register control RTI output, and the selected output drives the COP watchdog. See timer status and control register in [Section 9. Multifunction Timer Module](#).

NOTE: *The minimum COP timeout period is seven times the RTI period. The COP is cleared asynchronously with the value in the RTI divider; hence, the COP timeout period will vary between 7x and 8x the RTI period.*

7.3.3 Clearing the COP Watchdog

To clear the COP watchdog and prevent a COP reset, write a logic 0 to bit 0 (COPC) of the COP register at location \$07F0 (see [Figure 7-1](#)).

Clearing the COP bit disables the COP watchdog timer regardless of the $\overline{\text{IRQ}}/V_{\text{PP}}$ pin voltage.

If the main program executes within the COP timeout period, the clearing routine should be executed only once. If the main program takes longer than the COP timeout period, the clearing routine must be executed more than once.

NOTE: *Place the clearing routine in the main program and not in an interrupt routine. Clearing the COP watchdog in an interrupt routine might prevent COP watchdog timeouts even though the main program is not operating properly.*

7.4 Interrupts

The COP watchdog does not generate interrupts.

7.5 COP Register

The COP register (COPR) is a write-only register that returns the contents of EPROM location \$07F0 when read.

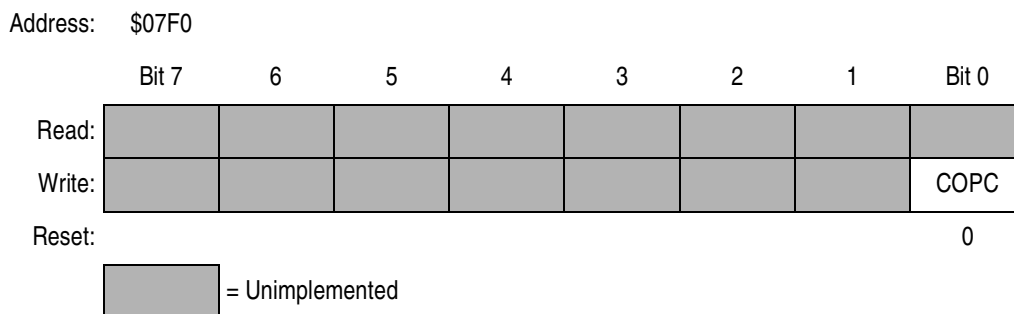


Figure 7-1. COP Register (COPR)

COPC — COP Clear Bit

This write-only bit resets the COP watchdog. Reading address \$07F0 returns undefined results.

7.6 Low-Power Modes

The STOP and WAIT instructions have these effects on the COP watchdog.

7.6.1 Stop Mode

The STOP instruction clears the COP watchdog counter and disables the clock to the COP watchdog.

NOTE: *To prevent the STOP instruction from disabling the COP watchdog, program the stop-to-wait conversion bit (SWAIT) in the mask option register to logic 1.*

Upon exit from stop mode by external reset:

- The counter begins counting from \$0000.
- The counter is cleared again after the oscillator stabilization delay and begins counting from \$0000 again.

Upon exit from stop mode by external interrupt:

- The counter begins counting from \$0000.
- The counter is not cleared again after the oscillator stabilization delay and continues counting throughout the oscillator stabilization delay.

NOTE: *Immediately after exiting stop mode by external interrupt, service the COP to ensure a full COP timeout period.*

7.6.2 Wait Mode

The WAIT instruction has no effect on the COP watchdog.

NOTE: *To prevent a COP timeout during wait mode, exit wait mode periodically to service the COP.*

Section 8. External Interrupt Module (IRQ)

8.1 Contents

| | | |
|-------|--|-----|
| 8.2 | Introduction | 101 |
| 8.3 | Operation | 102 |
| 8.3.1 | $\overline{\text{IRQ}}/V_{PP}$ Pin | 104 |
| 8.3.2 | Optional External Interrupts | 104 |
| 8.4 | IRQ Status and Control Register | 106 |
| 8.5 | External Interrupt Timing | 107 |
| 8.5.1 | 5.0-Volt External Interrupt Timing Characteristics | 107 |
| 8.5.2 | 3.3-Volt External Interrupt Timing Characteristics | 107 |

8.2 Introduction

The external interrupt (IRQ) module provides asynchronous external interrupts to the CPU. These sources can generate external interrupts:

- $\overline{\text{IRQ}}/V_{PP}$ pin
- PA0–PA3 pins

Features include:

- Dedicated external interrupt pin ($\overline{\text{IRQ}}/V_{PP}$)
- Selectable interrupt on four input/output (I/O) pins (PA0–PA3)
- Programmable edge-only or edge- and level-interrupt sensitivity

External Interrupt Module (IRQ)

8.3 Operation

The interrupt request/programming voltage pin (\overline{IRQ}/V_{PP}) and port A pins 0–3 (PA0–PA3) provide external interrupts. The PIRQ bit in the mask option register (MOR) enables PA0–PA3 as IRQ interrupt sources, which are combined into a single ORing function to be latched by the IRQ latch. **Figure 8-1** shows the structure of the IRQ module.

After completing its current instruction, the CPU tests the IRQ latch. If the IRQ latch is set, the CPU then tests the I bit in the condition code register and the IRQE bit in the IRQ status and control register. If the I bit is clear and the IRQE bit is set, the CPU then begins the interrupt sequence. This interrupt is serviced by the interrupt service routine located at \$07FA and \$07FB.

The CPU clears the IRQ latch while it fetches the interrupt vector, so that another external interrupt request can be latched during the interrupt service routine. As soon as the I bit is cleared during the return from interrupt, the CPU can recognize the new interrupt request. **Figure 8-2** shows the sequence of events caused by an interrupt.

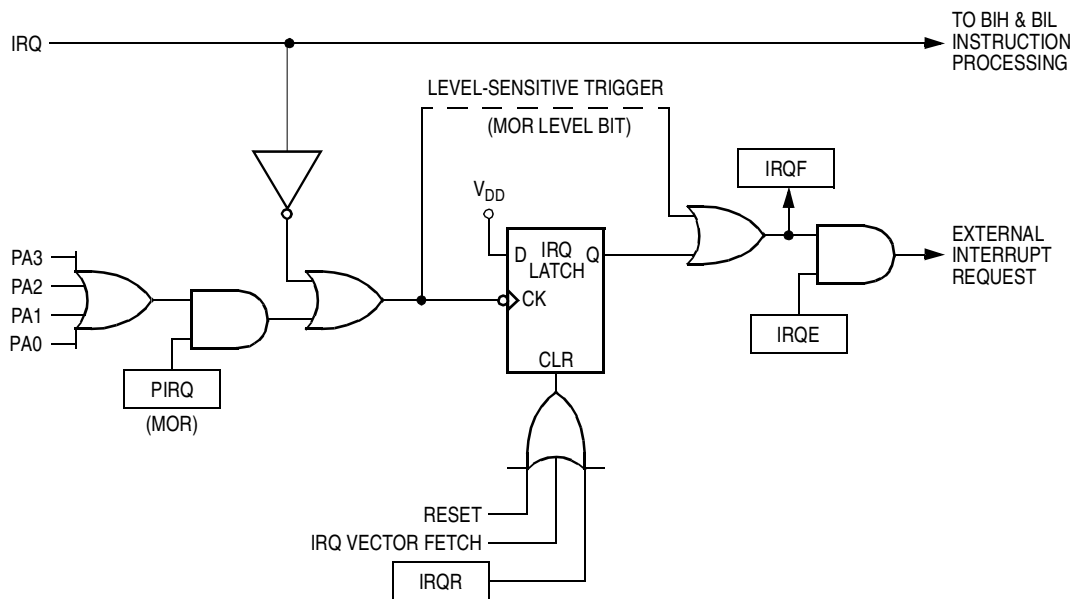


Figure 8-1. IRQ Module Block Diagram

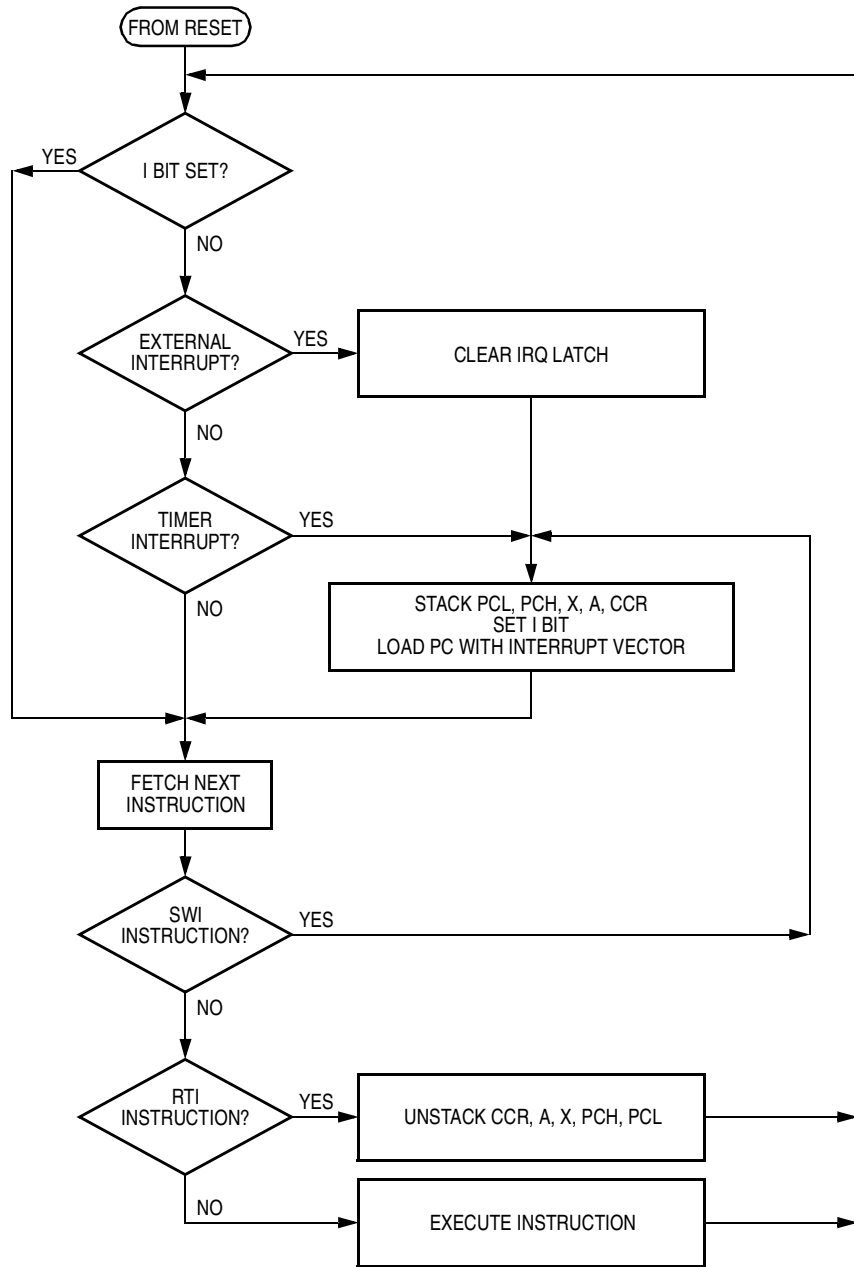


Figure 8-2. Interrupt Flowchart

External Interrupt Module (IRQ)

8.3.1 $\overline{\text{IRQ}}/V_{\text{PP}}$ Pin

An interrupt signal on the $\overline{\text{IRQ}}/V_{\text{PP}}$ pin latches an external interrupt request. The LEVEL bit in the mask option register provides negative edge-sensitive triggering or both negative edge-sensitive and low level-sensitive triggering for the interrupt function.

If edge- and level-sensitive triggering is selected, a falling edge or a low level on the $\overline{\text{IRQ}}/V_{\text{PP}}$ pin latches an external interrupt request. Edge- and level-sensitive triggering allows the use of multiple wired-OR external interrupt sources. An external interrupt request is latched as long as any source is holding the $\overline{\text{IRQ}}/V_{\text{PP}}$ pin low.

If level-sensitive triggering is selected, the $\overline{\text{IRQ}}/V_{\text{PP}}$ input requires an external resistor to V_{DD} for wired-OR operation. If the $\overline{\text{IRQ}}/V_{\text{PP}}$ pin is not used, it must be tied to the V_{DD} supply.

If edge-sensitive-only triggering is selected, a falling edge on the $\overline{\text{IRQ}}/V_{\text{PP}}$ pin latches an external interrupt request. A subsequent external interrupt request can be latched only after the voltage level on the $\overline{\text{IRQ}}/V_{\text{PP}}$ pin returns to logic 1 and then falls again to logic 0.

The $\overline{\text{IRQ}}/V_{\text{PP}}$ pin contains an internal Schmitt trigger as part of its input to improve noise immunity. The voltage on this pin can affect the mode of operation and should not exceed V_{DD} .

8.3.2 Optional External Interrupts

The inputs for the lower four bits of port A (PA0–PA3) can be connected to the IRQ pin input of the CPU if enabled by the PIRQ bit in the mask option register. This capability allows keyboard scan applications where the transitions or levels on the I/O pins will behave the same as the $\overline{\text{IRQ}}/V_{\text{PP}}$ pin except for the inverted phase (logic 1, rising edge). The active state of the $\overline{\text{IRQ}}/V_{\text{PP}}$ pin is a logic 0 (falling edge).

The PA0–PA3 pins are selected as a group to function as IRQ interrupts and are enabled by the IRQE bit in the IRQ status and control register. The PA0–PA3 pins can be positive-edge triggered only or positive-edge and high-level triggered.

If edge- and level-sensitive triggering is selected, a rising edge or a high level on a PA0–PA3 pin latches an external interrupt request. Edge- and level-sensitive triggering allows the use of multiple wired-OR external interrupt sources. As long as any source is holding a PA0–PA3 pin high, an external interrupt request is latched, and the CPU continues to execute the interrupt service routine.

If edge-sensitive only triggering is selected, a rising edge on a PA0–PA3 pin latches an external interrupt request. A subsequent external interrupt request can be latched only after the voltage level of the previous interrupt signal returns to logic 0 and then rises again to logic 1.

NOTE: *The branch if interrupt pin is high (BIH) and branch if interrupt pin is low (BIL) instructions apply only to the level on the \overline{IRQ}/V_{PP} pin itself and not to the output of the logic OR function with the PA0–PA3 pins. The state of the individual port A pins can be checked by reading the appropriate port A pins as inputs.*

Enabled PA0–PA3 pins cause an IRQ interrupt regardless of whether these pins are configured as inputs or outputs.

The \overline{IRQ} pin has an internal Schmitt trigger. The optional external interrupts (PA0–PA3) do not have internal Schmitt triggers.

The interrupt mask bit (I) in the condition code register (CCR) disables all maskable interrupt requests, including external interrupt requests.

8.4 IRQ Status and Control Register

The IRQ status and control register (ISCR) controls and monitors operation of the IRQ module. All unused bits in the ISCR read as logic 0s. The IRQF bit is cleared and the IRQE bit is set by reset.

Address: \$000A

| | Bit 7 | 6 | 5 | 4 | 3 | 2 | 1 | Bit 0 |
|--------|-------|---|---|---|------|---|------|-------|
| Read: | IRQE | 0 | 0 | 0 | IRQF | 0 | 0 | 0 |
| Write: | | | | R | | | IRQR | |
| Reset: | 1 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |

= Unimplemented
 R = Reserved

Figure 8-3. IRQ Status and Control Register (ISCR)

IRQR — Interrupt Request Reset Bit

This write-only bit clears the external interrupt request flag.

- 1 = Clears external interrupt and IRQF bit
- 0 = No effect on external interrupt and IRQF bit

IRQF — External Interrupt Request Flag

The external interrupt request flag is a clearable, read-only bit that is set when an external interrupt request is pending. Reset clears the IRQF bit.

- 1 = External interrupt request pending
- 0 = No external interrupt request pending

IRQE — External Interrupt Request Enable Bit

This read/write bit enables external interrupts. Reset sets the IRQE bit.

- 1 = External interrupt requests enabled
- 0 = External interrupt requests disabled

The STOP and WAIT instructions set the IRQE bit so that an external interrupt can bring the MCU out of these low-power modes. In addition, reset sets the I bit which masks all interrupt sources.

8.5 External Interrupt Timing

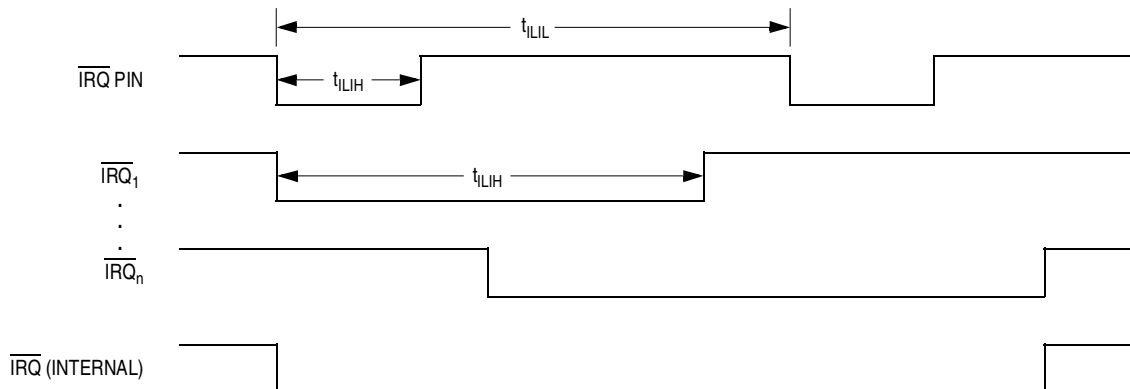


Figure 8-4. External Interrupt Timing

8.5.1 5.0-Volt External Interrupt Timing Characteristics

| Characteristic ⁽¹⁾ | Symbol | Min | Max | Unit |
|--|-----------|-----|---------------------|--------------------------|
| IRQ interrupt pulse width low (edge-triggered) | t_{LIL} | 1.5 | — | t_{cyc} ⁽²⁾ |
| IRQ interrupt pulse width (edge- and level-triggered) | t_{LIH} | 1.5 | Note ⁽³⁾ | t_{cyc} |
| PA0–PA3 interrupt pulse width high (edge-triggered) | t_{LIL} | 1.5 | — | t_{cyc} |
| PA0–PA3 interrupt pulse width high (edge- and level-triggered) | t_{LIH} | 1.5 | Note ⁽³⁾ | t_{cyc} |

1. $V_{DD} = 5.0 \text{ Vdc} \pm 10\%$, $V_{SS} = 0 \text{ Vdc}$, $T_A = -40^\circ\text{C}$ to $+105^\circ\text{C}$, unless otherwise noted

2. $t_{cyc} = 1/f_{op}$; $f_{op} = f_{osc}/2$.

3. The minimum, t_{LIL} , should not be less than the number of interrupt service routine cycles plus $19 t_{cyc}$.

8.5.2 3.3-Volt External Interrupt Timing Characteristics

| Characteristic ⁽¹⁾ | Symbol | Min | Max | Unit |
|--|-----------|-----|---------------------|--------------------------|
| IRQ interrupt pulse width low (edge-triggered) | t_{LIL} | 1.5 | — | t_{cyc} ⁽²⁾ |
| IRQ interrupt pulse width (edge- and level-triggered) | t_{LIH} | 1.5 | Note ⁽³⁾ | t_{cyc} |
| PA0–PA3 interrupt pulse width high (edge-triggered) | t_{LIL} | 1.5 | — | t_{cyc} |
| PA0–PA3 interrupt pulse width high (edge- and level-triggered) | t_{LIH} | 1.5 | Note ⁽³⁾ | t_{cyc} |

1. $V_{DD} = 3.3 \text{ Vdc} \pm 10\%$, $V_{SS} = 0 \text{ Vdc}$, $T_A = -40^\circ\text{C}$ to $+105^\circ\text{C}$, unless otherwise noted

2. $t_{cyc} = 1/f_{op}$; $f_{op} = f_{osc}/2$.

3. The minimum, t_{LIL} , should not be less than the number of interrupt service routine cycles plus $19 t_{cyc}$.

Section 9. Multifunction Timer Module

9.1 Contents

| | | |
|-------|---|-----|
| 9.2 | Introduction | 109 |
| 9.3 | Operation | 111 |
| 9.4 | Interrupts | 112 |
| 9.5 | I/O Registers | 112 |
| 9.5.1 | Timer Status and Control Register | 112 |
| 9.5.2 | Timer Counter Register | 114 |
| 9.6 | Low-Power Modes | 115 |
| 9.6.1 | Stop Mode | 115 |
| 9.6.2 | Wait Mode | 115 |

9.2 Introduction

The multifunction timer provides a timing reference with programmable real-time interrupt (RTI) capability. **Figure 9-1** shows the timer organization.

Features include:

- Timer overflow
- Four selectable interrupt rates
- Computer operating properly (COP) watchdog timer

Multifunction Timer Module

Freescale Semiconductor, Inc.

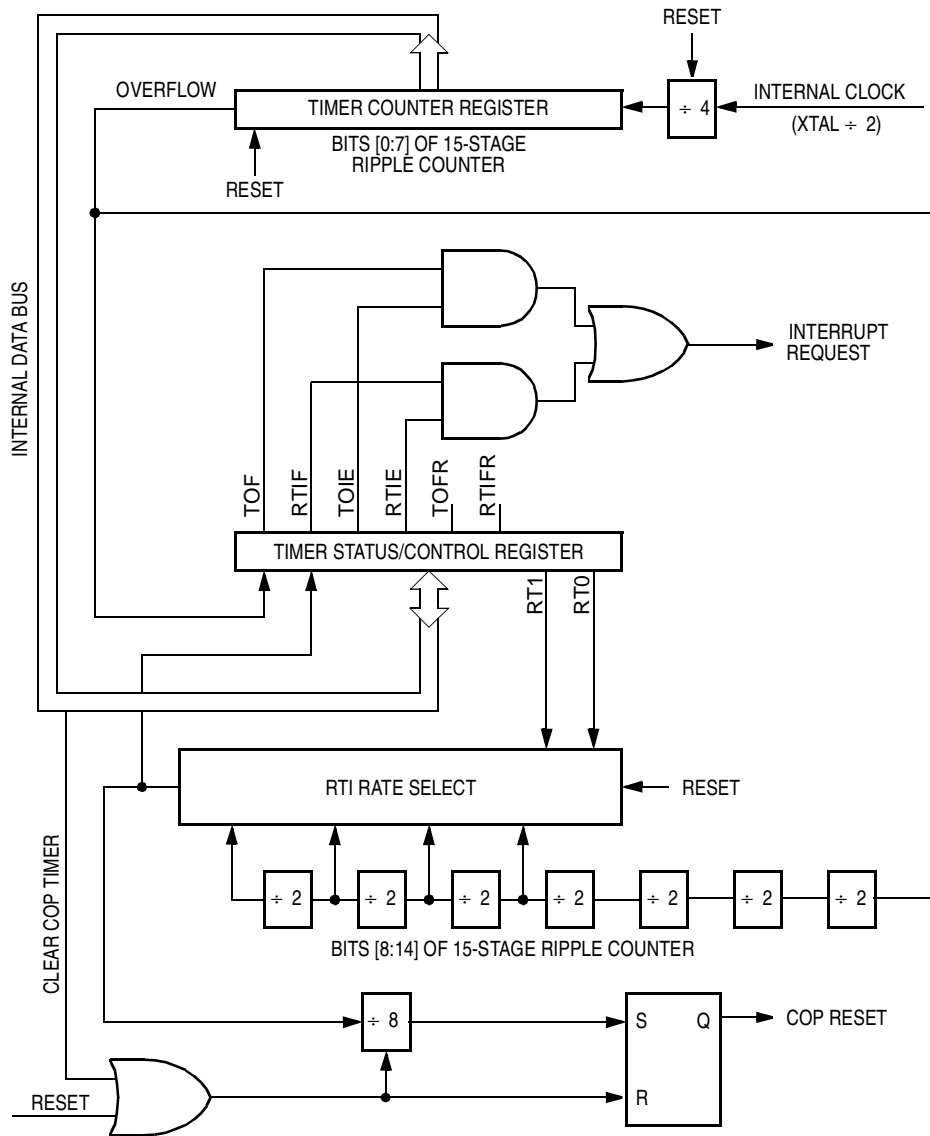


Figure 9-1. Multifunction Timer Block Diagram

| Addr. | Register Name | Bit 7 | 6 | 5 | 4 | 3 | 2 | 1 | Bit 0 | |
|--------|---|--------|------|------|------|------|------|-------|-------|------|
| \$0008 | Timer Status and Control Register (TSCR) See page 112. | Read: | TOF | RTIF | TOIE | RTIE | 0 | 0 | RT1 | RT0 |
| | | Write: | | | | | TOFR | RTIFR | | |
| | | Reset: | 0 | 0 | 0 | 0 | 0 | 0 | 1 | 1 |
| \$0009 | Timer Counter Register (TCR) See page 114. | Read: | TMR7 | TMR6 | TMR5 | TMR4 | TMR3 | TMR2 | TMR1 | TMR0 |
| | | Write: | | | | | | | | |
| | | Reset: | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |


 = Unimplemented

Figure 9-2. I/O Register Summary

9.3 Operation

A 15-stage ripple counter, preceded by a prescaler that divides the internal clock signal by four, provides the timing reference for the timer functions. The value of the first eight timer stages can be read at any time by accessing the timer counter register at address \$0009. A timer overflow function at the eighth stage allows a timer interrupt every 1024 internal clock cycles.

The next four stages lead to the real-time interrupt (RTI) circuit. The RT1 and RT0 bits in the timer status and control register at address \$0008 allow a timer interrupt every 16,384, 32,768, 65,536, or 131,072 clock cycles. The last four stages drive the selectable COP system. For information on the COP, refer to the [Section 7. Computer Operating Properly \(COP\) Module](#).

9.4 Interrupts

These timer sources can generate interrupts:

- Timer overflow flag (TOF) — The TOF bit is set when the first eight stages of the counter roll over from \$FF to \$00. The timer overflow interrupt enable bit, TOIE, enables TOF interrupt requests.
- Real-time interrupt flag (RTIF) — The RTIF bit is set when the selected RTI output becomes active. The real-time interrupt enable bit, RTIE, enables RTIF interrupt requests.

9.5 I/O Registers

These registers control and monitor the timer operation:

- Timer status and control register (TSCR)
- Timer counter register (TCR)

9.5.1 Timer Status and Control Register

The read/write timer status and control register (TSCR) performs these functions:

- Flags timer interrupts
- Enables timer interrupts
- Resets timer interrupt flags
- Selects real-time interrupt rates

Address: \$0008

| | Bit 7 | 6 | 5 | 4 | 3 | 2 | 1 | Bit 0 |
|--------|-------|------|------|------|------|-------|-----|-------|
| Read: | TOF | RTIF | TOIE | RTIE | 0 | 0 | RT1 | RT0 |
| Write: | | | | | TOFR | RTIFR | | |
| Reset: | 0 | 0 | 0 | 0 | 0 | 0 | 1 | 1 |


 = Unimplemented

Figure 9-3. Timer Status and Control Register (TSCR)

TOF — Timer Overflow Flag

This read-only flag becomes set when the first eight stages of the counter roll over from \$FF to \$00. TOF generates a timer overflow interrupt request if TOIE is also set. Clear TOF by writing a logic 1 to the TOFR bit. Writing to TOF has no effect. Reset clears TOF.

RTIF — Real-Time Interrupt Flag

This read-only flag becomes set when the selected RTI output becomes active. RTIF generates a real-time interrupt request if RTIE is also set. Clear RTIF by writing a logic 1 to the RTIFR bit. Writing to RTIF has no effect. Reset clears RTIF.

TOIE — Timer Overflow Interrupt Enable Bit

This read/write bit enables timer overflow interrupts. Reset clears TOIE.

- 1 = Timer overflow interrupts enabled
- 0 = Timer overflow interrupts disabled

RTIE — Real-Time Interrupt Enable Bit

This read/write bit enables real-time interrupts. Reset clears RTIE.

- 1 = Real-time interrupts enabled
- 0 = Real-time interrupts disabled

TOFR — Timer Overflow Flag Reset Bit

Writing a logic 1 to this write-only bit clears the TOF bit. TOFR always reads as logic 0. Reset clears TOFR.

RTIFR — Real-Time Interrupt Flag Reset Bit

Writing a logic 1 to this write-only bit clears the RTIF bit. RTIFR always reads as logic 0. Reset clears RTIFR.

RT1 and RT0 — Real-Time Interrupt Select Bits

These read/write bits select one of four real-time interrupt rates, as shown in [Table 9-1](#). Because the selected RTI output drives the COP watchdog, changing the real-time interrupt rate also changes the counting rate of the COP watchdog. Reset sets RT1 and RT0.

NOTE: *Changing RT1 and RT0 when a COP timeout is imminent can cause a real-time interrupt request to be missed or an additional real-time*

interrupt request to be generated. To prevent this occurrence, clear the COP timer before changing RT1 and RT0.

Table 9-1. Real-Time Interrupt Rate Selection

| RT1:RT0 | Number of Cycles to RTI | RTI Period ⁽¹⁾ | Number of Cycles to COP Reset | COP Timeout Period ⁽¹⁾ |
|---------|-------------------------|---------------------------|-------------------------------|-----------------------------------|
| 0 0 | $2^{14} = 16,384$ | 8.2 ms | $2^{17} = 131,072$ | 65.5 ms |
| 0 1 | $2^{15} = 32,768$ | 16.4 ms | $2^{18} = 262,144$ | 131.1 ms |
| 1 0 | $2^{16} = 65,536$ | 32.8 ms | $2^{19} = 524,288$ | 262.1 ms |
| 1 1 | $2^{17} = 131,072$ | 65.5 ms | $2^{20} = 1,048,576$ | 524.3 ms |

1. At 2-MHz bus, 4-MHz XTAL, 0.5 μ s per cycle

9.5.2 Timer Counter Register

A 15-stage ripple counter is the core of the timer. The value of the first eight stages is readable at any time from the read-only timer counter register (TCR) shown in Figure 9-4.

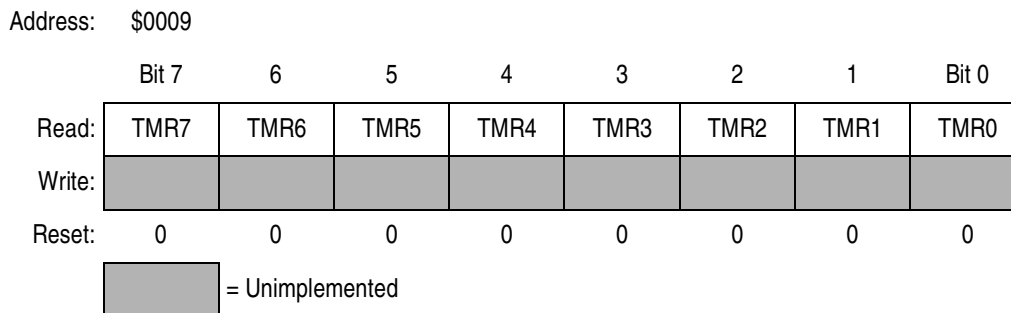


Figure 9-4. Timer Counter Register (TCR)

Power-on clears the entire counter chain and the internal clock begins clocking the counter. After 4064 cycles (or 16 cycles if the SOSCD bit in the mask option register is set), the power-on reset circuit is released, clearing the counter again and allowing the MCU to come out of reset.

A timer overflow function at the eighth counter stage allows a timer interrupt every 1024 internal clock cycles.

9.6 Low-Power Modes

The STOP and WAIT instructions put the MCU in low power-consumption standby states.

9.6.1 Stop Mode

The STOP instruction has these effects on the timer:

- Clears the timer counter
- Clears interrupt flags (TOF and RTIF) and interrupt enable bits (TOFE and RTIE) in TSCR, removing any pending timer interrupt requests and disabling further timer interrupts.

9.6.2 Wait Mode

The timer remains active after a WAIT instruction. Any enabled timer interrupt request can bring the MCU out of wait mode.

Section 10. Electrical Specifications

10.1 Contents

| | | |
|-------|--|-----|
| 10.2 | Introduction | 117 |
| 10.3 | Maximum Ratings | 118 |
| 10.4 | Operating Temperature Range | 119 |
| 10.5 | Thermal Characteristics | 119 |
| 10.6 | Power Considerations | 120 |
| 10.7 | 5.0-Volt DC Electrical Characteristics | 121 |
| 10.8 | 3.3-Volt DC Electrical Characteristics | 122 |
| 10.9 | Driver Characteristics | 123 |
| 10.10 | Typical Supply Currents | 125 |
| 10.11 | EPROM Programming Characteristics | 126 |
| 10.12 | 5.0-Volt Control Timing | 126 |
| 10.13 | 3.3-Volt Control Timing | 127 |

10.2 Introduction

This section contains electrical and timing specifications.

10.3 Maximum Ratings

Maximum ratings are the extreme limits to which the MCU can be exposed without permanently damaging it.

The MCU contains circuitry to protect the inputs against damage from high static voltages; however, do not apply voltages higher than those shown in the table here. Keep V_{In} and V_{Out} within the range $V_{SS} \leq (V_{In} \text{ or } V_{Out}) \leq V_{DD}$. Connect unused inputs to the appropriate voltage level, either V_{SS} or V_{DD} .

| Rating ⁽¹⁾ | Symbol | Value | Unit |
|---|-----------|--|------|
| Supply voltage | V_{DD} | -0.3 to +7.0 | V |
| Current drain per pin (excluding V_{DD} , V_{SS} , and PA4-PA7) | I | 25 | mA |
| Input voltage | V_{In} | $V_{SS} - 0.3$ to $V_{DD} + 0.3$ | V |
| \overline{IRQ}/V_{PP} pin | V_{PP} | $V_{SS} - 0.3$ to $2 \times V_{DD} + 0.3$ | V |
| Storage temperature range | T_{STG} | -65 to +150 | °C |

1. Voltages are referenced to V_{SS} .

NOTE: *This device is not guaranteed to operate properly at the maximum ratings. Refer to [10.7 5.0-Volt DC Electrical Characteristics](#) and [10.8 3.3-Volt DC Electrical Characteristics](#) for guaranteed operating conditions.*

10.4 Operating Temperature Range

| Package Type | Symbol | Value (T _L to T _H) | Unit |
|---|----------------|---|------|
| MC68HC705J1AP ⁽¹⁾ , DW ⁽²⁾ , S ⁽³⁾ | T _A | 0 to 70 | °C |
| MC68HC705J1AC ⁽⁴⁾ P, CDW, CS | T _A | -40 to +85 | °C |
| MC68HC705J1AV ⁽⁵⁾ P, VDW, VS | T _A | -40 to +105 | °C |

1. P = plastic dual in-line package (PDIP)
2. DW = small outline integrated circuit (SOIC)
3. S = ceramic DIP (cerdip)
4. C = extended temperature range
5. V = automotive temperature range

10.5 Thermal Characteristics

| Characteristic | Symbol | Value | Unit |
|---|-----------------|-------|------|
| Thermal resistance MC68HC705J1AP ⁽¹⁾ MC68HC705J1ADW ⁽²⁾ MC68HC705J1AS ⁽³⁾ | θ _{JA} | 60 | °C/W |

1. P = plastic dual in-line package (PDIP)
2. DW = small outline integrated circuit (SOIC)
3. S = ceramic DIP (cerdip)

10.6 Power Considerations

The average chip junction temperature, T_J , in °C can be obtained from:

$$T_J = T_A + (P_D \times \theta_{JA}) \quad (1)$$

Where:

T_A = ambient temperature in °C

θ_{JA} = package thermal resistance, junction to ambient in °C/W

$P_D = P_{INT} + P_{I/O}$

$P_{INT} = I_{CC} \times V_{CC}$ = chip internal power dissipation

$P_{I/O}$ = power dissipation on input and output pins (user-determined)

For most applications, $P_{I/O} < P_{INT}$ and can be neglected.

Ignoring $P_{I/O}$, the relationship between P_D and T_J is approximately:

$$P_D = \frac{K}{T_J + 273^\circ\text{C}} \quad (2)$$

Solving equations (1) and (2) for K gives:

$$= P_D \times (T_A + 273^\circ\text{C}) + \theta_{JA} \times (P_D)^2 \quad (3)$$

where K is a constant pertaining to the particular part. K can be determined from equation (3) by measuring P_D (at equilibrium) for a known T_A . Using this value of K, the values of P_D and T_J can be obtained by solving equations (1) and (2) iteratively for any value of T_A .

10.7 5.0-Volt DC Electrical Characteristics

| Characteristic ⁽¹⁾ | Symbol | Min | Typ ⁽²⁾ | Max | Unit |
|---|-----------------------|---------------------|---------------------------|-------------------------|--------------------------------|
| Output voltage $I_{Load} = 10.0 \mu A$ $I_{Load} = -10.0 \mu A$ | V_{OL} V_{OH} | — $V_{DD} - 0.1$ | — — | 0.1 — | V |
| Output high voltage ($I_{Load} = -0.8 \text{ mA}$) PA0–PA7, PB0–PB5 | V_{OH} | $V_{DD} - 0.8$ | — | — | V |
| Output low voltage ($I_{Load} = 1.6 \text{ mA}$) PA0–PA3, PB0–PB5 ($I_{Load} = 10.0 \text{ mA}$) PA4–PA7 | V_{OL} | — | — | 0.4 0.4 | V |
| Input high voltage PA0–PA7, PB0–PB5, \overline{IRQ}/V_{PP} , \overline{RESET} , OSC1 | V_{IH} | $0.7 \times V_{DD}$ | — | V_{DD} | V |
| Input low voltage PA0–PA7, PB0–PB5, \overline{IRQ}/V_{PP} , \overline{RESET} , OSC1 | V_{IL} | V_{SS} | — | $0.2 \times V_{DD}$ | V |
| Supply current Run mode ⁽³⁾ Wait mode ⁽⁴⁾ Stop mode ⁽⁵⁾ 25°C –40 to 105°C | I_{DD} | — — — — | 3.5 0.45 0.2 2.0 | 6.0 2.75 10 20 | mA mA μA μA |
| I/O ports hi-z leakage current PA0–PA7, PB0–PB5 (without individual pulldown activated) | I_{IL} | — | 0.2 | ± 1 | μA |
| Input pulldown current PA0–PA7, PB0–PB5 (with individual pulldown activated) | I_{IL} | 35 | 80 | 200 | μA |
| Input pullup current RESET | I_{IL} | –15 | –35 | –85 | μA |
| Input current ⁽⁶⁾ \overline{RESET} , \overline{IRQ}/V_{PP} , OSC1 | I_{in} | — | 0.2 | ± 1 | μA |
| Capacitance Ports (as inputs or outputs) \overline{RESET} , \overline{IRQ}/V_{PP} , OSC1, OSC2 | C_{Out} C_{In} | — — | — — | 12 8 | pF |
| Crystal/ceramic resonator oscillator mode internal resistor OSC1 to OSC2 ⁽⁷⁾ | R_{osc} | 1.0 | 2.0 | 3.0 | M Ω |

- $V_{DD} = 5.0 \text{ Vdc} \pm 10\%$, $V_{SS} = 0 \text{ Vdc}$, $T_A = -40^\circ\text{C}$ to $+105^\circ\text{C}$, unless otherwise noted
- Typical values at midpoint of voltage range, 25°C only
- Run mode I_{DD} is measured using external square wave clock source ($f_{osc} = 4.2 \text{ MHz}$); all inputs 0.2 V from rail; no dc loads; less than 50 pF on all outputs; $C_L = 20 \text{ pF}$ on OSC2
- Wait mode I_{DD} : only timer system active. Wait mode is affected linearly by OSC2 capacitance. Wait mode is measured with all ports configured as inputs; $V_{IL} = 0.2 \text{ V}$; $V_{IH} = V_{DD} - 0.2 \text{ V}$. Wait mode I_{DD} is measured using external square wave clock source ($f_{osc} = 4.2 \text{ MHz}$); all inputs 0.2 V from rail; no dc loads; less than 50 pF on all outputs; $C_L = 20 \text{ pF}$ on OSC2.
- Stop mode I_{DD} is measured with $OSC1 = V_{SS}$. Stop mode I_{DD} is measured with all ports configured as inputs; $V_{IL} = 0.2 \text{ V}$; $V_{IH} = V_{DD} - 0.2 \text{ V}$
- Only input high current rated to $+1 \mu A$ on \overline{RESET} .
- The R_{osc} value selected for RC oscillator versions of this device is unspecified. See [Appendix C. MC68HSR705J1A](#) for additional information.

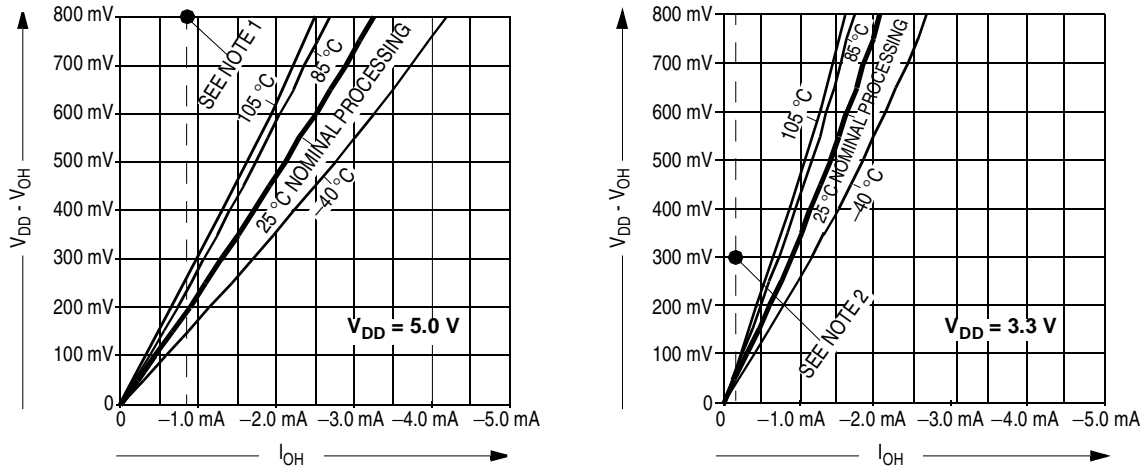
Electrical Specifications

10.8 3.3-Volt DC Electrical Characteristics

| Characteristic ⁽¹⁾ | Symbol | Min | Typ ⁽²⁾ | Max | Unit |
|---|-----------------------|---------------------|---------------------------|-----------------------|--------------------------------|
| Output voltage $I_{Load} = 10.0 \mu A$ $I_{Load} = -10.0 \mu A$ | V_{OL} V_{OH} | — $V_{DD} - 0.1$ | — — | 0.1 — | V |
| Output high voltage ($I_{Load} = -0.2 \text{ mA}$) PA0–PA7, PB0–PB5 | V_{OH} | $V_{DD} - 0.3$ | — | — | V |
| Output low voltage ($I_{Load} = 0.4 \text{ mA}$) PA0–PA3, PB0–PB5 ($I_{Load} = 5.0 \text{ mA}$) PA4–PA7 | V_{OL} | — | — | 0.3 0.3 | V |
| Input high voltage PA0–PA7, PB0–PB5, \overline{IRQ}/V_{PP} , \overline{RESET} , OSC1 | V_{IH} | $0.7 \times V_{DD}$ | — | V_{DD} | V |
| Input low voltage PA0–PA7, PB0–PB5, \overline{IRQ}/V_{PP} , \overline{RESET} , OSC1 | V_{IL} | V_{SS} | — | $0.2 \times V_{DD}$ | V |
| Supply current Run Mode ⁽³⁾ Wait Mode ⁽⁴⁾ Stop Mode ⁽⁵⁾ 25°C –40 to 105°C | I_{DD} | — — — — | 1.2 0.25 0.1 1.0 | 4.0 1.5 5 10 | mA mA μA μA |
| I/O ports hi-z leakage current PA0–PA7, PB0–PB5 (without individual pulldown activated) | I_{IL} | — | 0.1 | ± 1 | μA |
| Input pulldown current PA0–PA7, PB0–PB5 (with individual pulldown activated) | I_{IL} | 12 | 30 | 100 | μA |
| Input pullup current RESET | I_{IL} | –10 | –25 | –45 | μA |
| Input current ⁽⁶⁾ \overline{RESET} , \overline{IRQ}/V_{PP} , OSC1 | I_{in} | — | 0.1 | ± 1 | μA |
| Capacitance Ports (as inputs or outputs) \overline{RESET} , \overline{IRQ}/V_{PP} , OSC1, OSC2 | C_{Out} C_{In} | — — | — — | 12 8 | pF |
| Crystal/ceramic resonator oscillator mode internal resistor OSC1 to OSC2 ⁽⁷⁾ | R_{osc} | 1.0 | 2.0 | 3.0 | M Ω |

- $V_{DD} = 3.3 \text{ Vdc} \pm 10\%$, $V_{SS} = 0 \text{ Vdc}$, $T_A = -40^\circ\text{C}$ to $+105^\circ\text{C}$, unless otherwise noted
- Typical values at midpoint of voltage range, 25°C only
- Run mode I_{DD} is measured using external square wave clock source ($f_{osc} = 2.0 \text{ MHz}$); all inputs 0.2 V from rail; no dc loads; less than 50 pF on all outputs; $C_L = 20 \text{ pF}$ on OSC2
- Wait mode I_{DD} : only timer system active. Wait mode is affected linearly by OSC2 capacitance. Wait mode is measured with all ports configured as inputs; $V_{IL} = 0.2 \text{ V}$; $V_{IH} = V_{DD} - 0.2 \text{ V}$. Wait mode I_{DD} is measured using external square wave clock source ($f_{osc} = 2.0 \text{ MHz}$); all inputs 0.2 V from rail; no dc loads; less than 50 pF on all outputs; $C_L = 20 \text{ pF}$ on OSC2.
- Stop mode I_{DD} is measured with $OSC1 = V_{SS}$. Stop mode I_{DD} is measured with all ports configured as inputs; $V_{IL} = 0.2 \text{ V}$; $V_{IH} = V_{DD} - 0.2 \text{ V}$
- Only input high current rated to $+1 \mu A$ on \overline{RESET} .
- The R_{osc} value selected for RC oscillator versions of this device is unspecified. See [Appendix C. MC68HSR705J1A](#) for additional information.

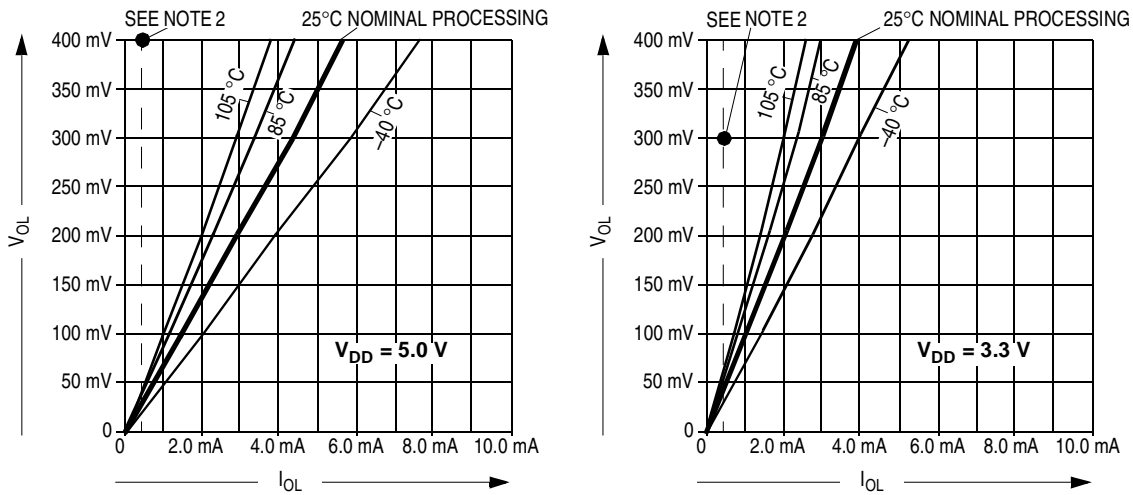
10.9 Driver Characteristics



Notes:

1. At $V_{DD} = 5.0\text{ V}$, devices are specified and tested for $(V_{DD} - V_{OH}) \leq 800\text{ mV}$ @ $I_{OH} = -0.8\text{ mA}$.
2. At $V_{DD} = 3.3\text{ V}$, devices are specified and tested for $(V_{DD} - V_{OH}) \leq 300\text{ mV}$ @ $I_{OH} = -0.2\text{ mA}$.

Figure 10-1. PA0-PA7, PB0-PB5 Typical High-Side Driver Characteristics

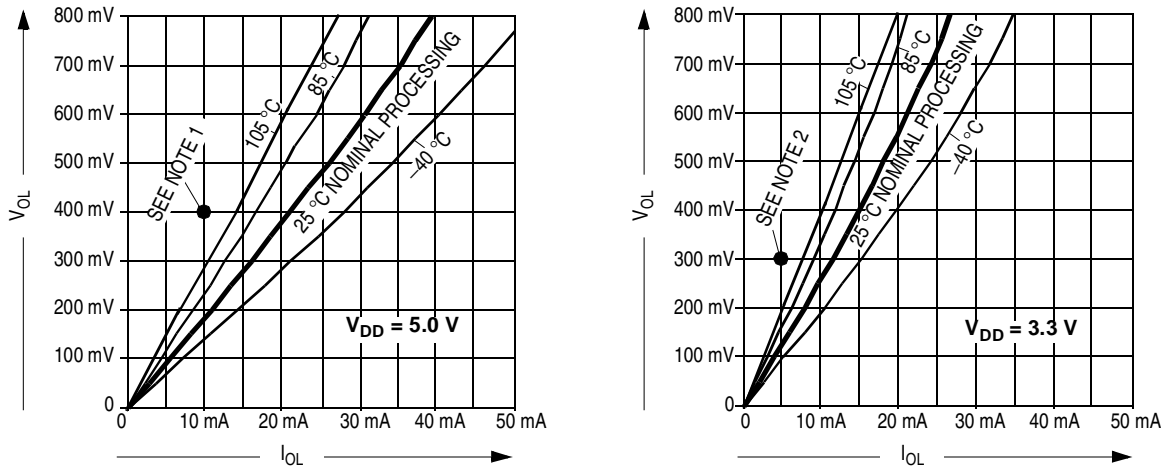


Notes:

1. At $V_{DD} = 5.0\text{ V}$, devices are specified and tested for $V_{OL} \leq 400\text{ mV}$ @ $I_{OL} = 1.6\text{ mA}$.
2. At $V_{DD} = 3.3\text{ V}$, devices are specified and tested for $V_{OL} \leq 300\text{ mV}$ @ $I_{OL} = 0.4\text{ mA}$.

Figure 10-2. PA0-PA3, PB0-PB5 Typical Low-Side Driver Characteristics

Electrical Specifications



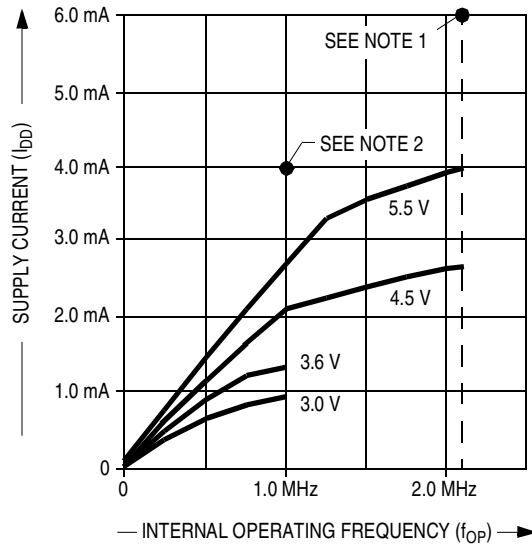
Notes:

1. At $V_{DD} = 5.0\text{ V}$, devices are specified and tested for $V_{OL} \leq 400\text{ mV}$ @ $I_{OL} = 10.0\text{ mA}$.
2. At $V_{DD} = 3.3\text{ V}$, devices are specified and tested for $V_{OL} \leq 300\text{ mV}$ @ $I_{OL} = 5.0\text{ mA}$.

Figure 10-3. PA4–PA7 Typical Low-Side Driver Characteristics

Freescale Semiconductor, Inc.

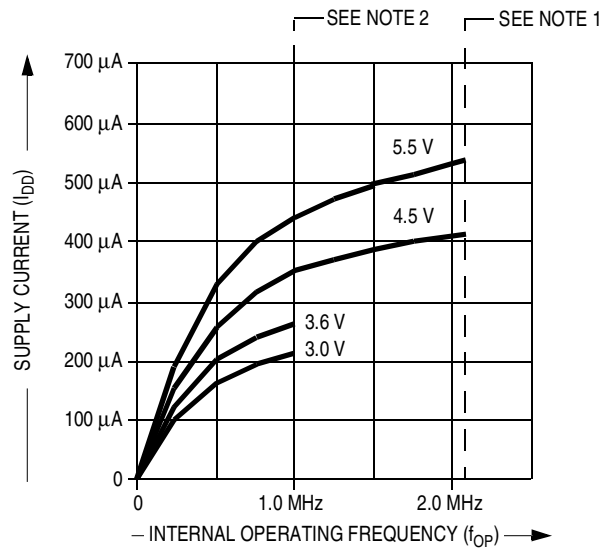
10.10 Typical Supply Currents



Notes:

1. At $V_{DD} = 5.0$ V, devices are specified and tested for $I_{DD} \leq 6.0$ mA @ $f_{OP} = 2.1$ MHz.
2. At $V_{DD} = 3.3$ V, devices are specified and tested for $I_{DD} \leq 4.0$ mA @ $f_{OP} = 1.0$ MHz.

Figure 10-4. Typical Operating I_{DD} (25°C)



Notes:

1. At $V_{DD} = 5.0$ V, devices are specified and tested for $I_{DD} \leq 2.75$ mA @ $f_{OP} = 2.1$ MHz.
2. At $V_{DD} = 3.3$ V, devices are specified and tested for $I_{DD} \leq 1.5$ mA @ $f_{OP} = 1.0$ MHz.

Figure 10-5. Typical Wait Mode I_{DD} (25°C)

Electrical Specifications

10.11 EPROM Programming Characteristics

| Characteristic ⁽¹⁾ | Symbol | Min | Typ | Max | Unit |
|--|--------------------------|--------|--------|--------|------|
| Programming voltage \overline{IRQ}/V_{PP} | V_{PP} | 16.0 | 16.5 | 17.0 | V |
| Programming current \overline{IRQ}/V_{PP} | I_{PP} | — | 3.0 | 10.0 | mA |
| Programming time Per array byte MOR | t_{EPGM} t_{MPGM} | 4 4 | — — | — — | ms |

1. $V_{DD} = 5.0 \text{ Vdc} \pm 10\%$, $V_{SS} = 0 \text{ Vdc}$, $T_A = -40^\circ\text{C}$ to $+105^\circ\text{C}$, unless otherwise noted

10.12 5.0-Volt Control Timing

| Characteristic ⁽¹⁾ | Symbol | Min | Max | Unit |
|---|------------------|---------|---------------------|-----------|
| Oscillator frequency Crystal oscillator option External clock source | f_{osc} | — dc | 4.2 4.2 | MHz |
| Internal operating frequency ($f_{osc} \div 2$) Crystal oscillator External clock | f_{op} | — dc | 2.1 2.1 | MHz |
| Cycle time ($1 \div f_{OP}$) | t_{cyc} | 476 | — | ns |
| \overline{RESET} pulse width low | t_{RL} | 1.5 | — | t_{cyc} |
| \overline{IRQ} interrupt pulse width low (edge-triggered) | t_{LIH} | 1.5 | — | t_{cyc} |
| \overline{IRQ} interrupt pulse width low (edge- and level-triggered) | t_{LIL} | 1.5 | Note ⁽²⁾ | t_{cyc} |
| PA0–PA3 interrupt pulse width high (edge-triggered) | t_{IHL} | 1.5 | — | t_{cyc} |
| PA0–PA3 interrupt pulse width (edge- and level-triggered) | t_{IHL} | 1.5 | Note ⁽²⁾ | t_{cyc} |
| OSC1 pulse width | t_{OH}, t_{OL} | 200 | — | ns |

1. $V_{DD} = 5.0 \text{ Vdc} \pm 10\%$, $V_{SS} = 0 \text{ Vdc}$, $T_A = -40^\circ\text{C}$ to $+105^\circ\text{C}$, unless otherwise noted

2. The maximum width, t_{LIL} or t_{LIH} , should not be more than the number of cycles it takes to execute the interrupt service routine plus 19 t_{cyc} or the interrupt service routine will be re-entered.

10.13 3.3-Volt Control Timing

| Characteristic ⁽¹⁾ | Symbol | Min | Max | Unit |
|---|------------------|---------|---------------------|-----------|
| Oscillator frequency Crystal oscillator option External clock source | f_{osc} | — dc | 2.0 2.0 | MHz |
| Internal operating frequency ($f_{osc} \div 2$) Crystal oscillator External clock | f_{op} | — dc | 1.0 1.0 | MHz |
| Cycle time ($1 \div f_{op}$) | t_{cyc} | 1000 | — | ns |
| \overline{RESET} pulse width low | t_{RL} | 1.5 | — | t_{cyc} |
| \overline{IRQ} interrupt pulse width low (edge-triggered) | t_{LIH} | 1.5 | — | t_{cyc} |
| \overline{IRQ} interrupt pulse width low (edge- and level-triggered) | t_{LIL} | 1.5 | Note ⁽²⁾ | t_{cyc} |
| PA0–PA3 interrupt pulse width high (edge-triggered) | t_{HIL} | 1.5 | — | t_{cyc} |
| PA0–PA3 interrupt pulse width (edge- and level-triggered) | t_{HIH} | 1.5 | Note ⁽²⁾ | t_{cyc} |
| OSC1 pulse width | t_{OH}, t_{OL} | 400 | — | ns |

1. $V_{DD} = 3.3 \text{ Vdc} \pm 10\%$, $V_{SS} = 0 \text{ Vdc}$, $T_A = -40^\circ\text{C}$ to $+105^\circ\text{C}$, unless otherwise noted

2. The maximum width, t_{LIL} or t_{LIH} , should not be more than the number of cycles it takes to execute the interrupt service routine plus $19 t_{cyc}$ or the interrupt service routine will be re-entered.

Electrical Specifications

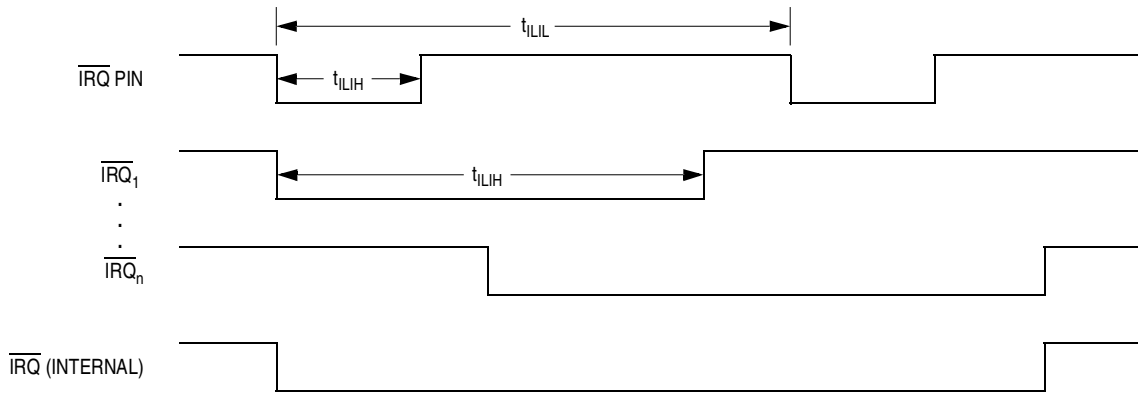
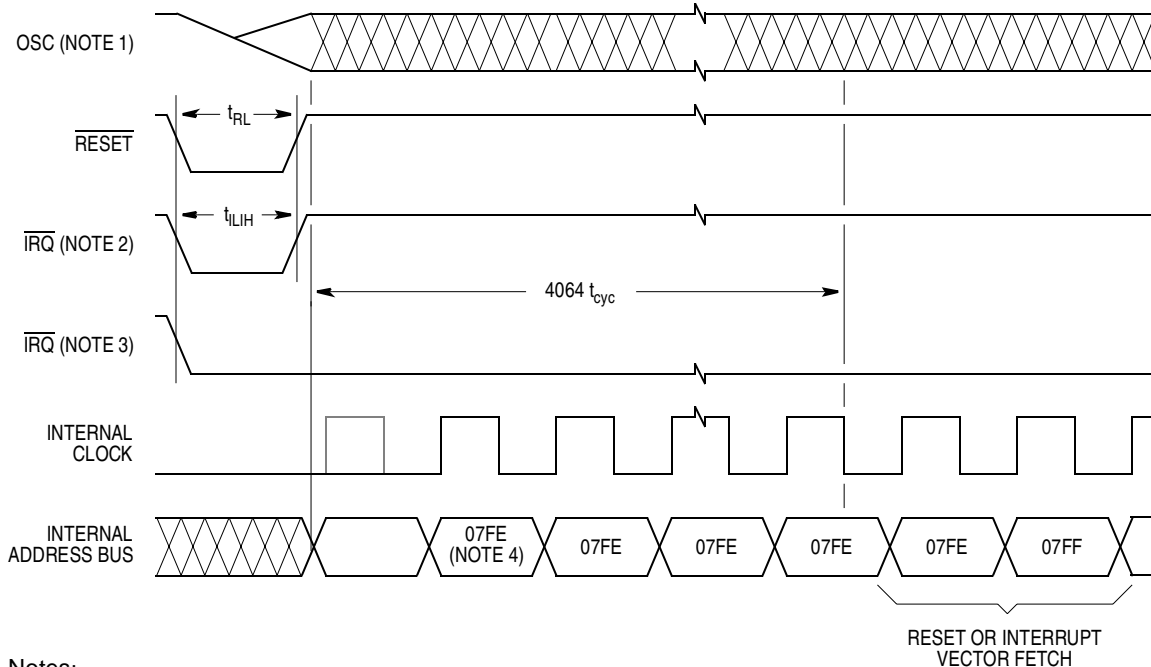
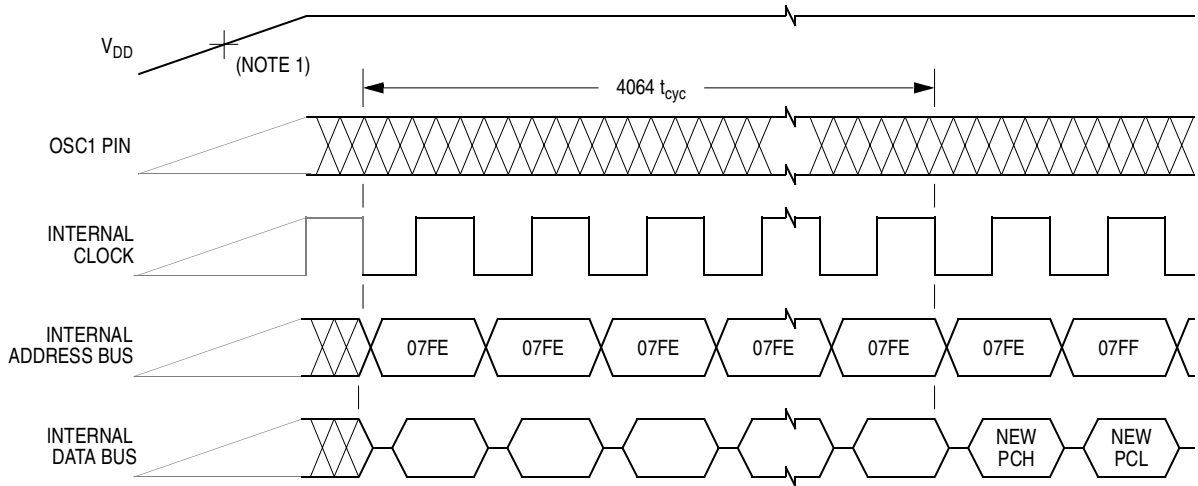


Figure 10-6. External Interrupt Timing



- Notes:
1. Internal clocking from OSC1 pin
 2. Edge-triggered external interrupt mask option
 3. Edge- and level-triggered external interrupt mask option
 4. Reset vector shown as example

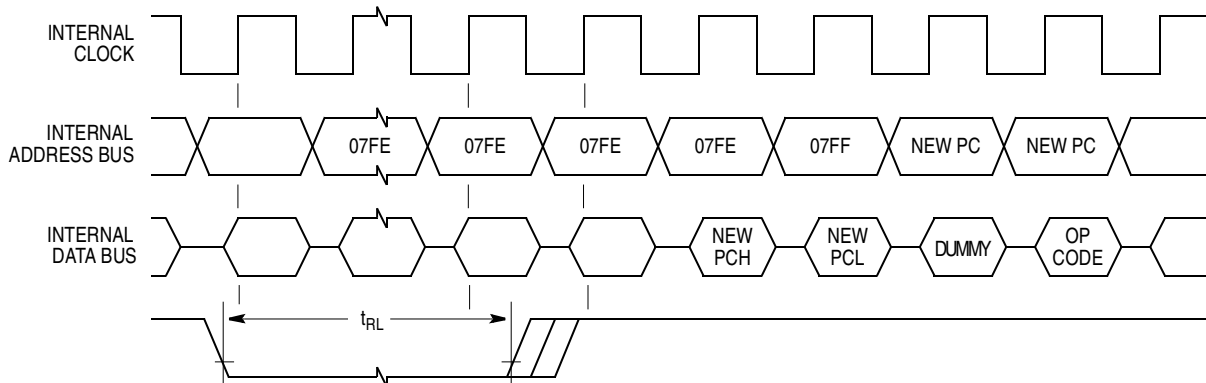
Figure 10-7. Stop Mode Recovery Timing



Notes:

1. Power-on reset threshold is typically between 1 V and 2 V.
2. Internal clock, internal address bus, and internal data bus are not available externally.

Figure 10-8. Power-On Reset Timing



Notes:

1. Internal clock, internal address bus, and internal data bus are not available externally.
2. The next rising edge of the internal clock after the rising edge of RESET initiates the reset sequence.

Figure 10-9. External Reset Timing

Section 11. Mechanical Specifications

11.1 Contents

| | | |
|------|---|-----|
| 11.2 | Introduction | 131 |
| 11.3 | Plastic Dual In-Line Package (Case 738) | 132 |
| 11.4 | Small Outline Integrated Circuit (Case 751) | 132 |
| 11.5 | Ceramic Dual In-Line Package (Case 732) | 133 |

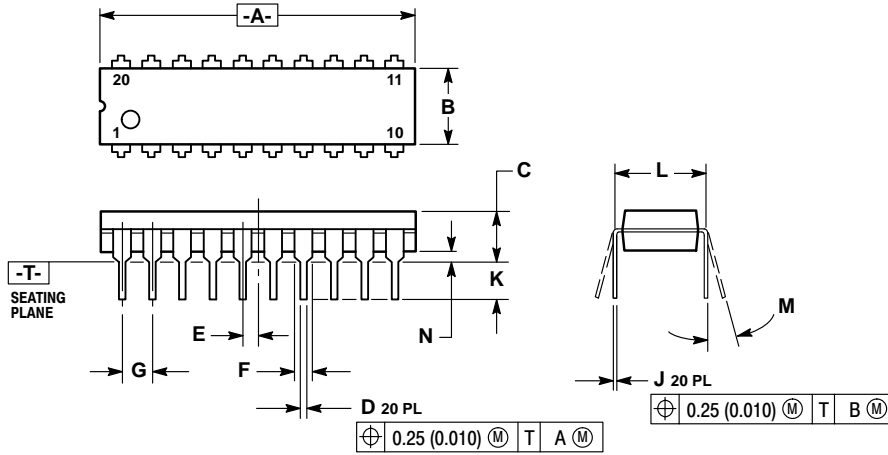
11.2 Introduction

The MC68HC705J1A, the resistor-capacitor (RC) oscillator, and high-speed option devices described in [Appendix A. MC68HRC705J1A](#), [Appendix B. MC68HSC705J1A](#), and [Appendix C. MC68HSR705J1A](#) are available in the following packages:

- 738-03 — plastic dual in-line package (PDIP)
- 751D-04 — small outline integrated circuit (SOIC)
- 732-03 — ceramic DIP (cerdip) (windowed)

Mechanical Specifications

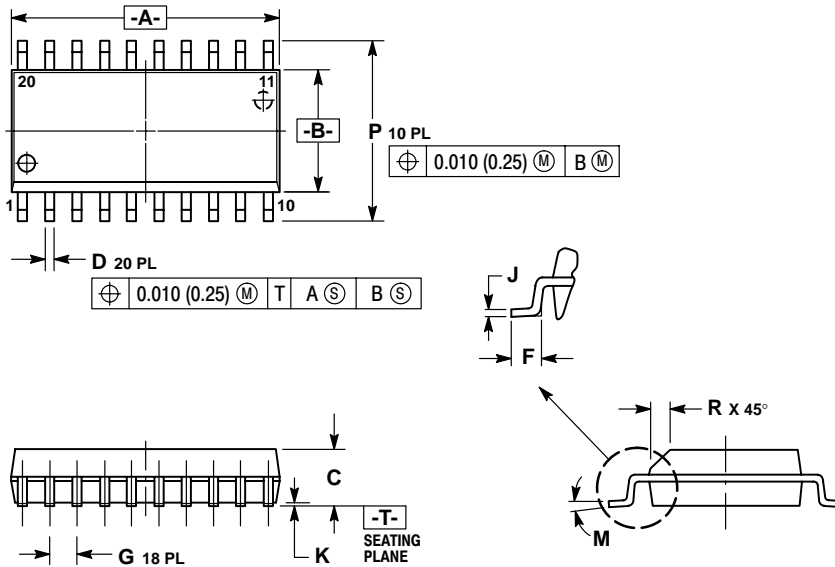
11.3 Plastic Dual In-Line Package (Case 738)



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

| DIM | INCHES | | MILLIMETERS | |
|-----|-----------|-------|-------------|-------|
| | MIN | MAX | MIN | MAX |
| A | 1.010 | 1.070 | 25.66 | 27.17 |
| B | 0.240 | 0.260 | 6.10 | 6.60 |
| C | 0.150 | 0.180 | 3.81 | 4.57 |
| D | 0.015 | 0.022 | 0.39 | 0.55 |
| E | 0.050 BSC | | 1.27 BSC | |
| F | 0.050 | | 1.27 | |
| G | 0.100 BSC | | 2.54 BSC | |
| J | 0.008 | | 0.21 | |
| K | 0.110 | | 2.80 | |
| L | 0.300 BSC | | 7.62 BSC | |
| M | 0° | | 15° | |
| N | 0.020 | | 0.51 | |

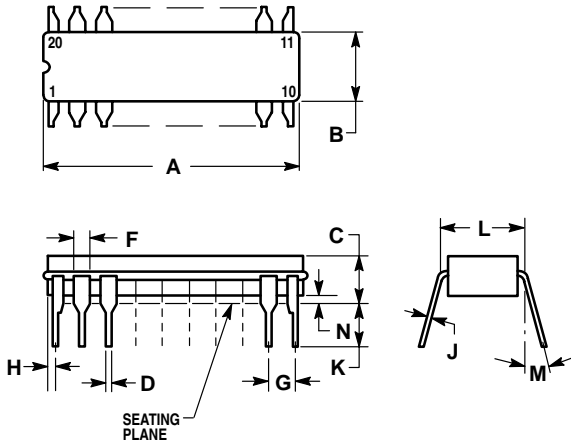
11.4 Small Outline Integrated Circuit (Case 751)



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.150 (0.006) PER SIDE.
 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF D DIMENSION AT MAXIMUM MATERIAL CONDITION.

| DIM | MILLIMETERS | | INCHES | |
|-----|-------------|-------|-----------|-------|
| | MIN | MAX | MIN | MAX |
| A | 12.65 | 12.95 | 0.499 | 0.510 |
| B | 7.40 | 7.60 | 0.292 | 0.299 |
| C | 2.35 | 2.65 | 0.093 | 0.104 |
| D | 0.35 | 0.49 | 0.014 | 0.019 |
| F | 0.50 | 0.90 | 0.020 | 0.035 |
| G | 1.27 BSC | | 0.050 BSC | |
| J | 0.25 | 0.32 | 0.010 | 0.012 |
| K | 0.10 | 0.25 | 0.004 | 0.009 |
| M | 0° | | 7° | |
| P | 10.05 | 10.55 | 0.395 | 0.415 |
| R | 0.25 | 0.75 | 0.010 | 0.029 |

11.5 Ceramic Dual In-Line Package (Case 732)



NOTES:

1. LEADS WITHIN 0.010 DIAMETER, TRUE POSITION AT SEATING PLANE, AT MAXIMUM MATERIAL CONDITION.
2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
3. DIMENSIONS A AND B INCLUDE MENISCUS.

| DIM | INCHES | |
|-----|-----------|-------|
| | MIN | MAX |
| A | 0.940 | 0.990 |
| B | 0.260 | 0.295 |
| C | 0.150 | 0.200 |
| D | 0.015 | 0.022 |
| F | 0.055 | 0.065 |
| G | 0.100 BSC | |
| H | 0.020 | 0.050 |
| J | 0.008 | 0.012 |
| K | 0.125 | 0.160 |
| L | 0.300 BSC | |
| M | 0° | 15° |
| N | 0.010 | 0.040 |

Section 12. Ordering Information

12.1 Contents

12.2 Introduction 135

12.3 MCU Order Numbers 135

12.2 Introduction

This section contains ordering information for the available package types.

12.3 MCU Order Numbers

Table 12-1 lists the MC order numbers.

Table 12-1. Order Numbers

| Package Type | Case Outline | Pin Count | Operating Temperature | Order Number ⁽¹⁾ |
|--------------|--------------|-----------|--|--|
| PDIP | 738-03 | 20 | 0 to 70°C -40 to +85°C -40 to +105°C | MC68HC705J1AP ⁽²⁾ MC68HC705J1AC ⁽³⁾ P MC68HC705J1AV ⁽⁴⁾ P |
| SOIC | 751D-04 | 20 | 0 to 70°C -40 to +85°C -40 to +105°C | MC68HC705J1ADW ⁽⁵⁾ MC68HC705J1ACDW MC68HC705J1AVDW |
| Cerdip | 732-03 | 20 | 0 to 70°C -40 to +85°C -40 to +105°C | MC68HC705J1AS ⁽⁶⁾ MC68HC705J1ACS MC68HC705J1AVS |

1. Refer to [Appendix A. MC68HRC705J1A](#), [Appendix B. MC68HSC705J1A](#), and [Appendix C. MC68HSR705J1A](#) for ordering information on optional high-speed and resistor-capacitor oscillator devices.
2. P = Plastic dual in-line package (PDIP)
3. C = Extended temperature range
4. V = Automotive temperature range
5. DW = Small outline integrated circuit (SOIC)
6. S = Ceramic dual in-line package (cerdip)

Appendix A. MC68HRC705J1A

A.1 Contents

| | | |
|-----|---|-----|
| A.2 | Introduction | 137 |
| A.3 | RC Oscillator Connections | 138 |
| A.4 | Typical Internal Operating Frequency for RC Oscillator Option. | 139 |
| A.5 | Package Types and Order Numbers | 140 |

A.2 Introduction

This appendix introduces the MC68HRC705J1A, a resistor-capacitor (RC) oscillator mask option version of the MC68HC705J1A. All of the information in this document applies to the MC68HRC705J1A with the exceptions given in this appendix.

A.3 RC Oscillator Connections

For greater cost reduction, the RC oscillator mask option allows the configuration shown in **Figure A-1** to drive the on-chip oscillator. Mount the RC components as close as possible to the pins for startup stabilization and to minimize output distortion.

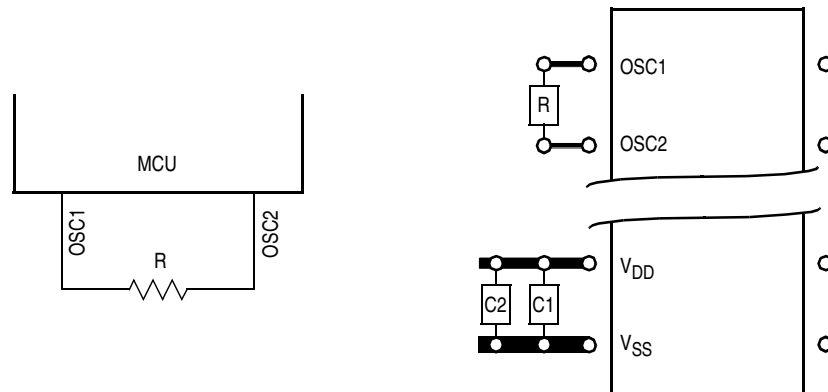


Figure A-1. RC Oscillator Connections

NOTE: The optional internal resistor is **not** recommended for configurations that use the RC oscillator connections as shown in **Figure A-1**. For such configurations, the oscillator internal resistor (OSCRES) bit of the mask option register should be programmed to a logic 0.

A.4 Typical Internal Operating Frequency for RC Oscillator Option

Figure A-2 shows typical internal operating frequencies at 25°C for the RC oscillator option.

NOTE: Tolerance for resistance is $\pm 50\%$. When selecting resistor size, consider the tolerance to ensure that the resulting oscillator frequency does not exceed the maximum operating frequency.

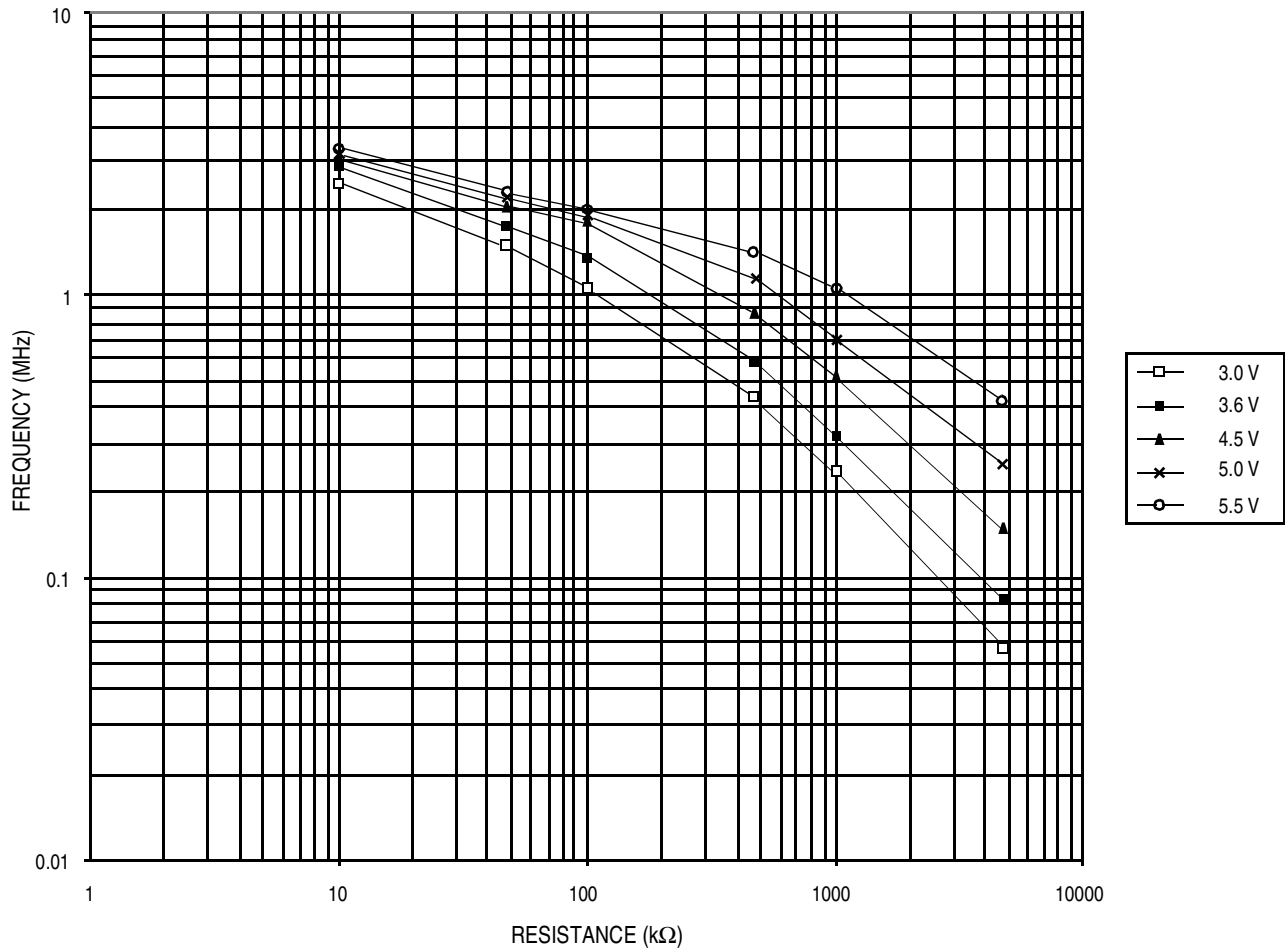


Figure A-2. Typical Internal Operating Frequency for Various V_{DD} at 25°C — RC Oscillator Option Only

A.5 Package Types and Order Numbers

Table A-1. MC68HRC705J1A (RC Oscillator Option)
Order Numbers

| Package Type | Case Outline | Pin Count | Operating Temperature | Order Number ⁽¹⁾ |
|--------------|--------------|-----------|--|---|
| PDIP | 738-03 | 20 | 0 to 70°C –40 to +85°C –40 to +105°C | MC68HRC705J1AP ⁽²⁾ MC68HRC705J1AC ^{(3)P} MC68HRC705J1AV ^{(4)P} |
| SOIC | 751D-04 | 20 | 0 to 70°C –40 to +85°C –40 to +105°C | MC68HRC705J1ADW ⁽⁵⁾ MC68HRC705J1ACDW MC68HRC705J1AVDW |
| Cerdip | 732-03 | 20 | 0 to 70°C –40 to +85°C –40 to +105°C | MC68HRC705J1AS ⁽⁶⁾ MC68HRC705J1ACS MC68HRC705J1AVS |

1. Refer to [Section 12. Ordering Information](#) for standard part ordering information.

2. P = plastic dual in-line package (PDIP)

3. C = extended temperature range

4. V = automotive temperature range

5. DW = small outline integrated circuit (SOIC)

6. S = ceramic dual in-line package (cerdip)

Appendix B. MC68HSC705J1A

B.1 Contents

| | | |
|-----|--|-----|
| B.2 | Introduction | 141 |
| B.3 | 5.0-Volt DC Electrical Characteristics | 142 |
| B.4 | 3.3-Volt DC Electrical Characteristics | 142 |
| B.5 | Typical Supply Currents | 142 |
| B.6 | Package Types and Order Numbers | 144 |

B.2 Introduction

This appendix introduces the MC68HSC705J1A, a high-speed version of the MC68HC705J1A. All of the information in this document applies to the MC68HSC705J1A with the exceptions given in this appendix.

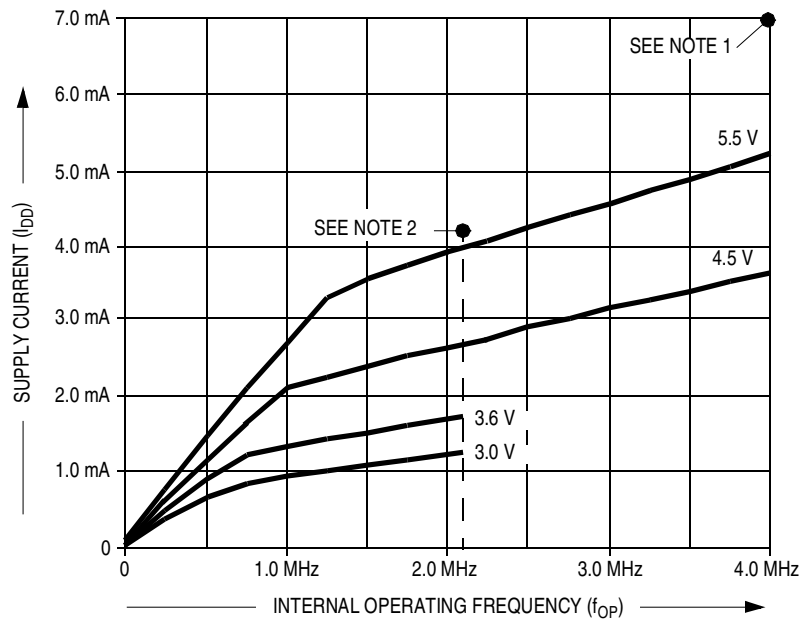
B.3 5.0-Volt DC Electrical Characteristics

| Characteristic | Symbol | Min | Typ | Max | Unit |
|--------------------------------------|----------|-----|------|------|------|
| Supply current ($f_{OP} = 4.0$ MHz) | | | | | |
| Run | I_{DD} | — | 4.25 | 7.0 | mA |
| Wait | | | 0.57 | 3.25 | |

B.4 3.3-Volt DC Electrical Characteristics

| Characteristic | Symbol | Min | Typ | Max | Unit |
|--------------------------------------|----------|-----|------|------|------|
| Supply current ($f_{OP} = 2.1$ MHz) | | | | | |
| Run | I_{DD} | — | 1.4 | 4.25 | mA |
| Wait | | | 0.28 | 1.75 | |

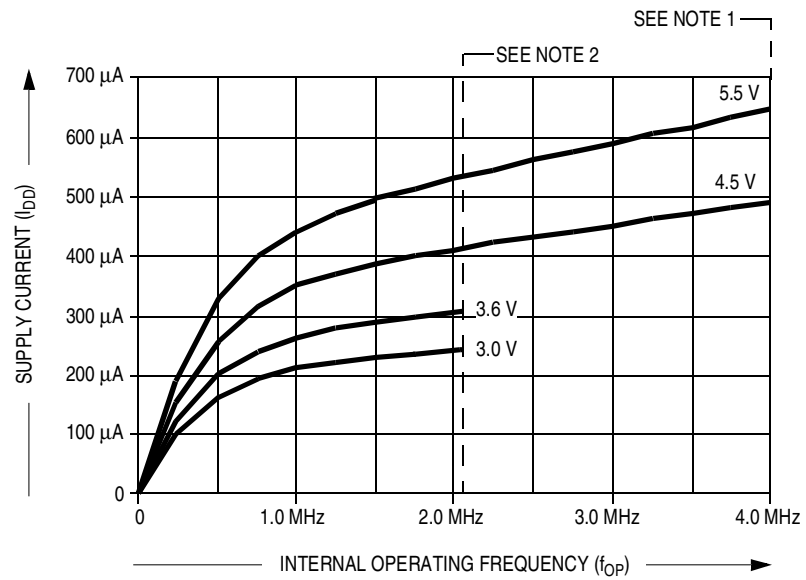
B.5 Typical Supply Currents



Notes:

1. At $V_{DD} = 5.0$ V, high-speed devices are specified and tested for $I_{DD} \leq 7.0$ mA @ $f_{OP} = 4.0$ MHz.
2. At $V_{DD} = 3.3$ V, high-speed devices are specified and tested for $I_{DD} \leq 4.25$ mA @ $f_{OP} = 2.1$ MHz.

Figure B-1. Typical High-Speed Operating I_{DD} (25°C)



Notes:

1. At V_{DD} = 5.0 V, high-speed devices are specified and tested for I_{DD} ≤ 3.25 mA @ f_{OP} = 4.0 MHz.
2. At V_{DD} = 3.3 V, high-speed devices are specified and tested for I_{DD} ≤ 1.75 mA @ f_{OP} = 2.1 MHz.

Figure B-2. Typical High-Speed Wait Mode I_{DD} (25°C)

B.6 Package Types and Order Numbers

Table B-1. MC68HSC705J1A (High Speed) Order Numbers

| Package Type | Case Outline | Pin Count | Operating Temperature | Order Number ⁽¹⁾ |
|--------------|--------------|-----------|---------------------------|--|
| PDIP | 738-03 | 20 | 0 to 70°C –40 to +85°C | MC68HSC705J1AP ⁽²⁾ MC68HSC705J1AC ⁽³⁾ P |
| SOIC | 751D-04 | 20 | 0 to 70°C –40 to +85°C | MC68HSC705J1ADW ⁽⁴⁾ MC68HSC705J1ACDW |
| Cerdip | 732-03 | 20 | 0 to 70°C –40 to +85°C | MC68HSC705J1AS ⁽⁵⁾ MC68HSC705J1ACS |

1. Refer to [Section 12. Ordering Information](#) for standard part ordering information.
2. P = plastic dual in-line package (PDIP)
3. C = extended temperature range
4. DW = small outline integrated circuit (SOIC)
5. S = ceramic dual in-line package (cerdip)

Appendix C. MC68HSR705J1A

C.1 Contents

| | | |
|-----|--|-----|
| C.2 | Introduction | 145 |
| C.3 | RC Oscillator Connections (External Resistor) | 145 |
| C.4 | Typical Internal Operating Frequency at 25°C for High-Speed RC Oscillator Option. | 146 |
| C.5 | RC Oscillator Connections (No External Resistor) | 147 |
| C.6 | Typical Internal Operating Frequency versus Temperature (No External Resistor) | 148 |
| C.7 | Package Types and Order Numbers | 149 |

C.2 Introduction

This appendix introduces the MC68HSR705J1A, a high-speed version of the MC68HRC705J1A. All of the information in this document applies to the MC68HSR705J1A with the exceptions given in this appendix.

C.3 RC Oscillator Connections (External Resistor)

Refer to [Appendix A. MC68HRC705J1A](#) for a description of the resistor-capacitor (RC) oscillator connections with external resistor.

C.4 Typical Internal Operating Frequency at 25°C for High-Speed RC Oscillator Option

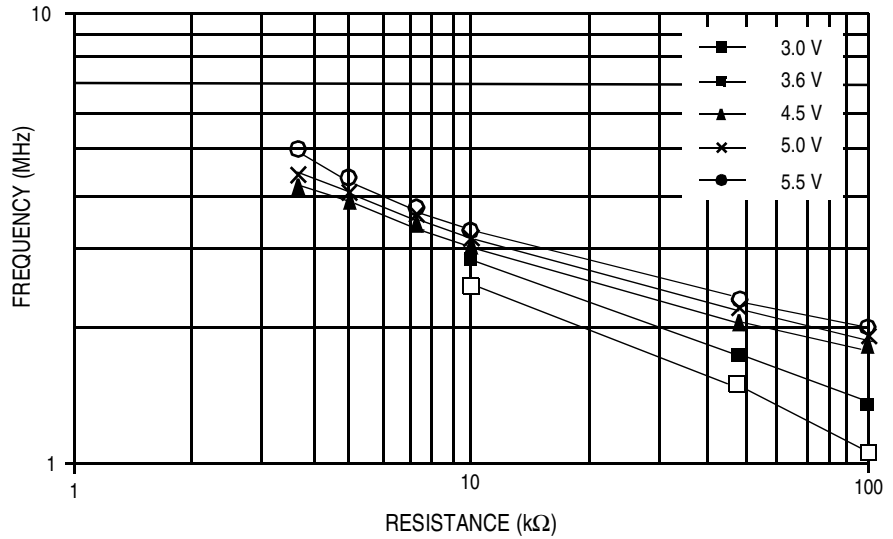


Figure C-1. Typical Internal Operating Frequency at 25°C for High-Speed RC Oscillator Option

For lower frequency operation characteristics, refer to [Appendix A. MC68HRC705J1A](#).

NOTE: Tolerance for resistance is ± 50 percent. When selecting resistor size, consider the tolerance to ensure that resulting oscillator frequency does not exceed the maximum operating frequency.

C.5 RC Oscillator Connections (No External Resistor)

For maximum cost reduction, the RC oscillator mask connections shown in **Figure C-2** allow the on-chip oscillator to be driven with **no** external components. This can be accomplished by programming the oscillator internal resistor (OSCRES) bit in the mask option register to a logic 1. When programming the OSCRES bit for the MC68HSR705J1A, an internal resistor is selected which yields typical internal oscillator frequencies as shown in **Figure C-3**. The internal resistance for this device is different than the resistance of the selectable internal resistor on the MC68HC705J1A and the MC68HSC705J1A devices.

NOTE: *This option is not available on the ROM version of this device (MC68HC05J1A).*

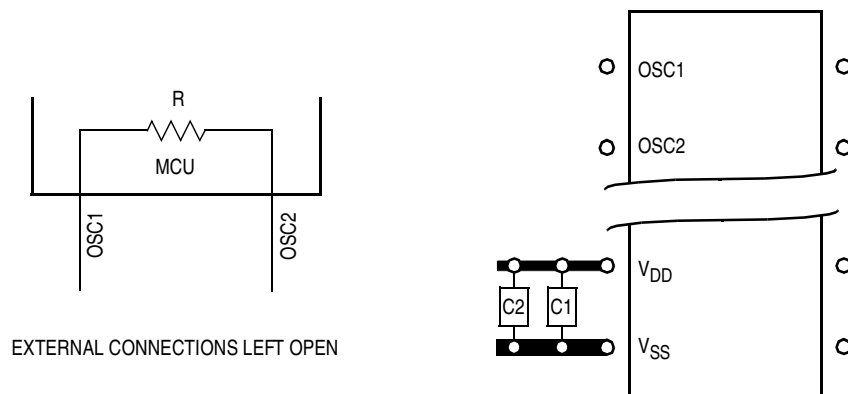


Figure C-2. RC Oscillator Connections (No External Resistor)

C.6 Typical Internal Operating Frequency versus Temperature
(No External Resistor)

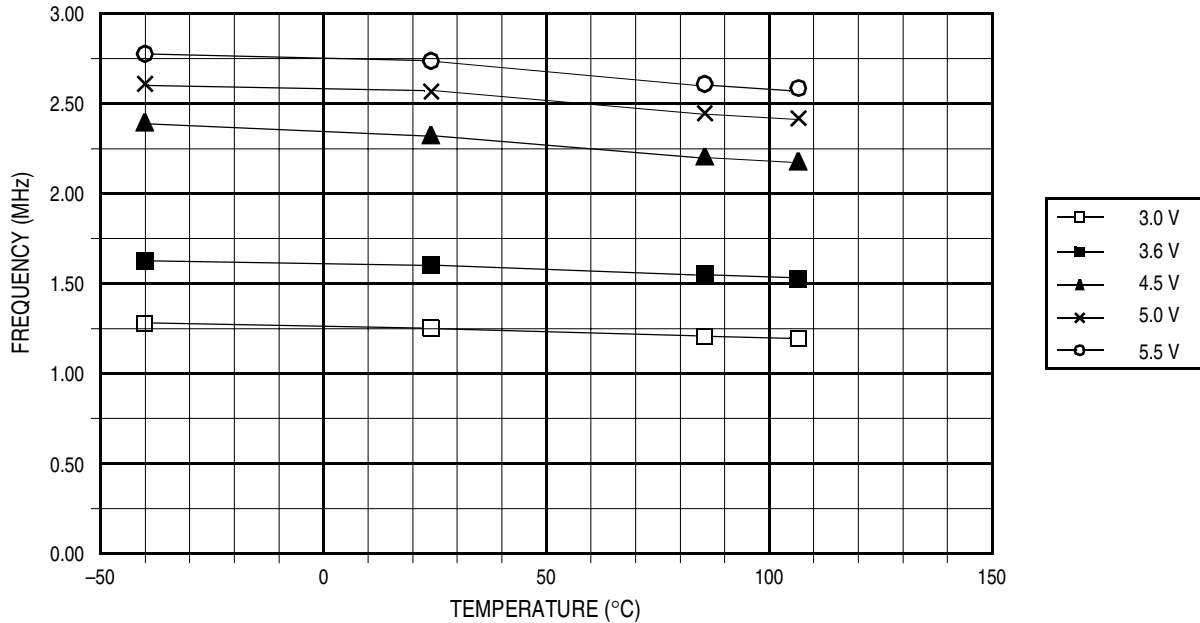


Figure C-3. Typical Internal Operating Frequency versus Temperature (OSCRES Bit = 1)

NOTE: Due to process variations, operating voltages, and temperature requirements, the internal resistance and tolerance are unspecified. Typically for a given voltage and temperature, the frequency should not vary more than ± 500 kHz. However, this data is not guaranteed. It is the user's responsibility to ensure that the resulting internal operating frequency meets the user's requirements.

C.7 Package Types and Order Numbers

Table C-1. MC68HSR705J1A (High-Speed RC Oscillator Option) Order Numbers⁽¹⁾

| Package Type | Case Outline | Pin Count | Operating Temperature | Order Number |
|--------------|--------------|-----------|---------------------------|--|
| PDIP | 738-03 | 20 | 0 to 70°C –40 to +85°C | MC68HSR705J1AP ⁽²⁾ MC68HSR705J1AC ⁽³⁾ P |
| SOIC | 751D-04 | 20 | 0 to 70°C –40 to +85°C | MC68HSR705J1ADW ⁽⁴⁾ MC68HSR705J1ACDW |
| Cerdip | 732-03 | 20 | 0 to 70°C –40 to +85°C | MC68HSR705J1AS ⁽⁵⁾ MC68HSR705J1ACS |

1. Refer to [Section 12. Ordering Information](#) for standard part ordering information.
2. P = plastic dual in-line package (PDIP)
3. C = extended temperature range
4. DW = small outline integrated circuit (SOIC)
5. S = ceramic dual in-line package (cerdip)

Index

| | |
|--|-----|
| A | |
| accumulator register (A) | 48 |
| addressing modes | 52 |
| B | |
| block diagram | 23 |
| brownout | 98 |
| C | |
| C bit | 51 |
| central processor unit (CPU) | 45 |
| computer operating properly (COP) module | 97 |
| condition code register (CCR) | 50 |
| COP watchdog | 82 |
| COP in stop mode | 100 |
| COP in wait mode | 100 |
| COP register (COPR) | 99 |
| COP reset | 72 |
| features | 97 |
| interrupts | 99 |
| low-power modes | 100 |
| operation | 98 |
| programmable option | 25 |
| COPEN bit | 42 |
| CPU | 46 |
| features | 46 |
| instruction set | 52 |
| instruction set summary | 61 |
| instruction types | 55 |
| opcode map | 67 |
| programming model | 47 |

| | |
|---|----------|
| CPU registers | |
| accumulator register (A) | 48 |
| index register (X) | 48 |
| program counter register (PC) | 50 |
| stack pointer register (SP) | 49 |
| D | |
| data direction registers | |
| data direction register A (DDRA) | 90 |
| data direction register B (DDRB) | 93 |
| data-retention mode | 84 |
| E | |
| ELAT bit | 39 |
| electrical specifications | 117 |
| control timing | 126, 127 |
| DC electrical characteristics | 121, 122 |
| driver characteristics | 123 |
| maximum ratings | 118 |
| MC68HSC705J1A (high-speed option) | 142 |
| MC68HSR705J1A (high-speed RC oscillator option) | 145 |
| operating temperature range | 119 |
| port A | 95 |
| port B | 95 |
| power considerations | 120 |
| thermal resistance | 119 |
| typical supply currents | 125 |
| electrostatic damage | 87 |
| EPGM bit | 39 |
| EPMSEC bit | 41 |
| EPROM | |
| EPROM security programmable option | 25 |
| EPROM/OTPROM | 38 |
| erasing | 40 |
| programming | 38, 40 |
| programming characteristics | 43 |
| programming register (EPROG) | 39 |

| | |
|---|----------|
| external interrupt module (IRQ) | 101 |
| external interrupt pins | 31 |
| external reset. | 72 |
| G | |
| general description | 21 |
| H | |
| H bit | 51 |
| I | |
| I bit. | 51 |
| index register (X) | 48 |
| instruction set | 52 |
| addressing modes | 52 |
| instruction set summary | 61 |
| instruction types | 55 |
| opcode map | 67 |
| instruction types. | 55 |
| interrupts | |
| external interrupt | 73, 74 |
| external interrupt logic | 74 |
| external interrupt module | 101 |
| external interrupt timing | 75, 107 |
| external interrupt vector | 76 |
| features | 101 |
| interrupt flowchart. | 78, 103 |
| interrupt processing | 76 |
| interrupt sources | 73 |
| interrupt stacking order | 77 |
| IRQ module block diagram. | 102 |
| IRQ status and control register (ISCR) | 106 |
| IRQ/V _{PP} pin | 101, 104 |
| operation | 102 |
| optional external interrupts. | 104 |
| pin sensitivity selection. | 104 |
| pin triggering option | 25 |
| port A external interrupts programmable option. | 25 |

| | |
|--|-------------|
| real-time interrupts | 76 |
| reset/interrupt vector addresses. | 77 |
| software interrupt | 73 |
| software interrupt vector. | 76 |
| sources. | 73 |
| timer interrupt vector | 76 |
| timer interrupts | 76, 112 |
| timer overflow. | 76 |
| IRQ latch | 73 |
| $\overline{\text{IRQ}}/\text{V}_{\text{PP}}$ pin | 31, 98, 104 |
| IRQE bit. | 106 |
| IRQF bit | 106 |
| IRQR bit. | 106 |
| J | |
| junction temperature | 120 |
| L | |
| LEVEL bit. | 42 |
| low-power modes | 79 |
| COP timeout period | 82 |
| data-retention mode. | 80, 84 |
| effects on clock generation | 81 |
| effects on COP. | 82 |
| effects on CPU. | 82 |
| effects on EPROM/OTEPROM. | 84 |
| effects on timer. | 83 |
| exiting stop mode. | 80 |
| exiting wait mode | 80 |
| flowchart (STOP/HALT/WAIT) | 86 |
| halt mode | 79 |
| STOP instruction flowchart. | 86 |
| stop mode | 79, 82 |
| stop recovery timing. | 85 |
| timer | 115 |
| timing of stop mode recovery | 85 |
| wait mode. | 79 |

M

| | |
|---|-----|
| mask option register (MOR) | 40 |
| programming | 41 |
| MC68HC705J1A | |
| features | 24 |
| MC68HRC705J1A (RC oscillator option) | 137 |
| operating frequency | 139 |
| order numbers | 140 |
| package types | 140 |
| RC oscillator connections. | 138 |
| MC68HSC705J1A (high-speed option) | 141 |
| DC electrical characteristics. | 142 |
| order numbers | 144 |
| package types | 144 |
| typical operating current. | 142 |
| typical wait mode current | 143 |
| MC68HSR705J1A (high-speed RC oscillator option) | 145 |
| operating frequencies (with OSCRES bit set) | 148 |
| operating frequency | 146 |
| order numbers | 149 |
| package types | 149 |
| RC oscillator. | 147 |
| RC oscillator connections. | 147 |
| mechanical specifications | 131 |
| memory | 33 |
| EPROM/OTPROM | 38 |
| EPROM/OTPROM programming. | 38 |
| features | 33 |
| I/O register summary | 35 |
| mask option register. | 40 |
| memory map | 34 |
| RAM. | 37 |
| MPGM bit. | 39 |
| multifunction timer module. | 109 |

N

| | |
|-----------------|----|
| N bit | 51 |
|-----------------|----|

O

| | |
|---|--------------------|
| opcode map | 67 |
| options (mask) | 40 |
| options (programmable) | 25 |
| ordering information | 135 |
| MC68HRC705J1A (RC oscillator option) | 140 |
| MC68HSC705J1A (high-speed option) | 144 |
| MC68HSR705J1A (high-speed RC oscillator option) | 149 |
| order numbers | 135, 140, 144, 149 |
| OSC1 pin | 27 |
| OSC2 pin | 27 |
| oscillator | |
| crystal oscillator internal resistor option | 25 |
| delay counter programmable option | 25 |
| on-chip oscillator stabilization delay | 71 |
| pins | 27 |
| OSCREG bit | 41 |

P

| | |
|---|-----|
| PA0–PA3 pins | 101 |
| package types | 135 |
| parallel input/output (I/O) ports | 87 |
| pin assignments | 26 |
| PIRQ bit | 42 |
| port A | |
| data direction register (DDRA) | 90 |
| data register (PORTA) | 89 |
| electrical characteristics | 95 |
| I/O circuitry | 90 |
| I/O pin interrupts (PA0–PA3) | 92 |
| LED drive capability | 92 |
| pin operation | 91 |
| pins | 31 |
| pulldown register (PDRA) | 91 |
| port B | |
| data direction register (DDRB) | 93 |
| electrical characteristics | 95 |

| | |
|--|--------|
| I/O circuitry | 93 |
| pin operation | 94 |
| pins. | 31 |
| port B data register (PORTB). | 92 |
| pulldown register (PDRB). | 94 |
| power dissipation. | 120 |
| power-on reset. | 71 |
| program counter (PC) | 50 |
| programmable options. | 25 |
| programming model (CPU) | 47 |
| pulldown register A (PDRA). | 91 |
| pulldown register B (PDRB). | 94 |
| pulldown resistors | |
| programmable option | 25 |
| R | |
| RAM. | 37 |
| stack RAM | 76 |
| registers | |
| CPU | 48 |
| I/O register summary | 35 |
| parallel I/O port register summary | 88 |
| <u>RESET</u> pin. | 30, 72 |
| resets. | 70 |
| COP register (COPR). | 72 |
| COP watchdog reset | 72 |
| external reset | 72 |
| external reset timing. | 72 |
| illegal address | 72 |
| power-on reset (POR) | 71 |
| power-on reset timing. | 71 |
| reset sources | 70 |
| reset/interrupt vector addresses. | 77 |
| resistors (pulldown) | |
| programmable option | 25 |
| RT1, RT0 bits | 113 |

RTIE bit 113
 RTIF bit 113
 RTIFR bit 113

S

Schmitt trigger 31, 104, 105
 SOSCD bit 41
 stack pointer register (SP) 49
 STOP instruction 81, 100, 106
 stop mode 82, 100
 effect on COP watchdog 100
 effects on timer. 115
 STOP instruction flowchart. 86
 stop recovery timing. 85
 stop/halt mode programmable option 25
 SWAIT bit 42
 SWPDI bit 42

T

thermal resistance 120
 timer
 block diagram 110
 features 109
 I/O registers 112
 interrupts 76, 112
 low-power modes 115
 operation 111
 timer counter register 114
 timer interrupt vector 76
 timer status and control register (TSCR) 112
 TOF bit 113
 TOFR bit 113
 TOIE bit 113

V

V_{DD} pin 25
V_{SS} pin..... 25

W

WAIT instruction 81, 100, 106
wait mode 100
 effects on timer..... 115

Z

Z bit 51

Freescale Semiconductor, Inc.

Freescale Semiconductor, Inc.

**For More Information On This Product,
Go to: www.freescale.com**

Freescale Semiconductor, Inc.

Home Page:

www.freescale.com

email:

support@freescale.com

USA/Europe or Locations Not Listed:

Freescale Semiconductor
Technical Information Center, CH370
1300 N. Alma School Road
Chandler, Arizona 85224
(800) 521-6274
480-768-2130

support@freescale.com

Europe, Middle East, and Africa:

Freescale Halbleiter Deutschland GmbH
Technical Information Center
Schatzbogen 7

81829 Muenchen, Germany

+44 1296 380 456 (English)

+46 8 52200080 (English)

+49 89 92103 559 (German)

+33 1 69 35 48 48 (French)

support@freescale.com

Japan:

Freescale Semiconductor Japan Ltd.

Headquarters

ARCO Tower 15F

1-8-1, Shimo-Meguro, Meguro-ku

Tokyo 153-0064, Japan

0120 191014

+81 2666 8080

support.japan@freescale.com

Asia/Pacific:

Freescale Semiconductor Hong Kong Ltd.

Technical Information Center

2 Dai King Street

Tai Po Industrial Estate,

Tai Po, N.T., Hong Kong

+800 2666 8080

support.asia@freescale.com

For Literature Requests Only:

Freescale Semiconductor

Literature Distribution Center

P.O. Box 5405

Denver, Colorado 80217

(800) 441-2447

303-675-2140

Fax: 303-675-2150

LDCForFreescaleSemiconductor@hibbertgroup.com

RoHS-compliant and/or Pb- free versions of Freescale products have the functionality and electrical characteristics of their non-RoHS-compliant and/or non-Pb- free counterparts. For further information, see <http://www.freescale.com> or contact your Freescale sales representative.

For information on Freescale's Environmental Products program, go to <http://www.freescale.com/epp>.

Information in this document is provided solely to enable system and software implementers to use Freescale Semiconductor products. There are no express or implied copyright licenses granted hereunder to design or fabricate any integrated circuits or integrated circuits based on the information in this document. Freescale Semiconductor reserves the right to make changes without further notice to any products herein. Freescale Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Freescale Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. "Typical" parameters which may be provided in Freescale Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. Freescale Semiconductor does not convey any license under its patent rights nor the rights of others. Freescale Semiconductor products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the Freescale Semiconductor product could create a situation where personal injury or death may occur. Should Buyer purchase or use Freescale Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold Freescale Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that Freescale Semiconductor was negligent regarding the design or manufacture of the part.



MC68HC705J1A/D

**For More Information On This Product,
Go to: www.freescale.com**